

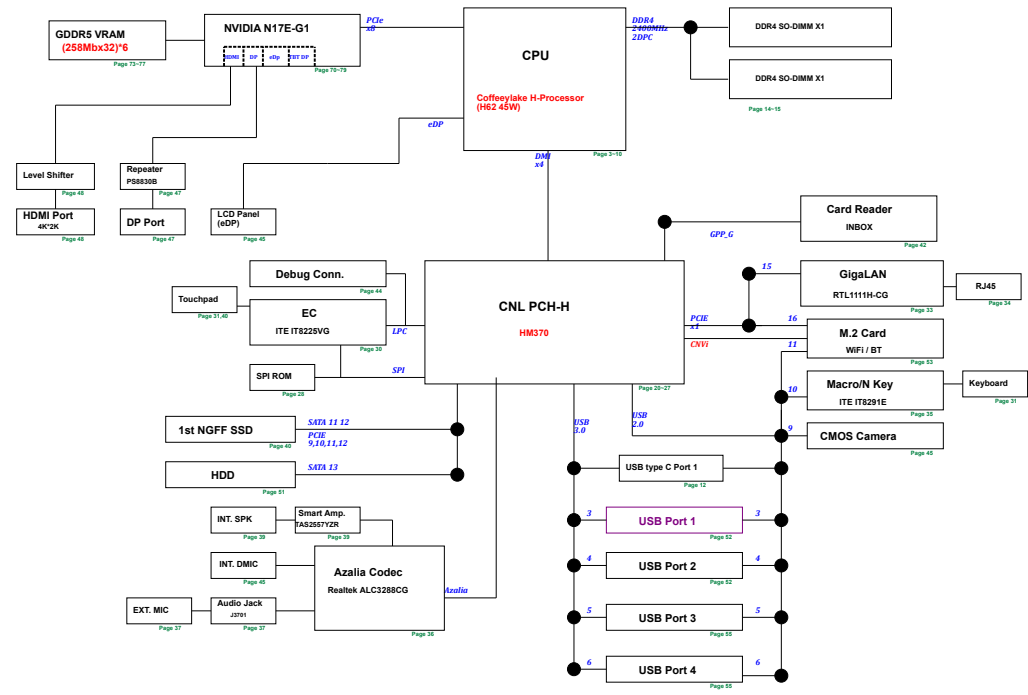
001_Block Diagram
002_System Setting
003_CPU_DMI,PEG,eDP,DDI
004_CPU_D0R4
005_CPU_GND
006_CPU_CFG,RSVD
007_
008_CPU_PWR
009_CPU_PWR
010_CPU_POWER_CAP
011_TBT_Alpine-Ridge
012_TBT_TPS65982&Type C
013_TBT_PWR
014_DIM_DDR4 SO-DIMM A(0)
015_DIM_DDR4 SO-DIMM B(0)
016_DIM_DDR4 SO-DIMM A(1)
017_DIM_DDR4 SO-DIMM B(1)
018_DIM_CA/DQ Voltage
020_PCH_HOA,SMB,SEQ,RTC,JTAG
021_PCH_PCIE,SATA,USB2,MISC
022_PCH_CLK,LPC,USB3
023_PCH_LVDS,eDP,DP
024_PCH_SPI,CNV
025_PCH_GPIO
026_PCH_POWER,GND
027_PCH_POWER,GND
028_PCH_SPI ROM,OTH
029_TEST_POINT
030_XSC_IT8225
031_XSC_KB & TP
032_RST_Reset Circuit
033_LAN_RTL8111H-CG
034_LAN_RJ45_CON
035_MacroN_KEY_IT8291
036_AUD_ALC295
037_AUD_EXT Jack
039_AUD_INT SPK
040_NGFF_SSD_PCIE_CON
041_NGFF_SSD_PCIE_CON_3
042_CR_GL3215
043_
044_BUG_LPC
045_eDP_CON & Tobii IS4_CON
046_
047_Display Port
048_HDMI
049_
050_FAN_Thermal Sensor & Fan
051_HDD
052_USB3.0 Port
053_NGFF_WLAN & BT & XBBOX
055_USB3.0 Port
056_LED & Switch
057_DSG_Discharge
058_Power Protect
059_EMI
060_DC & BAT IN
063_>>>Power Button_IO_BD
064_>>>LED_IO_BD
065_ME_W2B conn. & NUT
066_
067_
068_
069_
070_GPU_PCIE I/F
071_GPU_POWER
072_GPU_FRAME BUFFER
073_VRAM-CHANNEL A
074_VRAM-CHANNEL B
075_VRAM-CHANNEL C
076_VRAM-CHANNEL D
077_VRAM_CAP

080_PW_COFFEE LAKE (1)
081_PW_COFFEE LAKE (2)
082_PW_VCCIO
083_PW_+1.05VSUS
084_PW_+1.8VSUS
086_PW_+1.2V/+VTT/+2.5V
087_PW_+3VADSW/+SVSUS
088_PW_LOAD SWITCH
089_PW_CHARGER
090_PW_PROTECTION
091_PW_+NVVDD (1)
092_PW_+NVVDD (2)
093_PW_+NVVDD (3)
094_PW_+FBVDDQ
096_PW_+12VS_FAN
097_PW_PEX_VDD
098_PW_IPC

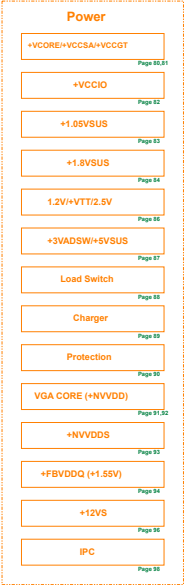
100_Power On Timing-AC mode
101_Power On Timing-DC mode

GL704GM Block Diagram

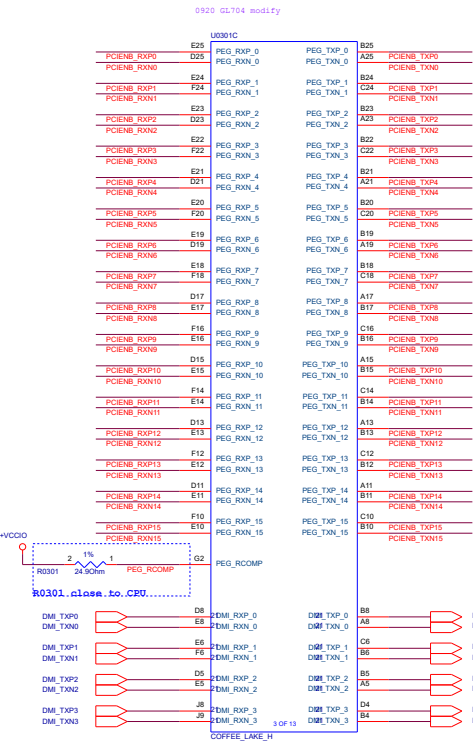
Coffeelake H Platform



- Reset Circuit
- Thermal Sensor
- PWM Fan
- Switch & LEDs
- Discharge Circuit
- Power Protect
- DC & Battery
- Skew Holes



PCIe



Display

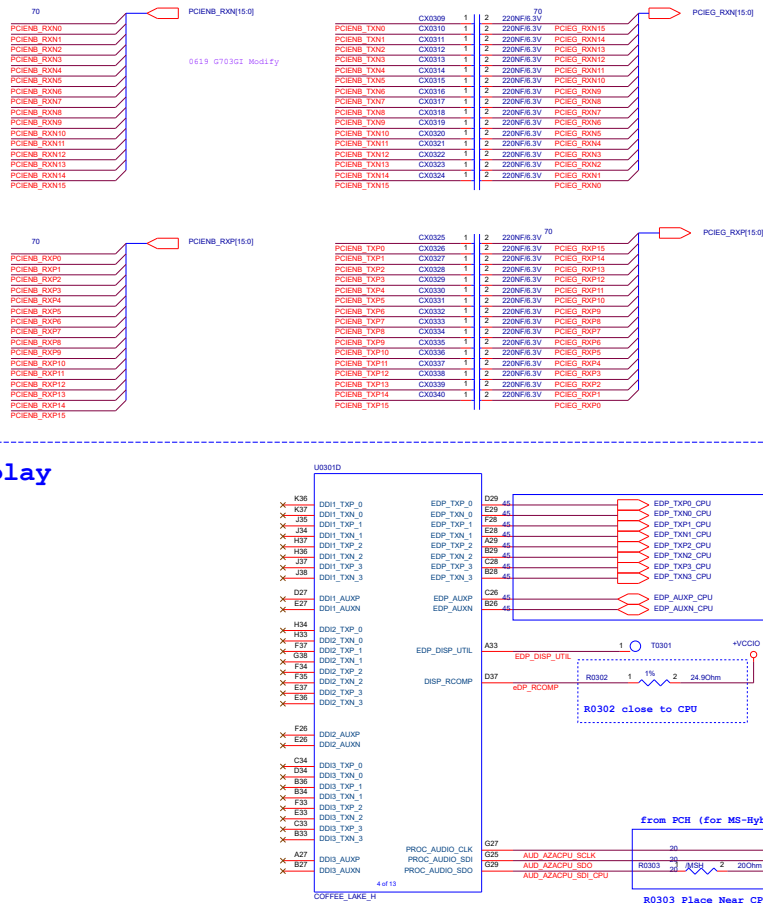
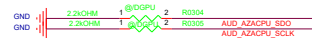


Table 8-3. Few Supported Normal and Lane-reversed Bifurcation Configurations

x16 Controller Negotiated Width	x8 Controller Negotiated Width	x4 Controller Negotiated Width	Processor	Physical Lanes															
				0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
x16	Off	Off	Direct	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
x8	x8	Off	Direct	0	1	2	3	4	5	6	7	0	1	2	3	4	5	6	7
x8	x4	x4	Direct	0	1	2	3	4	5	6	7	0	1	2	3	0	1	2	3
x16	Off	Off	Reverse	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
x8	x8	Off	Reverse	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
x8	x4	x4	Reverse	3	2	1	0	3	2	1	0	7	6	5	4	3	2	1	0

Notes:

- Support is also provided for narrow width and use devices with lower number of lanes (that is, usage on x4 configuration), however further bifurcation is not supported.
- In case that more than one device is connected, the device with the highest lane count, should always be connected to the lower lanes, as follows:
 - Connect lane 0 of 1st device to lane 0.
 - Connect lane 0 of 2nd device to lane 8.
 - Connect lane 0 of 3rd device to lane 12.
 For example:
 - When using 1x8 + 2x4, the 8 lane device must use lanes 0:7.
 - When using 1x4 + 1x2, the 4 lane device must use lanes 0:3, and other 2 lanes device must use lanes 8:9.
 - When using 1x4 + 1x2 + 1x1, 4 lane device must use lanes 0:3, two lane device must use lanes 8:9, one lane device must use lane 12.

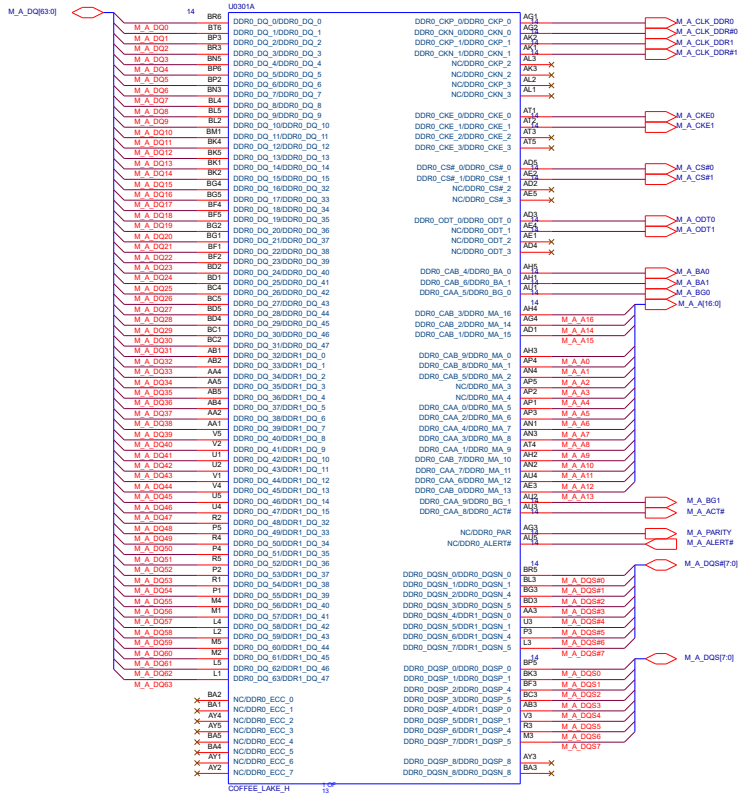


Refer to CFL-H PDG P.363 (Doc.571391)

31.1.4 Disabling and Termination Guidelines for the Intel® High Definition Audio Interface

When HDA_SDIN[1:0], DISPA_SDIN interface is not implemented on the platform the signal pin(s) may be left unconnected.

When the Intel® Display Audio interface is not implemented, PROC_AUDIO_CLK and PROC_AUDIO_SDI need to be terminated to GND via a weak pull-down resistor (i.e. ~2KΩ), PROC_AUDIO_SDO can be left unconnected.



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Memory Channel B

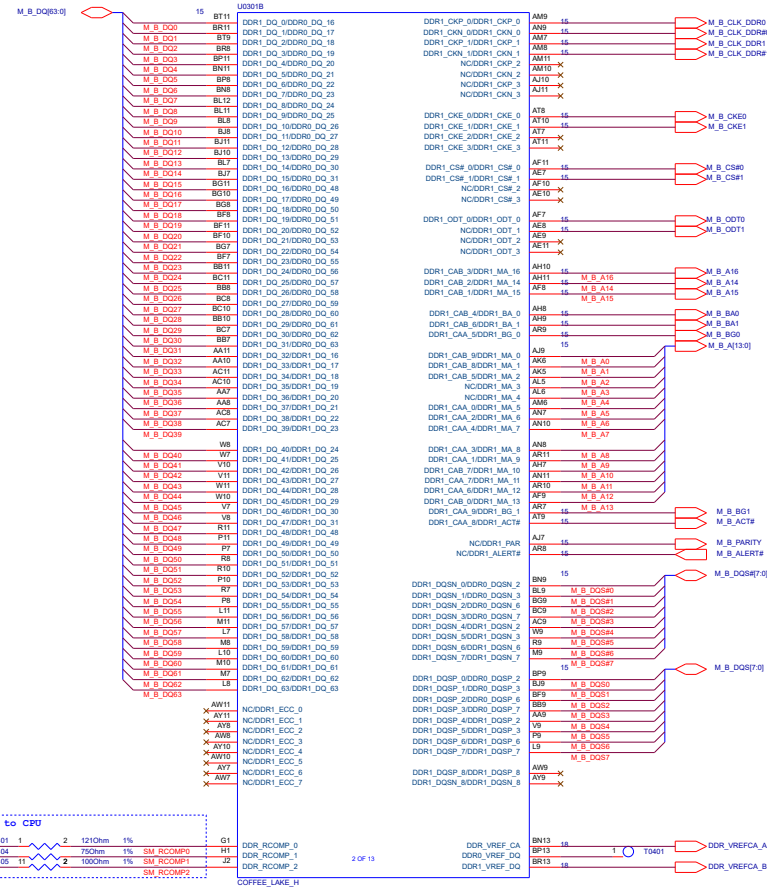
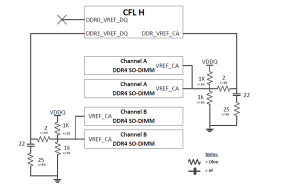
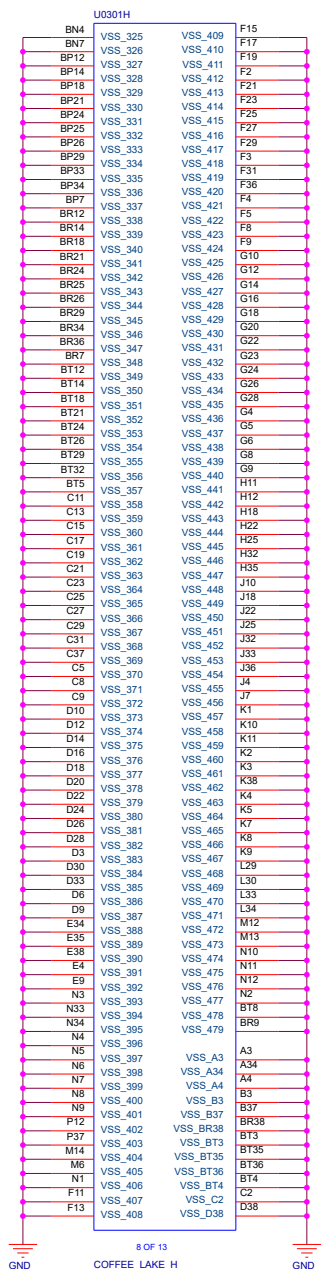
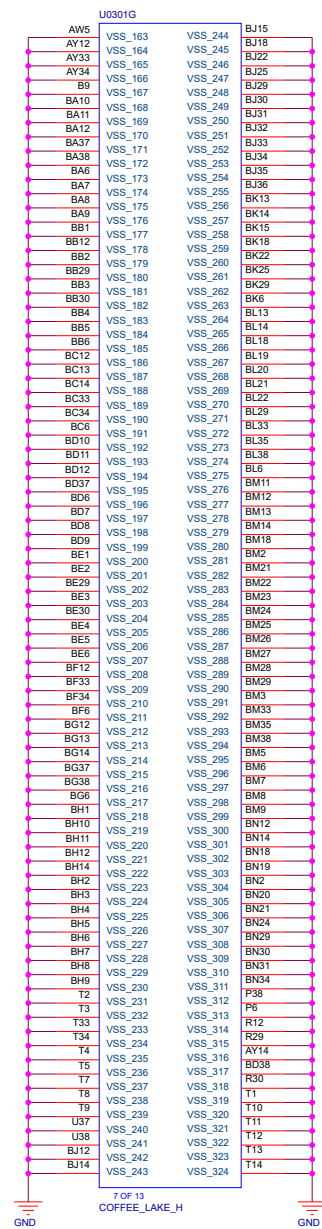
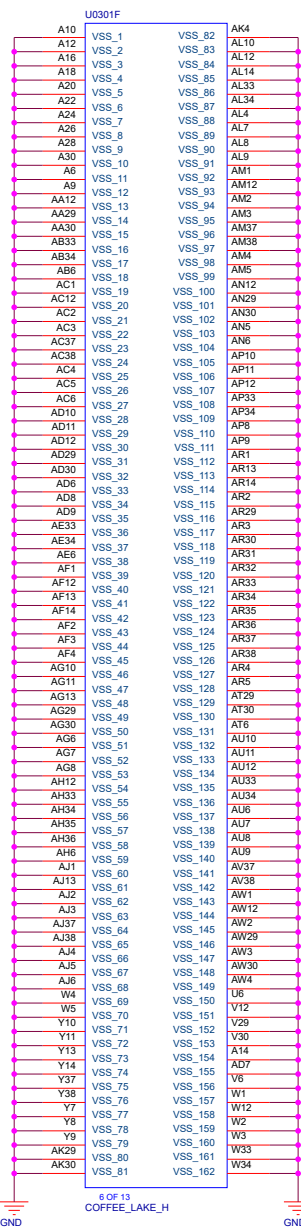
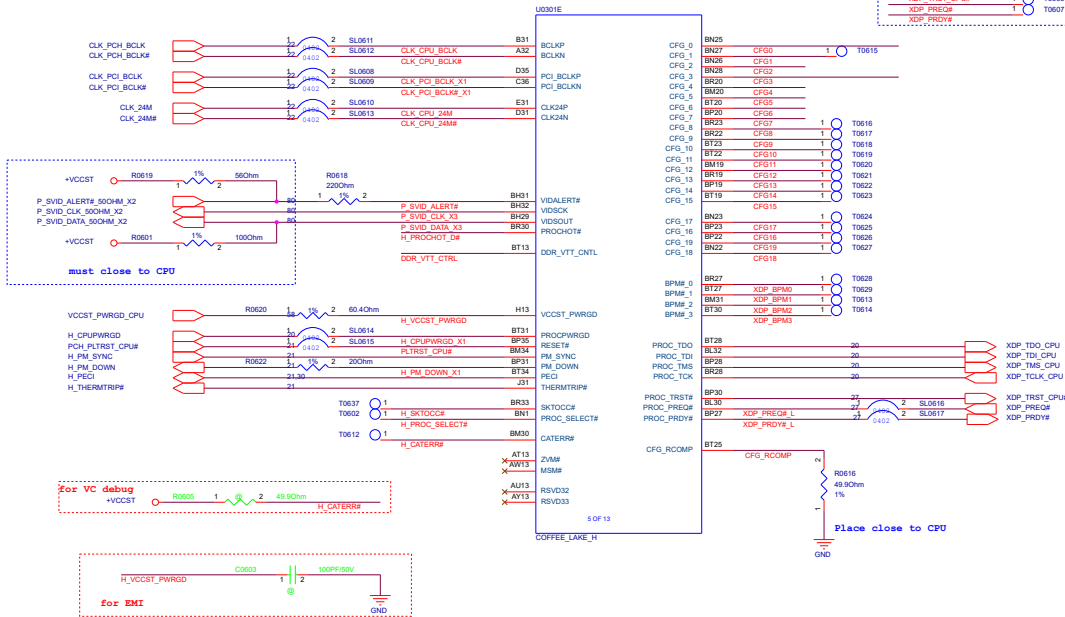


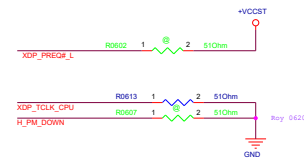
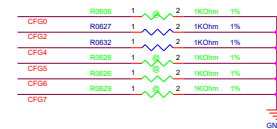
Figure 4-25. CFL H DDR4 SO-DIMM V_{REF-CA} Overview







CFG Straps



CFG Straps for Processor

CFG[0] : Stall reset sequence after PCU PLL lock until de-asserted
--

- 1 : (Default) Normal Operation; No stall
- 0 : Stall

CFG[1] : Reserved Configuration Lane

Reserved Configuration Lane

CFG[2] : PCI Express® Static x16 Lane Numbering Reversal

- 1 : (Default) Normal Operation
- 0 : Lane Numbers Reversed

CFG[3] : Reserved configuration lanes

Reserved Configuration Lane

CFG[4] : eDP Enable

- 1 : Disabled
- 0 : Enabled

CFG[6:5] : PCI Expre

- 00 : 1 x8 , 2 x4 PCI Express*
01 : Reserved

- 10 : 2 x8 PCI Express*
- 11 : 1 x16 PCI Express*

CFG[7] : PEG Training

- 1 : (Default) PEG Transfer
- 0 : PEG Wait for PIO

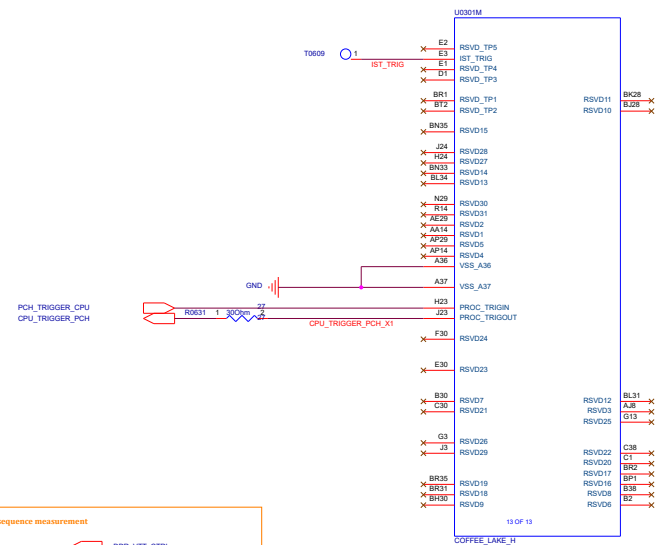
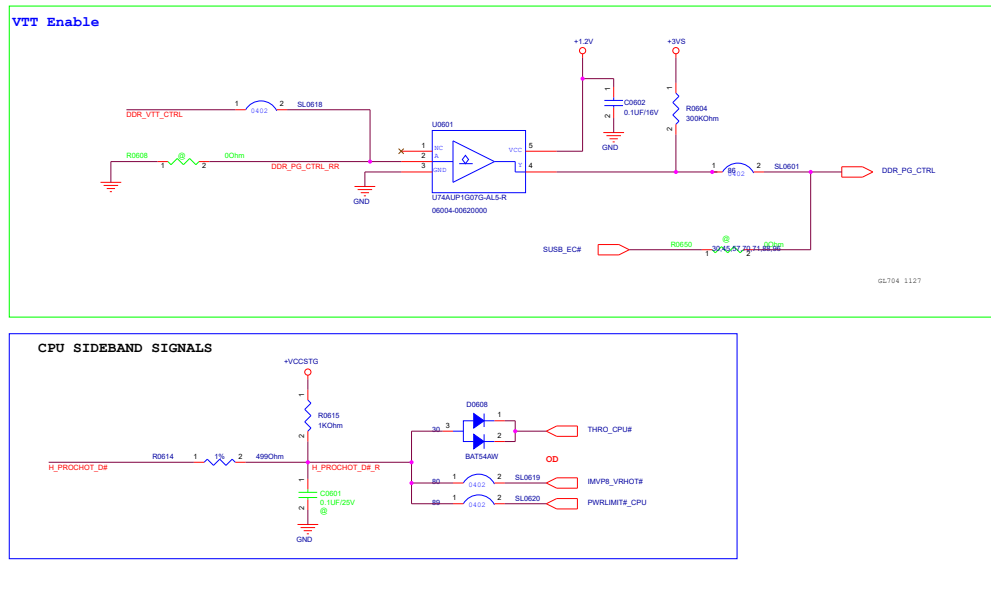
--	--

CFG[19:8] : Reserved Configuration Lanes

Reserved Configuration Lane

Refer : Intel 570805_CFL_EDS_Vol1_Rev1.1, Table 6-7, P.116

DDR_VTT_CNTL:
System Memory Power Gate Control:
Disables the platform memory VTT regulator in C8 and deeper and S3.



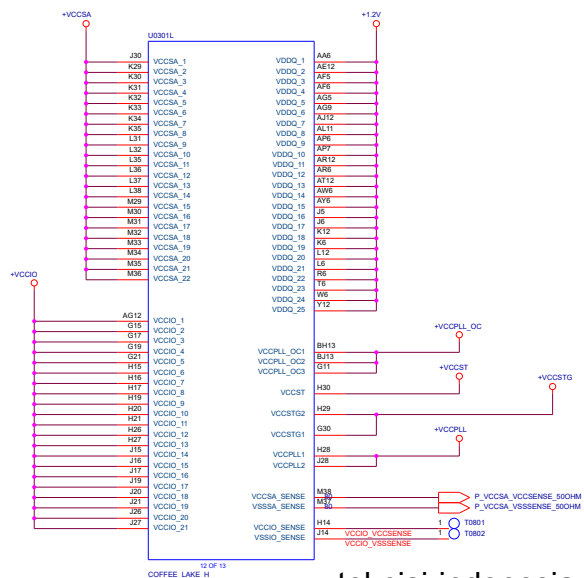
For power sequence measurement

29 DDR_VTT_CTRL DDR_VTT_CTRL

29 H_CPUPWRGD_X1 H_CPUPWRGD_X1

<Close Design>

		Project Name GL704GSM		Rev R1.1
Title : ****				
Size C	Dept.: ASUSTeK COMPUTER INC.		Engineer:	Gaming RD4 EE1
Date: Friday, July 27, 2018			Sheet	7 of 103



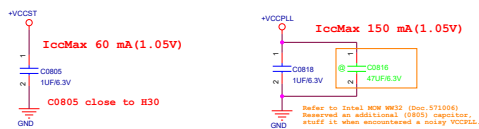
Configuration		Estimated SoC Power Delta from Config #1 to #2
Config #1 (Premium)	Config #2 (Volume)	CFL H
VccST off in S3	On in S3	+25-30mW
VccPLL_OC off in S0/C10	On in S0/C10	+3-10mW
VccPLL_OC off in S0ix	On in S0ix	+3-10mW

Main Source	1st PWR	2nd PWR	3rd PWR
AC_BAT_SYS	+1.05VSUS	+VCCST	+1.05V_VCCST
		+VCCSTG	+1.05V_VCCPLL
	+1.2V	+VDDQ_CPU	
		+VCCPLL_OC	
	+VCCSA		
	+VCCIO		

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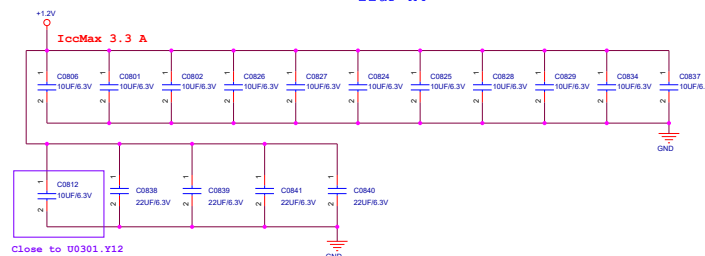
+VCCST/+VCCPLL
DECAPS Place Back Side (TOP)

Rev 0430

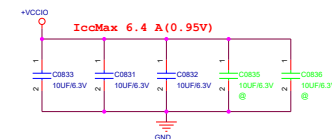


+VDDQ DECAPS Place Back Side (TOP)

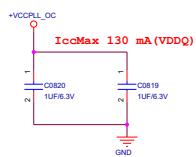
10uF x 11
22uF x 4



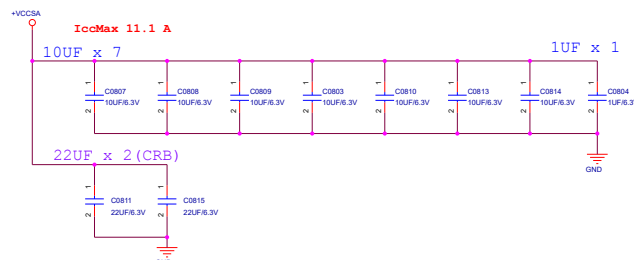
+VCCIO DECAPS Place Back Side (TOP)



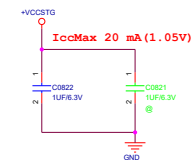
+VCCPLL_OC DECAPS Place Back Side (TOP)



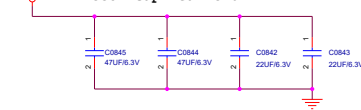
+VCCSA DECAPS Place Back Side (TOP)

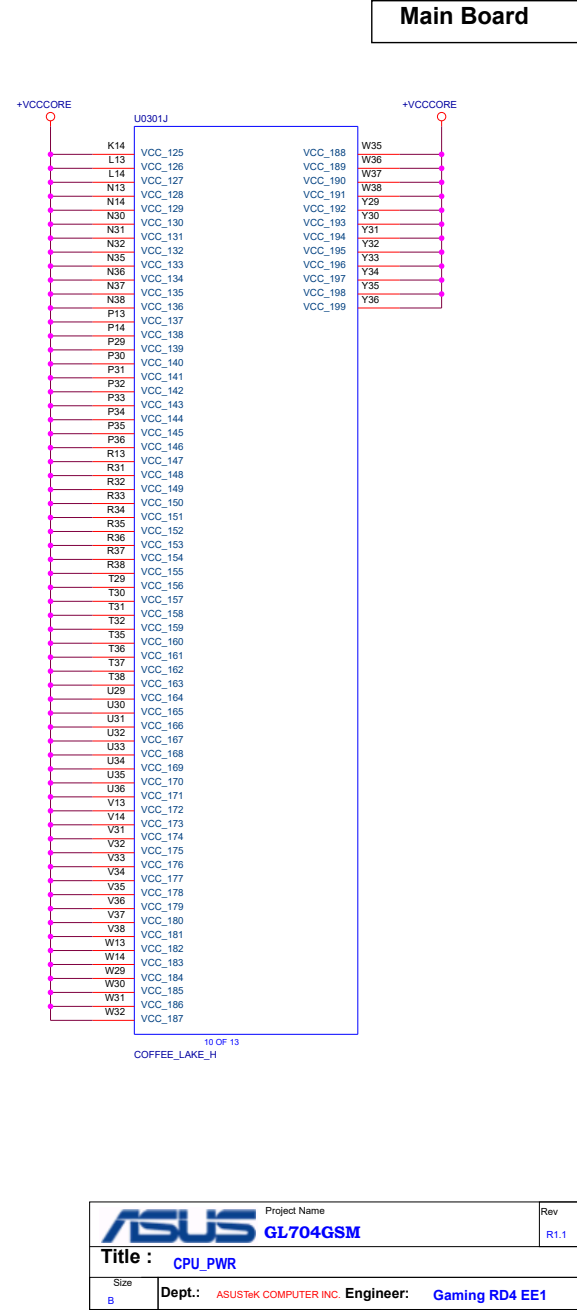
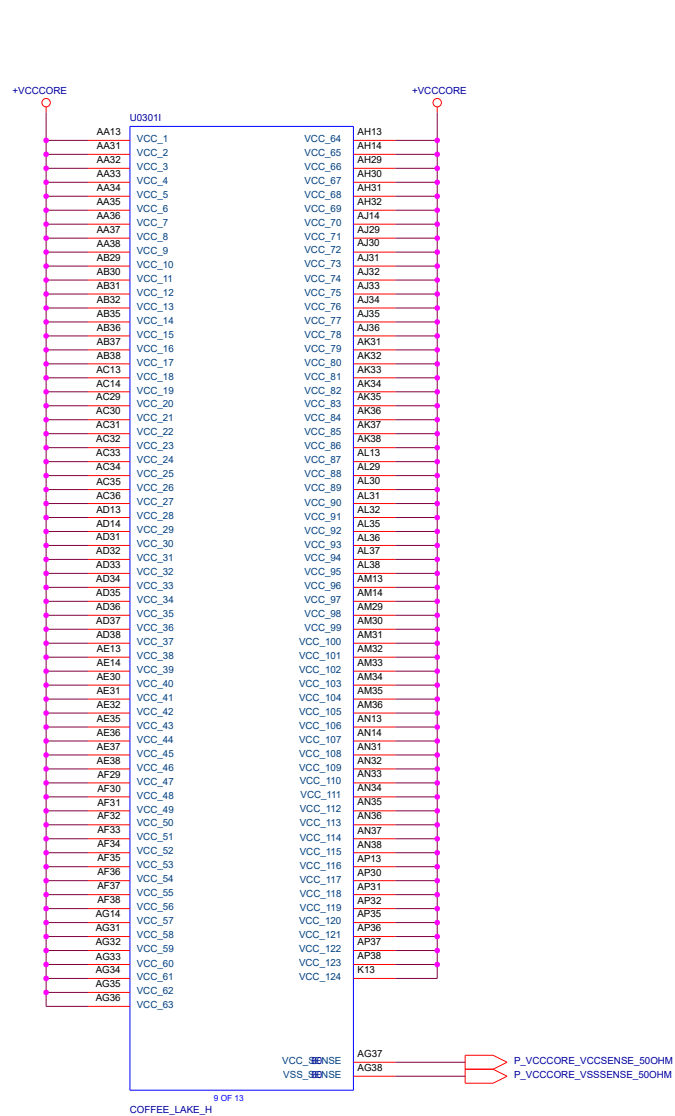
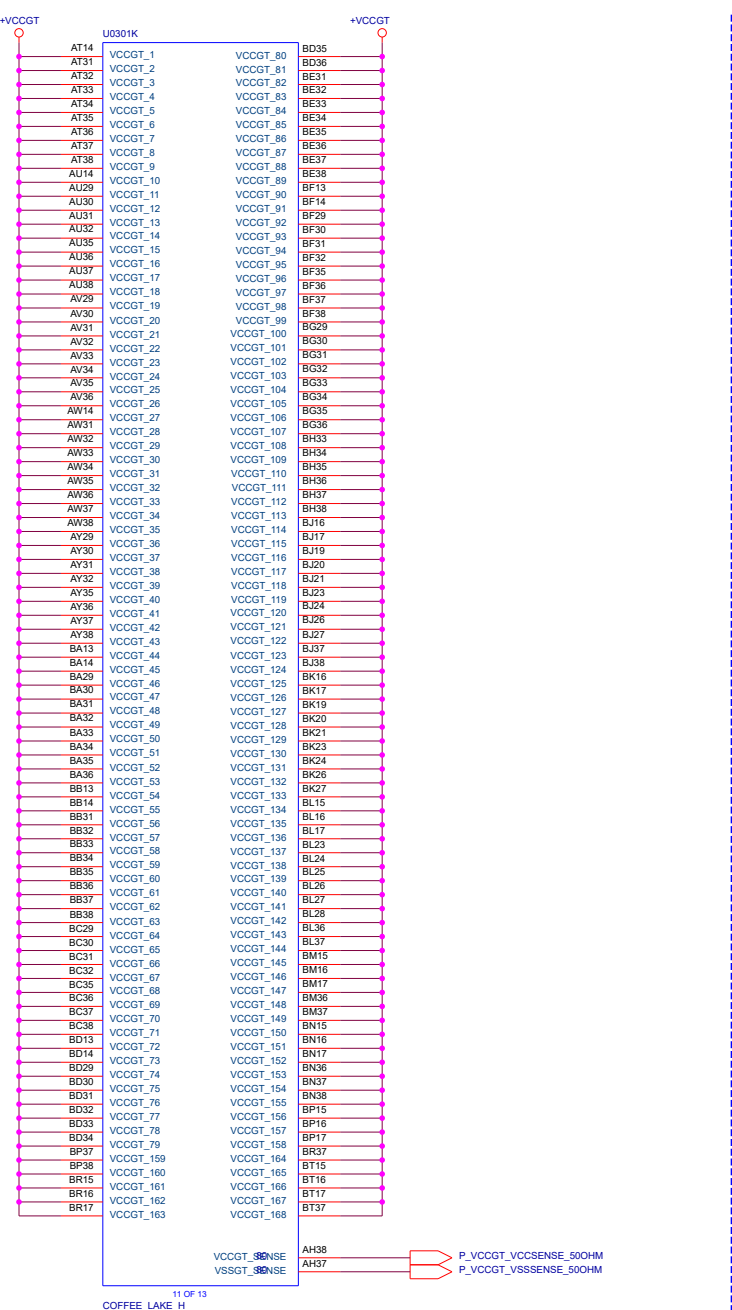


+VCCSTG DECAPS Place Back Side (TOP)



+VCCSA cap near CPU





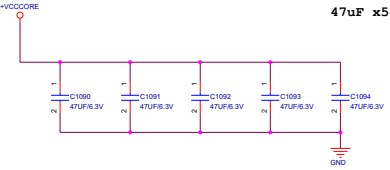
+VCCORE DECAPS Place Back Side (TOP)

22uF x12
10uF x21
1uF x24



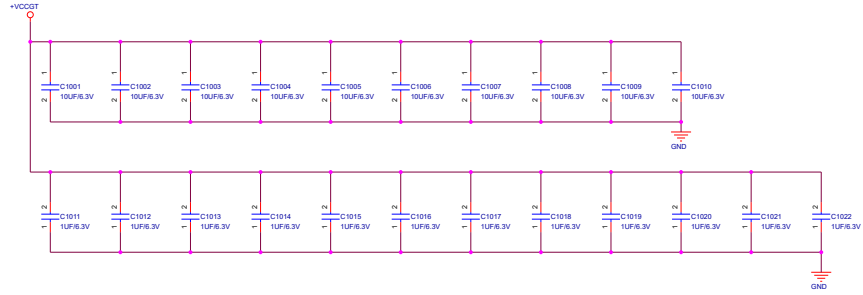
+VCCORE cap near CPU

47uF x5



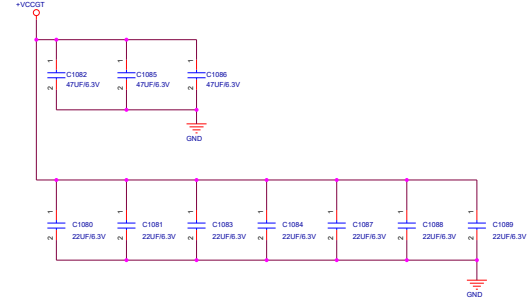
+VCCGT DECAPS Place Back Side (TOP)

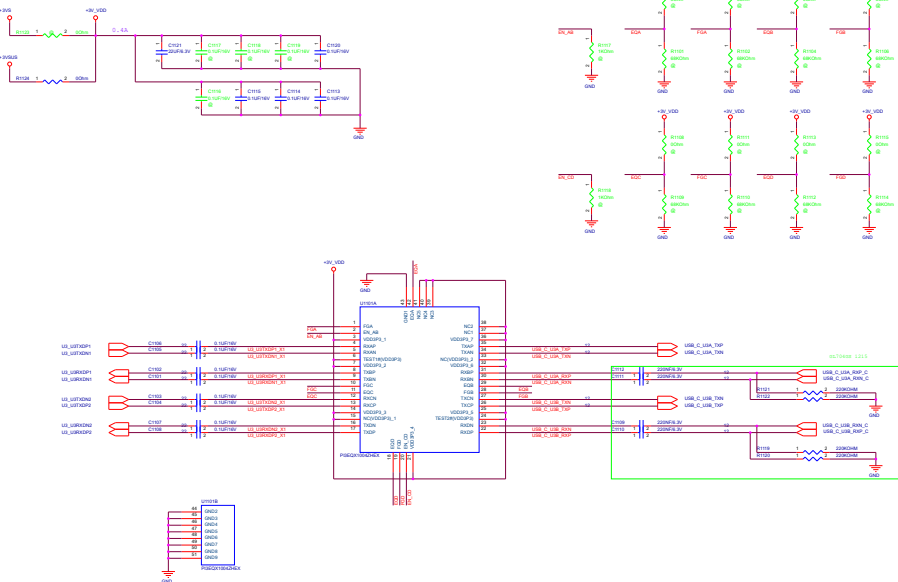
10uF x10
1uF x12



+VCCGT cap near CPU

47uF x3
22uF x7





	Squalizer setting (dB)
HQ A/B/C/D	500Hz
S (1k to Gnd)	10.9
S (Short to Gnd)	6.7
F (Floating)	8.9
I (0 to VDD)	13.1

	Flat Gain setting
PG A/B/C/D	dB
S (1k to Gnd)	-3
S (Short to Gnd)	-1.5
F (Floating)	0
I (0 to VDD)	+2

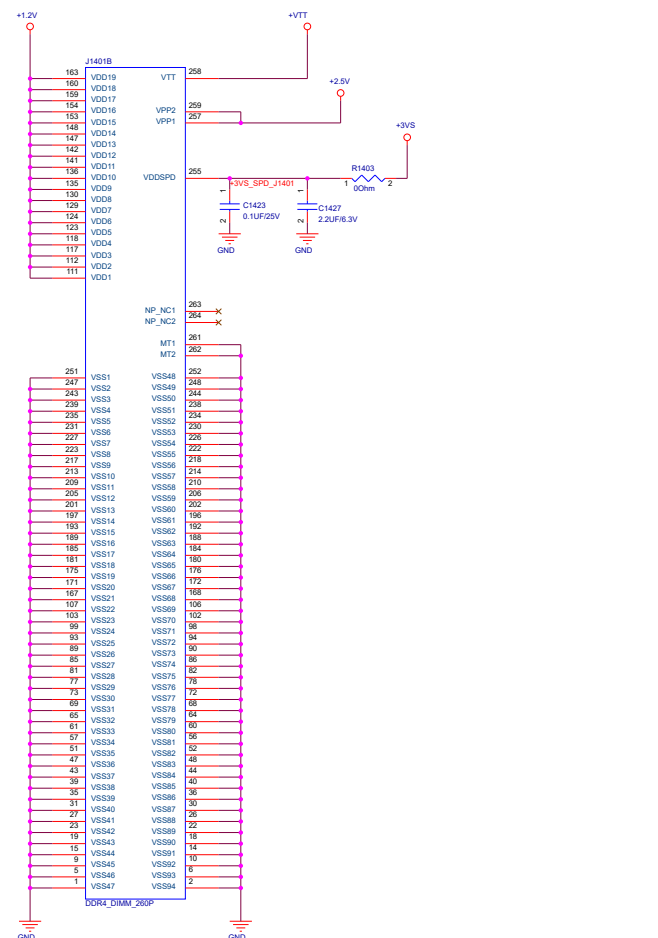
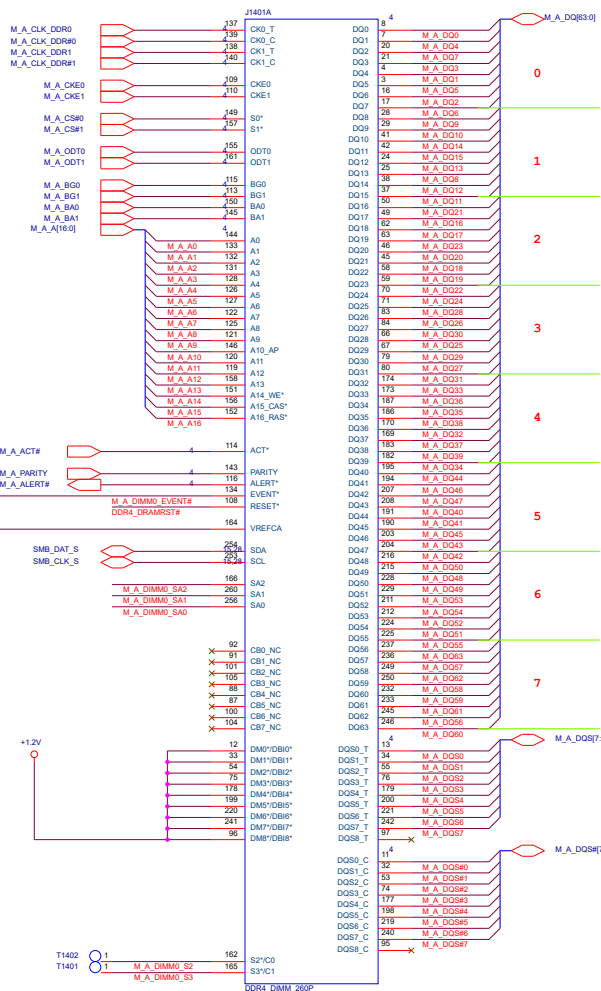
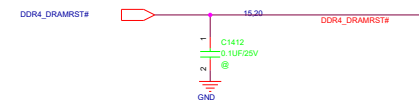
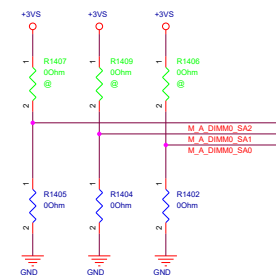
	Channel Enable setting
EN	With internal 300kOhm pull-up Resistor
0	Disable
1	Enable

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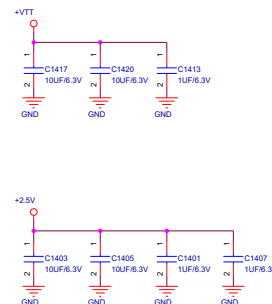
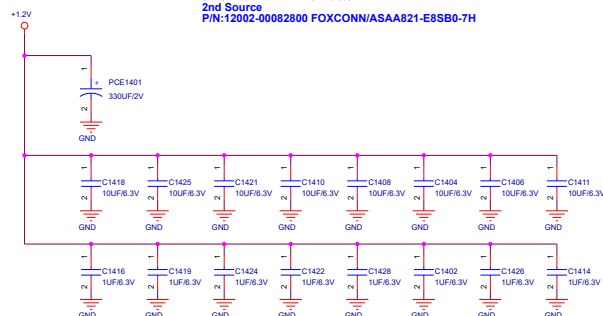
SODIMM CHA-DIMM0
BOT H8.0mm REV (J1401)

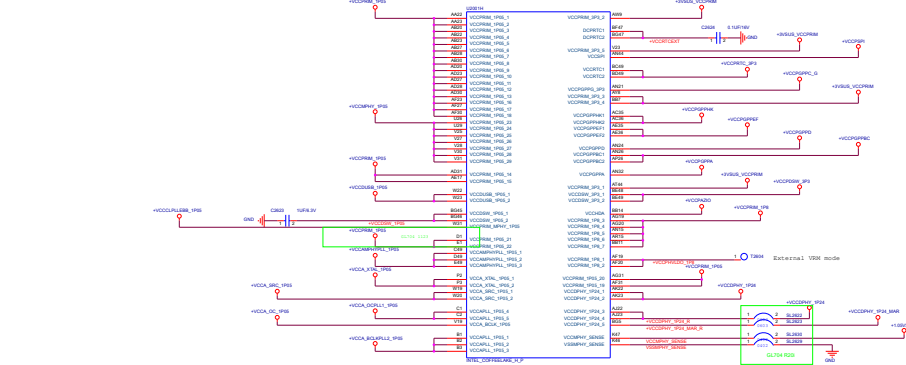
12002-00080100
DDR4 DIMM 260P 4H REV
20171207

```
SPD ADDRESS FOR CHANNEL-A
WRITE ADDRESS: 0xA0
READ ADDRESS: 0xA1
SA0 = 0; SA1 = 0; SA2 = 0
```



12002-00080100
J1401 DDR4 DIMM Connector
2nd Source
P/N:12002-00082800 FOXCONN/ASAA821-E8SB0-7H





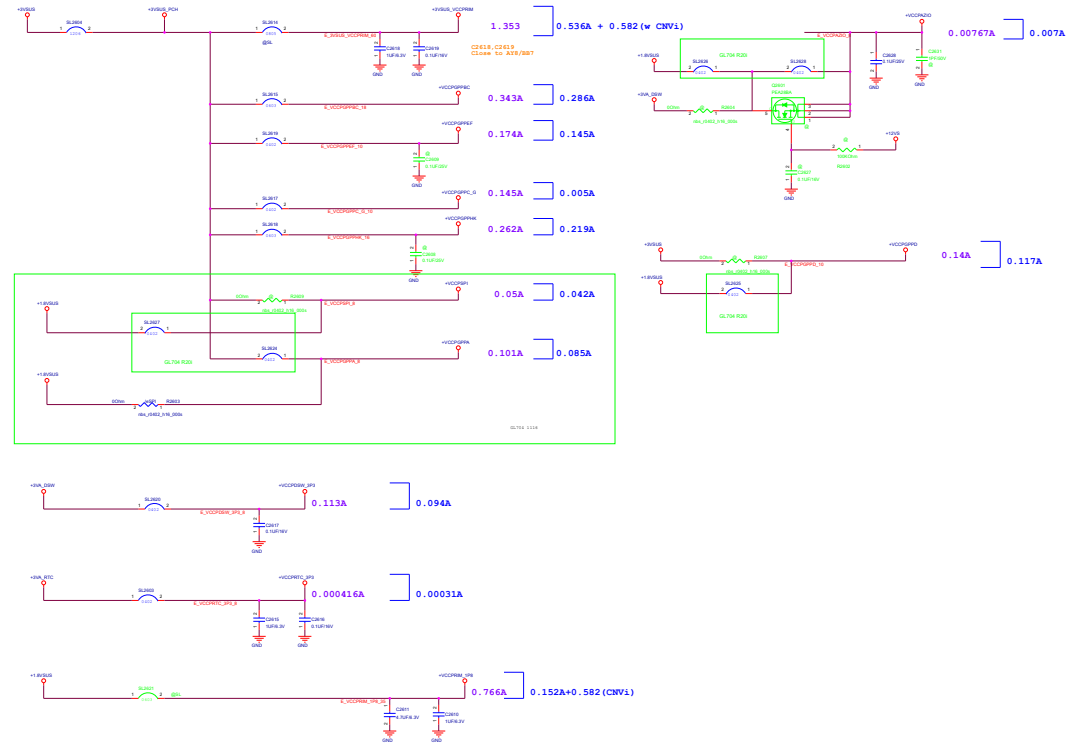
Refer to CS-A-P-PCB-R02-R1.0 (Doc. 571182)

Table S-1. Power Descriptions for PCH in CNL-H

Name	Description
VCCPHVLD0_1P8	1.8V Primary Well. On the motherboard, this power pin must be connected to 1.8V VCCPH_1P8 and internal 1.8 V VRM Mode and GP-NC-020 in Exclusive 1.8V VRM Mode .
VCCPWLDO_1P8	AF19
VCCPWLDO_1P8	AF20
VCCPHV_1P24	1.24V for CNV1 logic. This rail is generated internally with a LDO and needs to be routed to the motherboard so that this rail can be supplied back to the SoC. Refer to the Cannon Lake -U1Y PDK for implementation details.

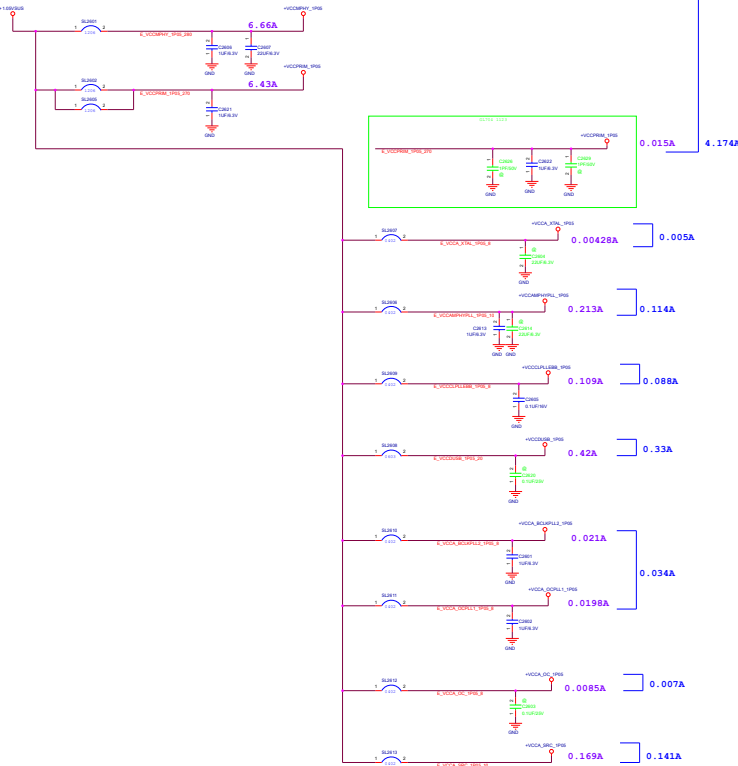


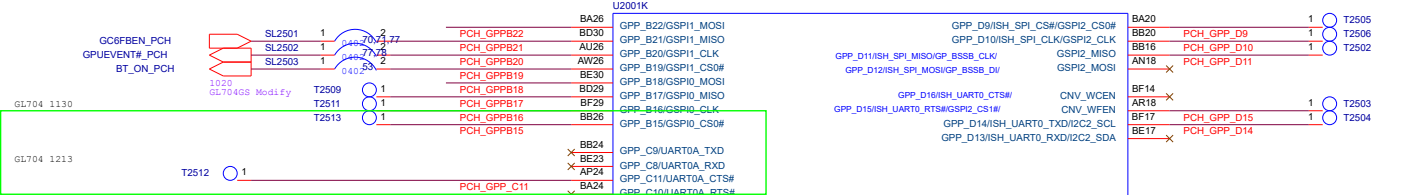
Purple reference CRB
Blue reference RDS



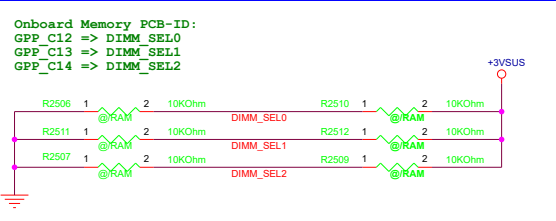
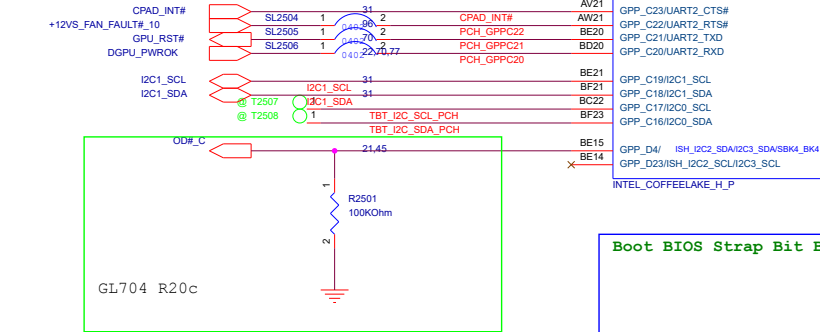
GPIO Voltage Level

Group	Power pin	Power option	Power plane
GPP_A	VCCGPPA	1.8V or 3.3V	+3VSDS
GPP_B	VCCGPPBC	1.8V or 3.3V	+3VSDS
GPP_C	VCCGPPBC	1.8V or 3.3V	+3VSDS
GPP_D	VCCGPPD	1.8V or 3.3V	+1.8VSDS
GPP_E	VCCGPPF	1.8V or 3.3V	+3VSDS
GPP_F	VCCGPPF	1.8V or 3.3V	+3VSDS
GPP_G	VCCGPP3_3P3 VCCGPP3_1P8	Dynamic voltage to be config IODS	+3VSDS
GPP_H	VCCGPPH	1.8V or 3.3V	+3VSDS
GPP_I	VCCGPPH	3.3V Only	+3VSDS
GPP_J	VCCPRIM_1P8	1.8V Only	+1.8VSDS
GPP_K	VCCGPPH	1.8V or 3.3V	+3VSDS
GPIO	VCCDSD_3P3	3.3V Only	+3VA_DSW



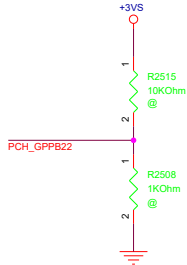


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	Hynix (2Gb)	XXX (2Gb)	Micron (2Gb)
DIMM_SEL0			
DIMM_SEL1			
DIMM_SEL2			

Boot BIOS Strap Bit BBS



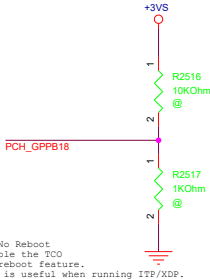
PCH_GPPB22: weal internal pull down

PU	LPC
PD	SPI (Default)

	US	UK	JP
KB_LANG_ID0 (KB pin33)	1	0	0
KB_LANG_ID1 (KB pin34)	0	0	1

US:PIN 33 NC , PIN 34 GND
UK:PIN 33,34 GND
JP:PIN 33 GND , PIN 34 NC

No Reboot

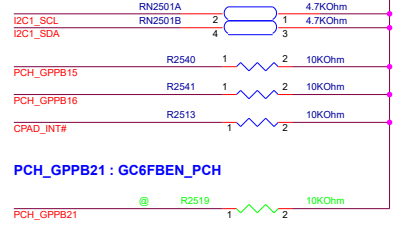
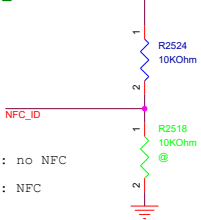


NOTE: Enable No Reboot
PCH will disable the TCO
Timer system reboot feature.
This function is useful when running ITP/XDP.

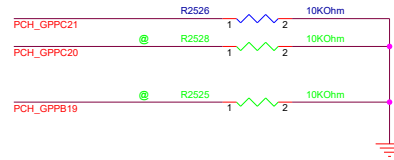
PCH_GPPB18: weak internal pull down

PU	Enable
PD	Disable (Default)

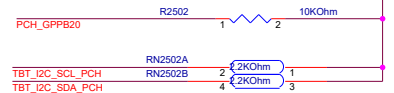
NFC ID

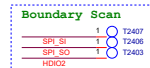
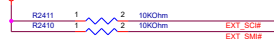


PCH_GPPC21: GPU_RST# PCH_GPPC20: DGPU_PWROK

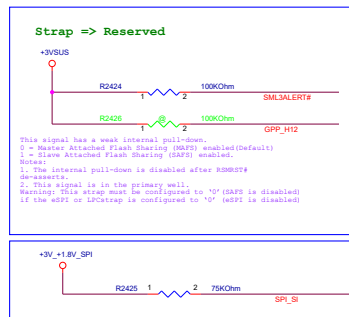
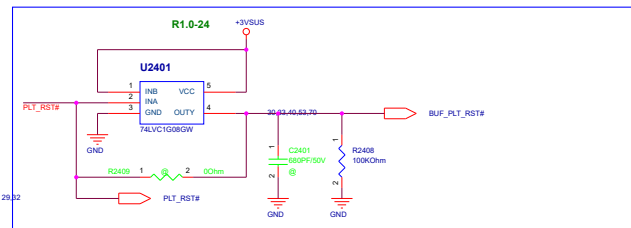
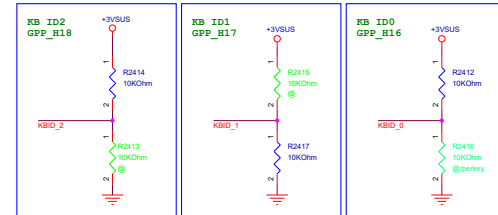
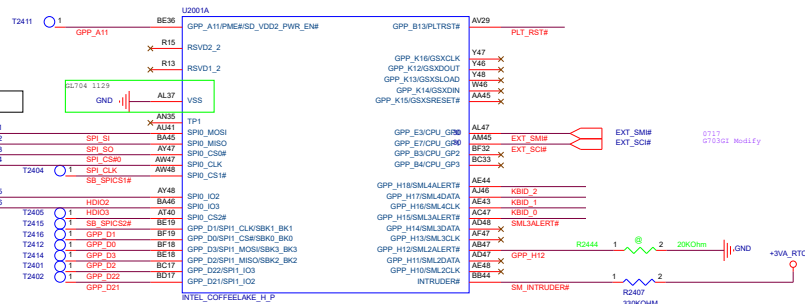


PCH_GPPB20 : GPU_EVENT#_PCH



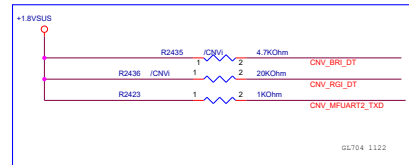
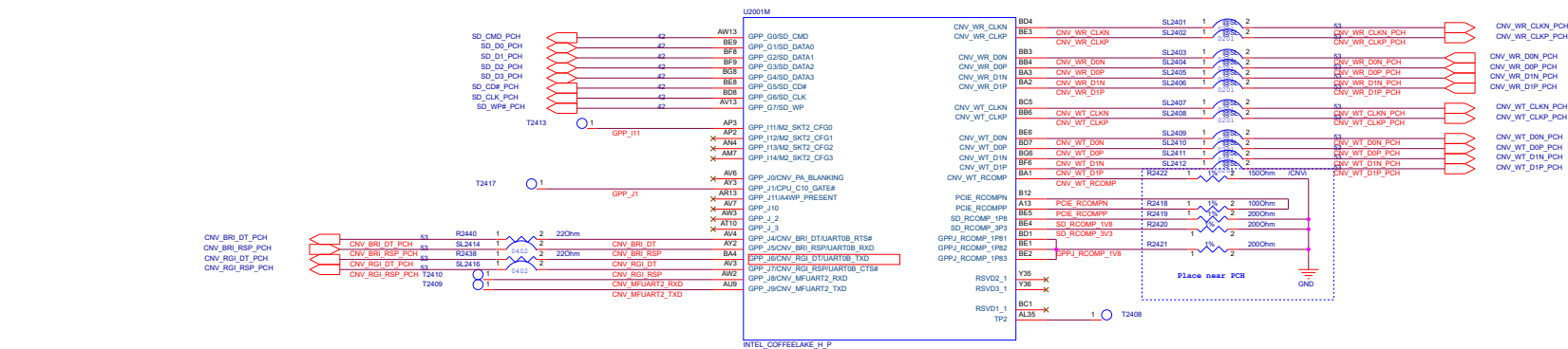


Refer to CFL-H PDG R0.7 (Doc.571391)
SPI0 Series Resistor : 50ohm for Single Flash Topology



PCH Side (HW 請依照此表格做設計判斷)				
Code	ROG RGB KB Type	KBID 2 (GPP_H18)	KBID 1 (GPP_H17)	KBID 0 (GPP_H16)
0x00	Non-RGB	H	H	H
0x01	RGB per Region via QWER/WASD modes	H	H	L
0x02	RGB per Region via 4 zones	H	L	H
0x03	RGB per key	H	L	L

5. 需請 BIOS RD 在 KB ID 讀取的部分, 額外加入 **Reverse code**, 以符合第 1 點 table



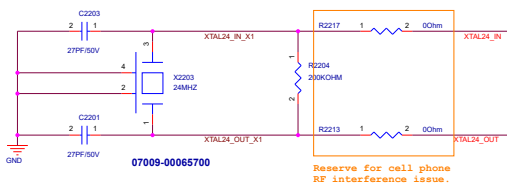
GPP J4(CNV BRI DT):
This signal has a weak internal pull down.
0 = 38.4MHz XTAL frequency selected.(Default)
1 = 24MHz XTAL frequency selected.

(M0W39)
Pin Strap for XTAL frequency selection
An external 4.7K PU to VCC(1.8V or 3.3V) is required
on this strap for PCH 24 MHZ XTAL operation

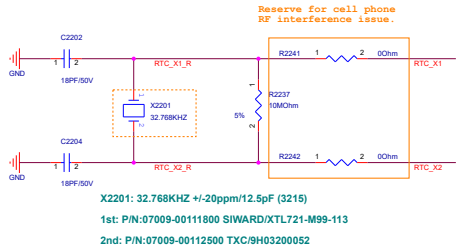
```
GFP_J6(CNV, RGI, DT):
An External pull-up or pull-down is required.
0 = Integrated CNVi enable.
1 = Integrated CNVi disable.
[Intel FAE]
RGI DT has an automatic detect CNVi mechanism,
please do not use external PD.
The CRF has an internal strong 1K PD already.
Do not leave this pin float,
if CNVi is not used, it still need a 20K ohm PU.
```

```
GPP_J9/CNV MFUART2 TXD:
The signal has a weak internal pull-down
0 = VCCSPI is connected to 3.3V rail
1 = VCCSPI is connected to 1.8V rail
```

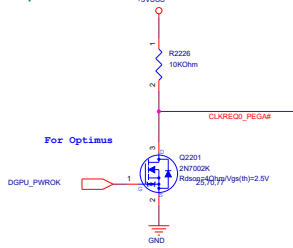
XTAL 24MHz



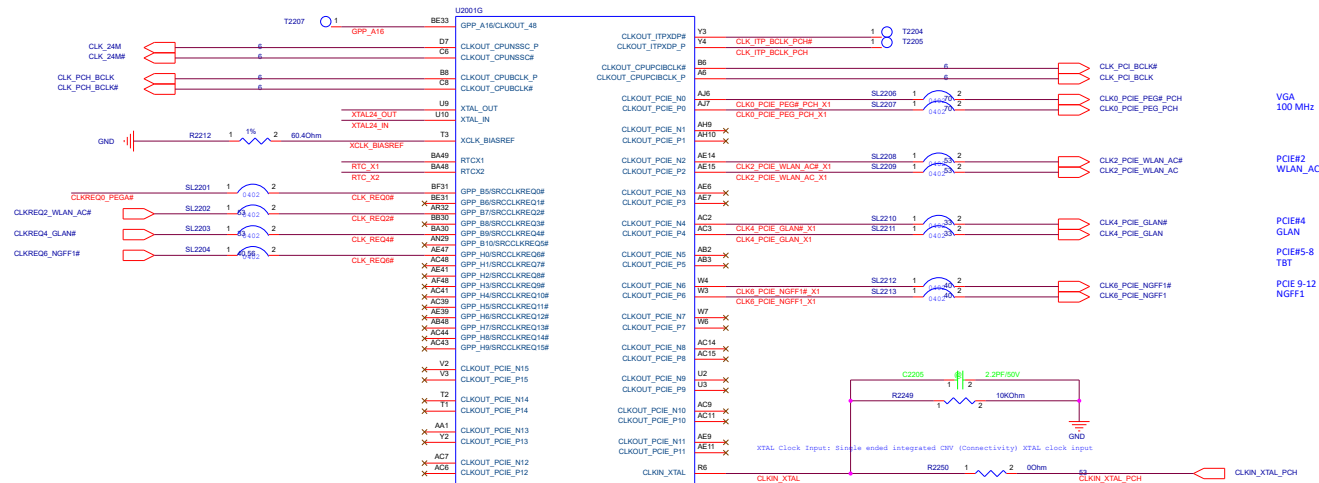
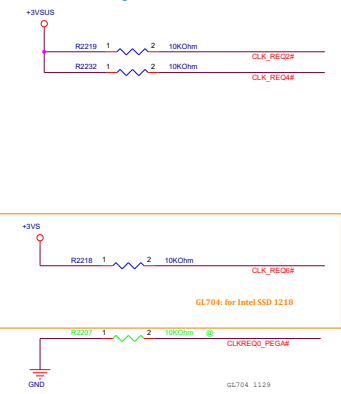
RTC CRYSTAL 32.768KHz



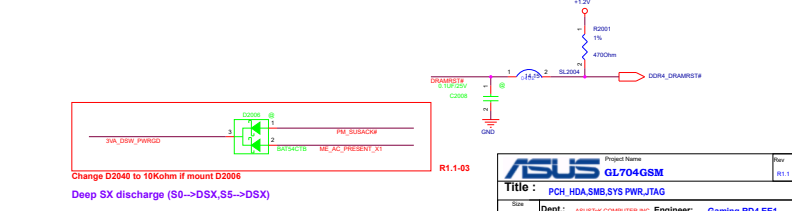
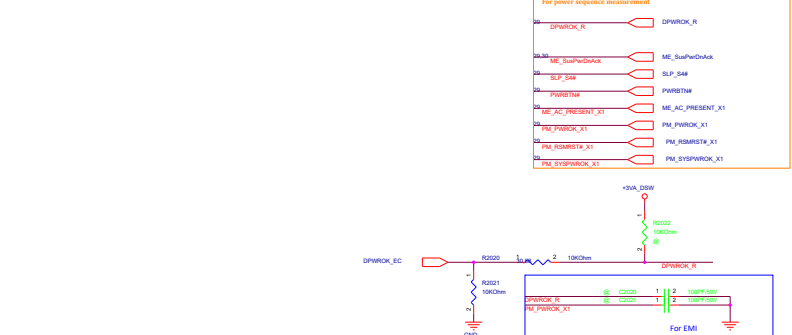
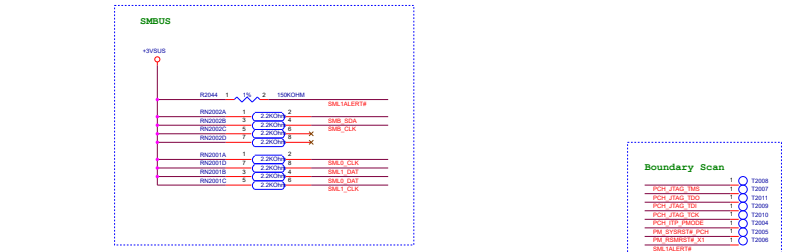
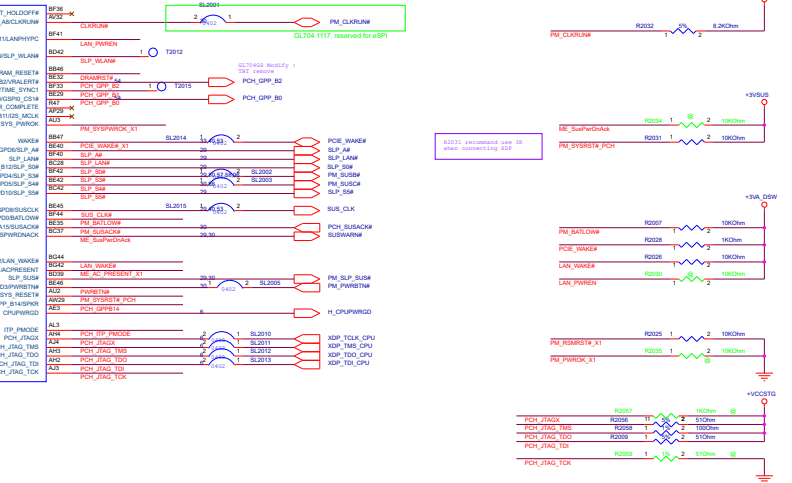
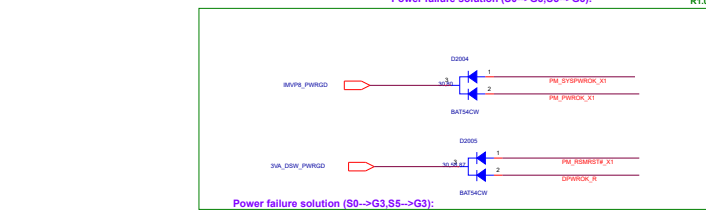
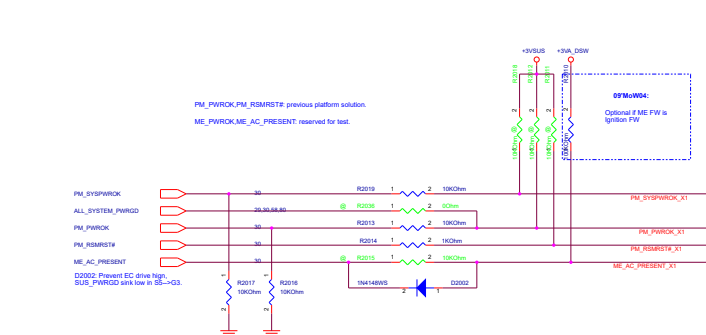
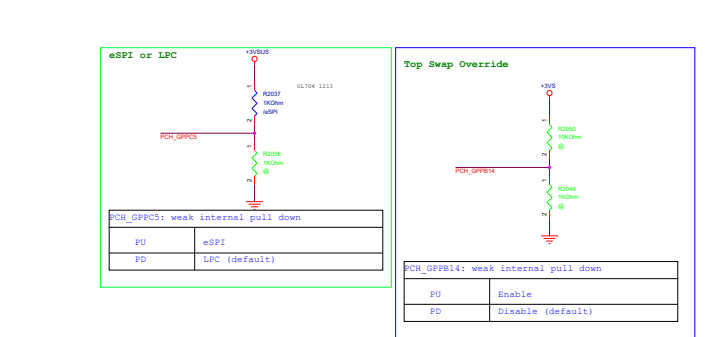
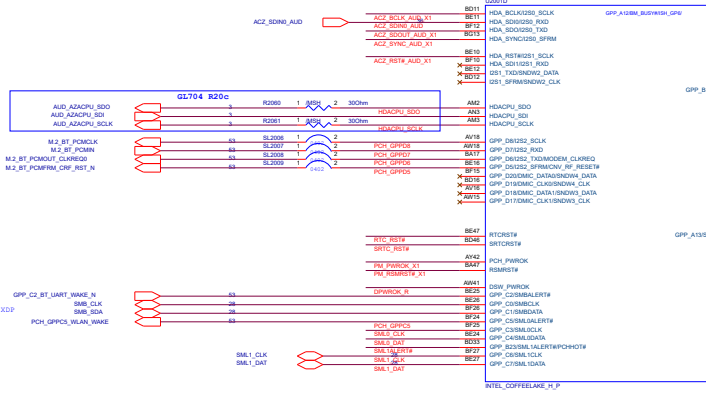
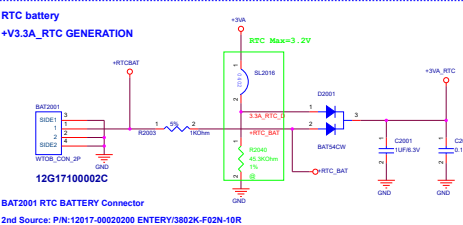
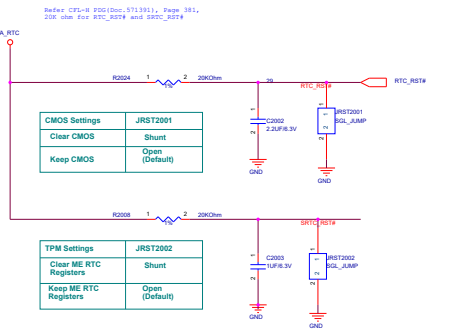
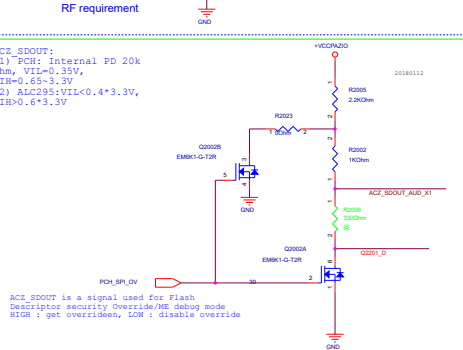
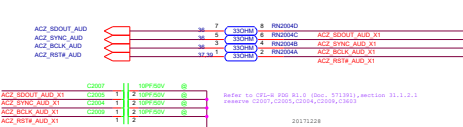
DGPU CLKReq#



PCH CLKREQ Setting:



HD Audio





Project Name

GL704GSM

Rev

R1.1

Title : *****

Size

B

Dept.: ASUSTeK COMPUTER INC. **Engineer:** **Gaming RD4 EE1**

Date: Friday, July 27, 2018

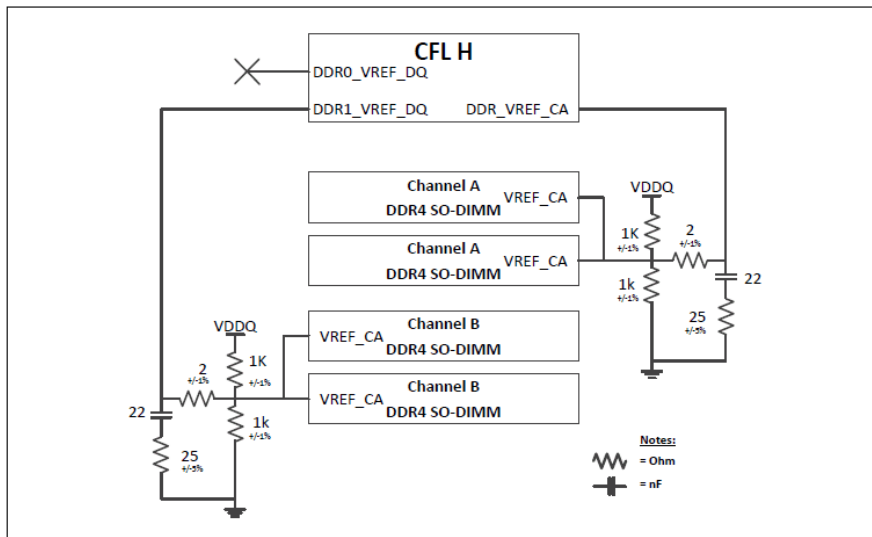
Sheet

19

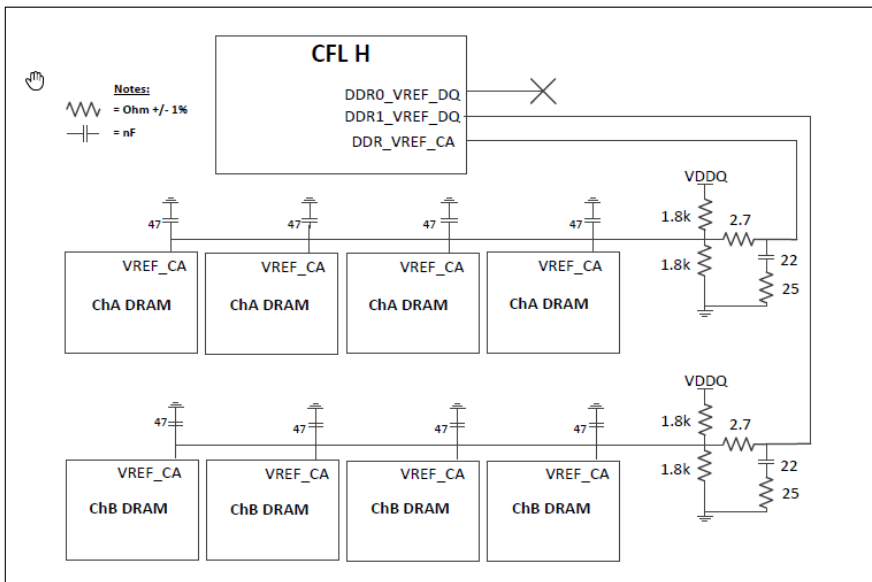
of

103

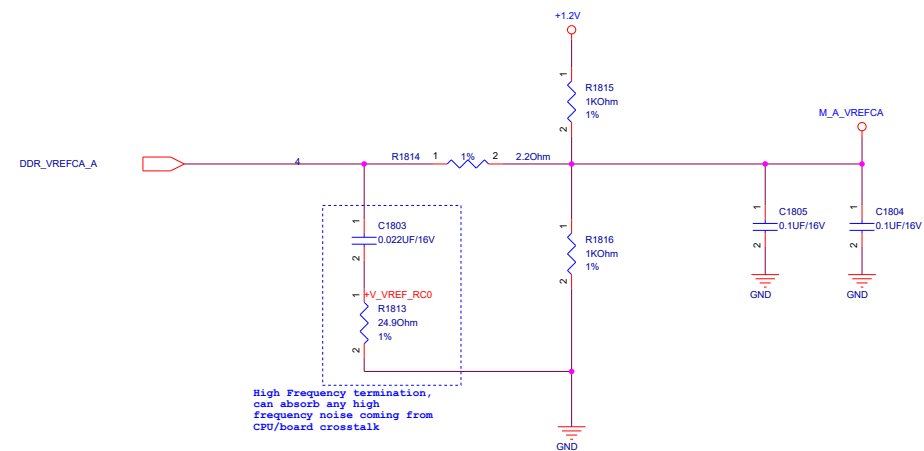
CFL H DDR4 SO-DIMM V_{REF-CA} Overview



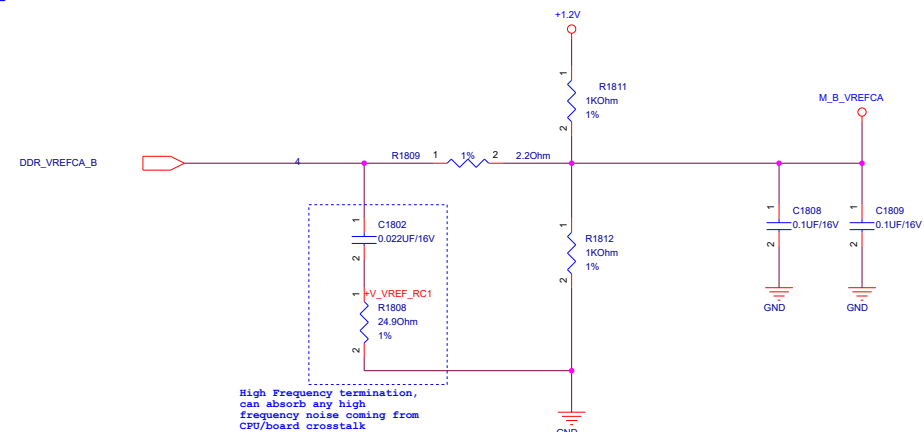
CFL H DDR4 x16 Memory Down V_{REF-CA} Overview



Vref for CHA DIMM0



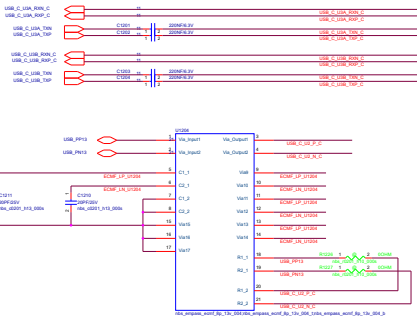
Vref for CHB DIMM0



SODIMM CHB-DIMM1
TOP H4.0mm REV (J1701)

SODIMM CHA-DIMM1
TOP H4.0mm STD (J1601)

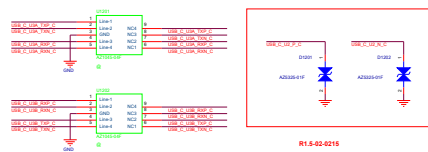
PCH USB3.0 / USB2.0



NOTE] PCH USB3.0 & Asmedia USB3.1 Co-layout of Design Rule :

1. Co-layout 元件擺置，盡量離TYPE-C Connector 越近越好。
2. Co-layout Y-型走線要越短越好。

USB3.0
ESD-Protection

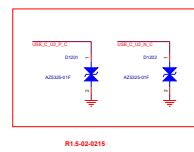


ESD PROTECTION

IN:07G028076030 ESD PROTECTION AZ1045-04F

PIN:07G028153010 ESD PROTECTION IP4284CZ10-TB

USB2.0
ESD-Protection



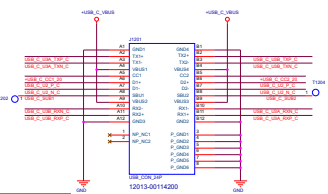
R1.5-02-0215

D4701 ESD Diode

1st Source: P/N:07024-00200200 AMAZING/AZC099-045P.R70

2nd Source: P/N:07024-00710000 NXP/PUSB2X4

TYPE-C Connector

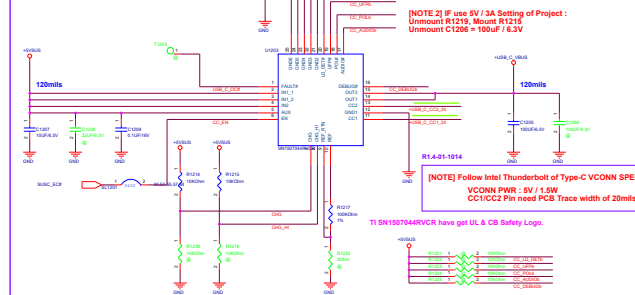


0

Figure 1. The effect of the number of trials on the number of correct responses. The number of correct responses was significantly higher than the number of incorrect responses in all cases. Error bars represent the standard error of the mean.

TI CC Logic SN1507044RVCR = TPS25810RVCR, DFP (Host), 5V / 1.5A

(ASUS Only Use)



NOTE 1] Present Application 1.5A/5V Type-C USB3.0 Device

NOTE 2] IF use 5V / 3A Setting of Project :
Amount R1219, Mount R1215
Amount C1206 = 100uF / 6.3V

[NOTE] Follow Intel Thunderbolt of Type-C VCONN SPE
VCONN PWR : 5V / 1.5W
CC1/CC2 Pin need PCB Trace width of 20mils

RVCB have get UL & CB Safety Logo

[NOTE] Vendor TI got New Name for ASUS Only, so TI SN1507044RVCR=TPS25810RVCR

Please Follow Design IP : TYPE-C CC Logic IC need use P/N:06050-00280000 TI/SN1507044RVCR

```
Set CC
I limit = 1.7A
```

Table 3. USB Type-C Current Advertisement

CHG	CHG_HI	CC CAPABILITY BROADCAST	CURRENT LIMIT (typ)	LOAD DETECT THRESHOLD (typ)
0	0	STD	1.7 A	NA
0	1	STD	1.7 A	NA
1	0	1.5 A	1.7 A	NA
1	1	3 A	3.4 A	1.95 A

6.7.2 Thunderbolt VCONN Source Electrical Requirements

17 The Thunderbolt Power Provider VCONN Electrical Parameters are specified Table 6-3.

Parameter	Description	Min	Typ	Max	Units	Note
VSrc_Snap	Minimum voltage provided to port in snap	4.75	5	5.5	V	7.5mA min
VSrc_Active	Minimum power provided to port in Active	4.75	5	5.5	V	1.5W min

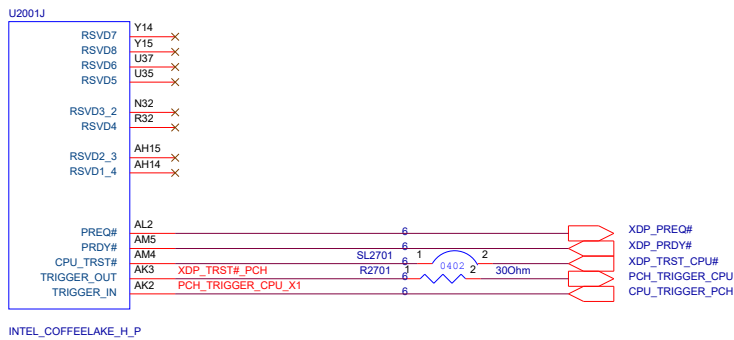
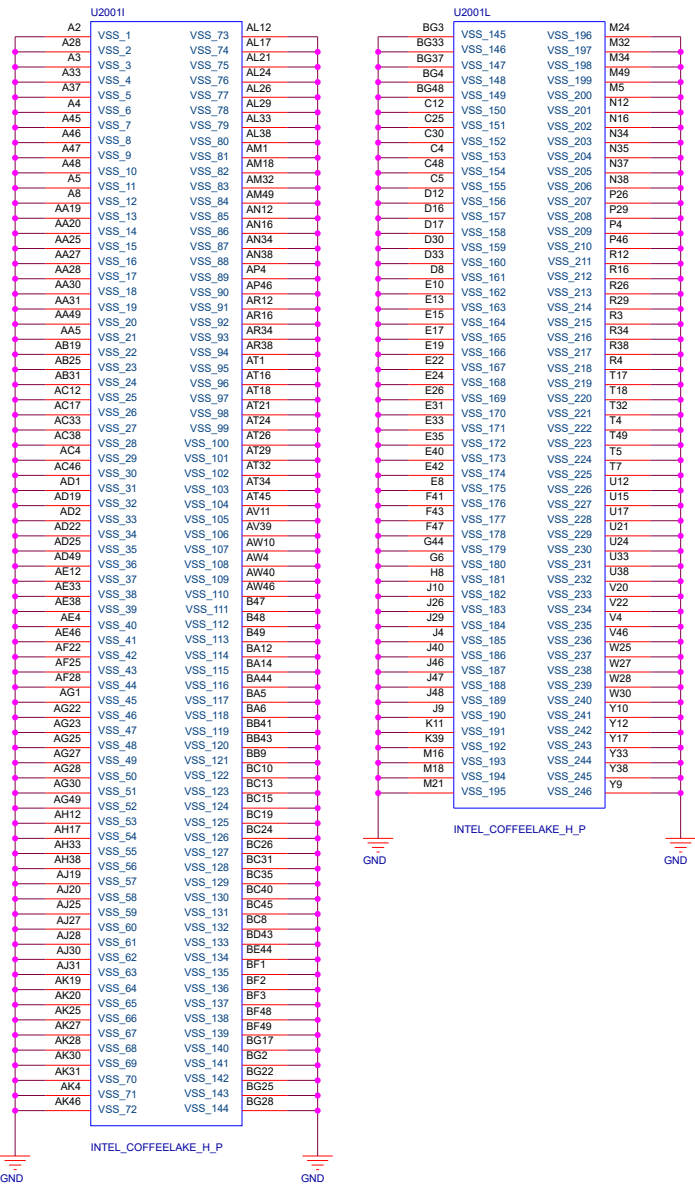
18 **Notes:**
19 L. Thunderbolt Specific Requirement

5.3 VCONN Requirements

The Thunderbolt Active Cable shall be powered from VCONN not VBUS.

The USB Type-C full featured active cable shall consume 1 W maximum from VCONN by default and 5W maximum from VCONN when in Thunderbolt or DisplayPort Alternate Modes. Ra shall be connected to VCONN on initial connection.

The Thunderbolt Active cable shall respond to S0P⁺ and S0P⁻ messages. The cable shall respond to S0P⁺ from the side of the cable which receives VCONN from the USB Type-C connector. The cable responds to S0P⁻ from the side which does not receive VCONN. The cable shall continue to respond to S0P⁺ and S0P⁻ after a VCONN_Swap.



XDP_PREQ#

XDP_PRDY#

XDP_TRST#_PCH

PCH_TRIGGER_CPU

CPU_TRIGGER_PCH

SL2701

RZ701

0402

300hm

INTEL_COFFEELAKE_H_P

GND

GND

GND

GND

GND

GND

GND

GND

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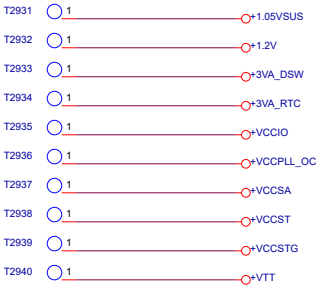
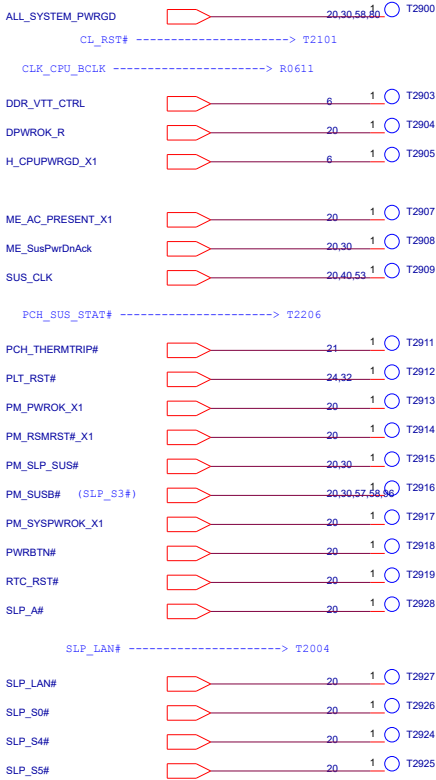
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GND

GND

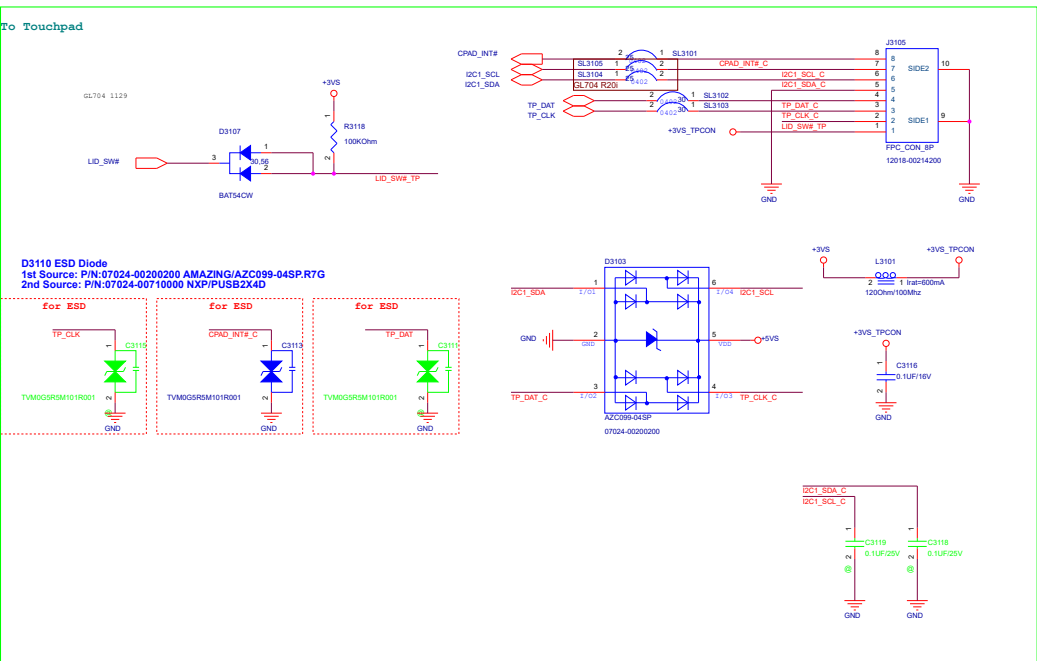
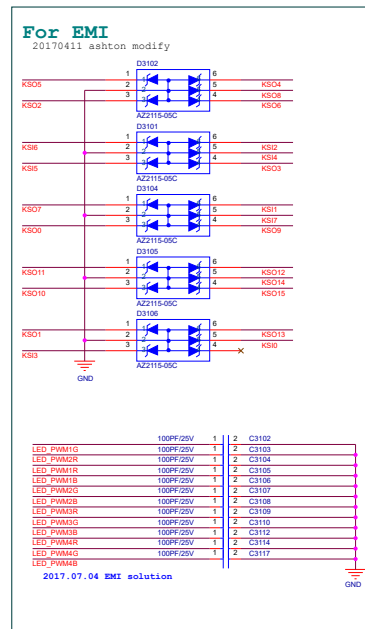
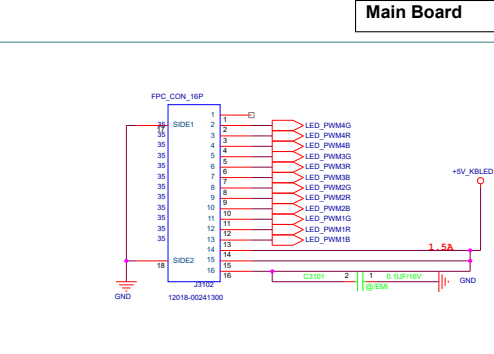
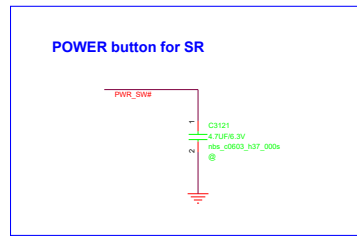
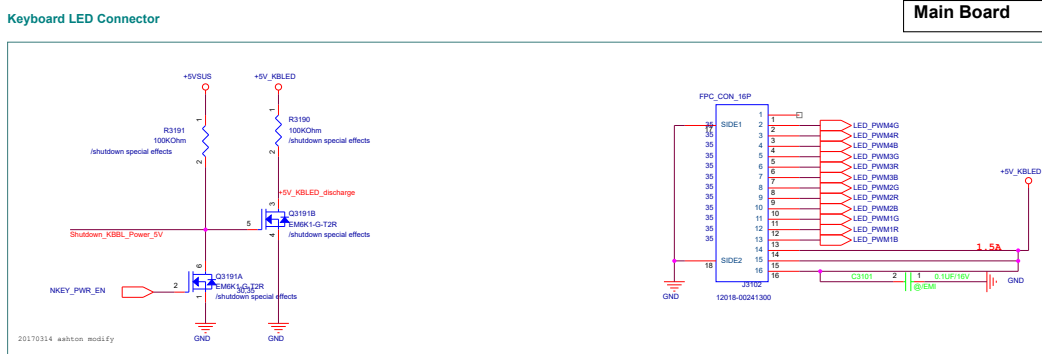
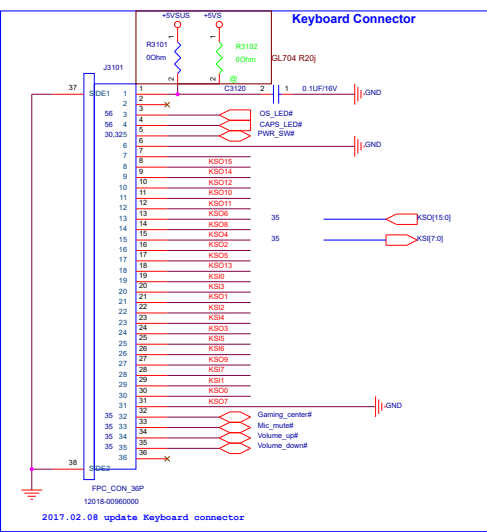
GND

GND



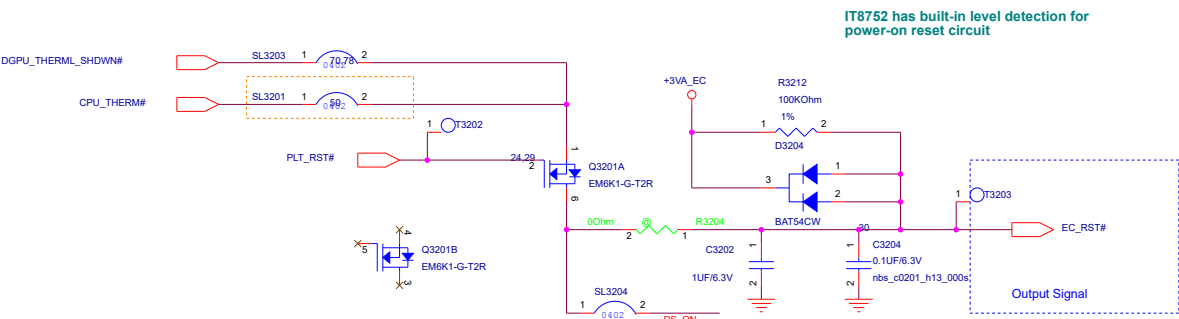
+1.0V_VCCPLL -----> R0809
H_VCCST_PWRGD -----> R0620



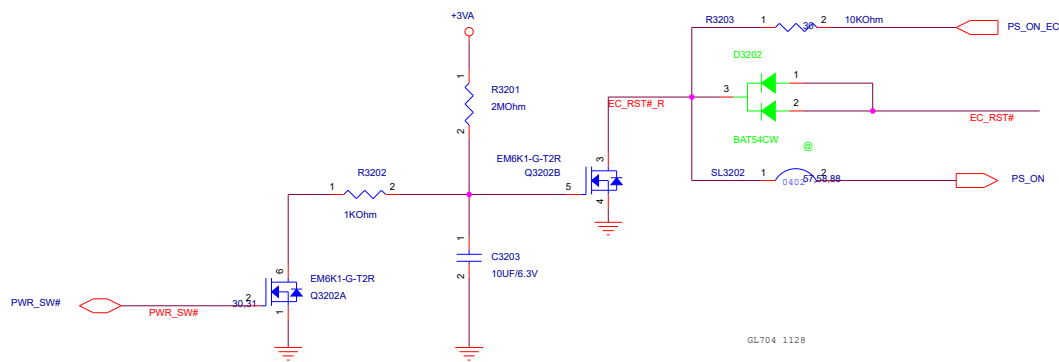


<Core Design>


Thermal Policy



battery embedded (press pwr_sw 10sec, then reset ec)

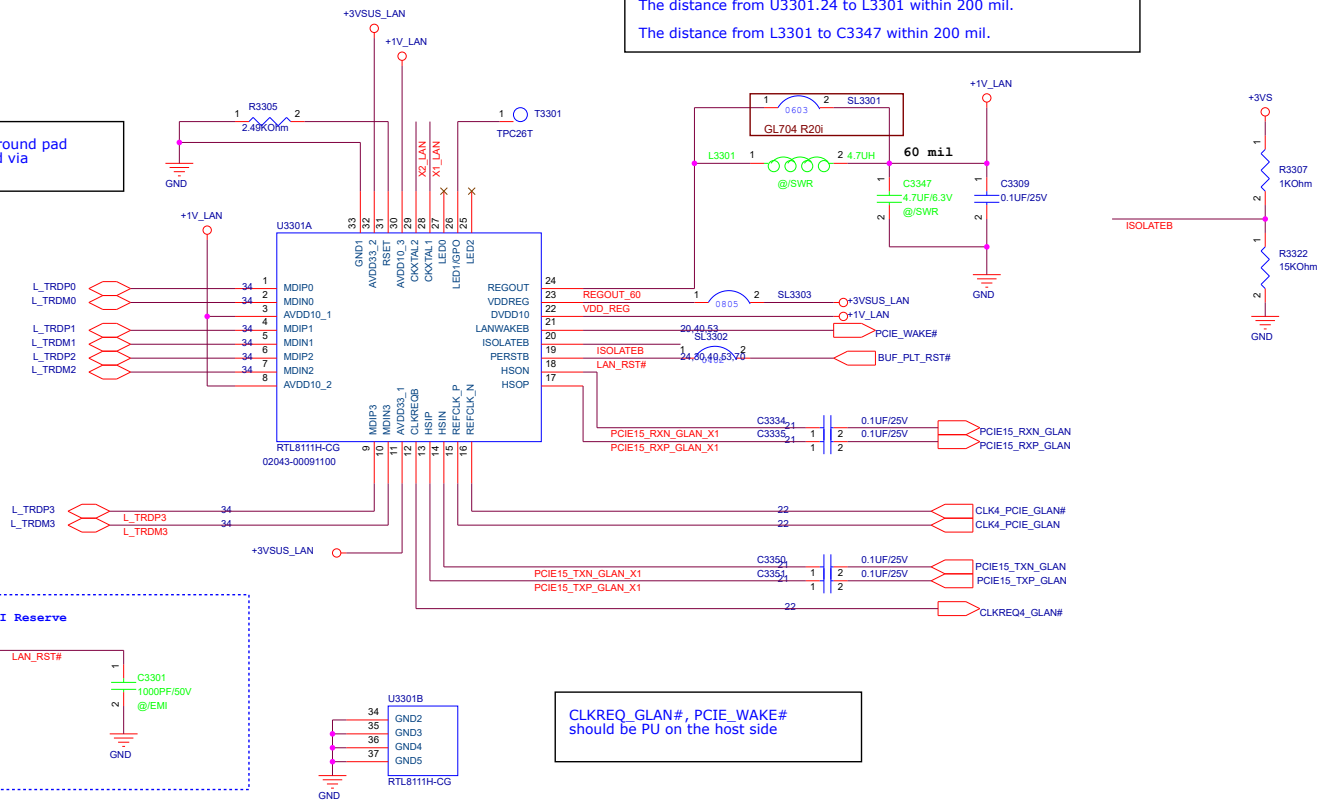


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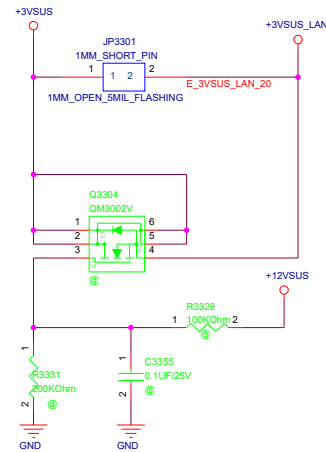
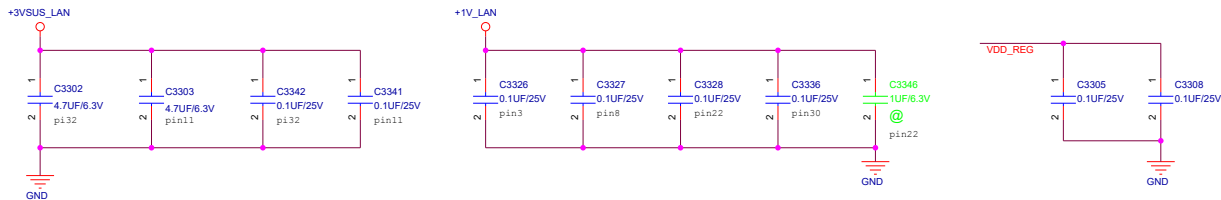
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Title : RST_Reset Circuit					
Size B		Dept.: ASUSTeK COMPUTER INC.		Engineer: Gaming RD4 EE1	
Date: Friday, July 27, 2018			Sheet 32 of 103		

33/34 pin ground pad
need ground via

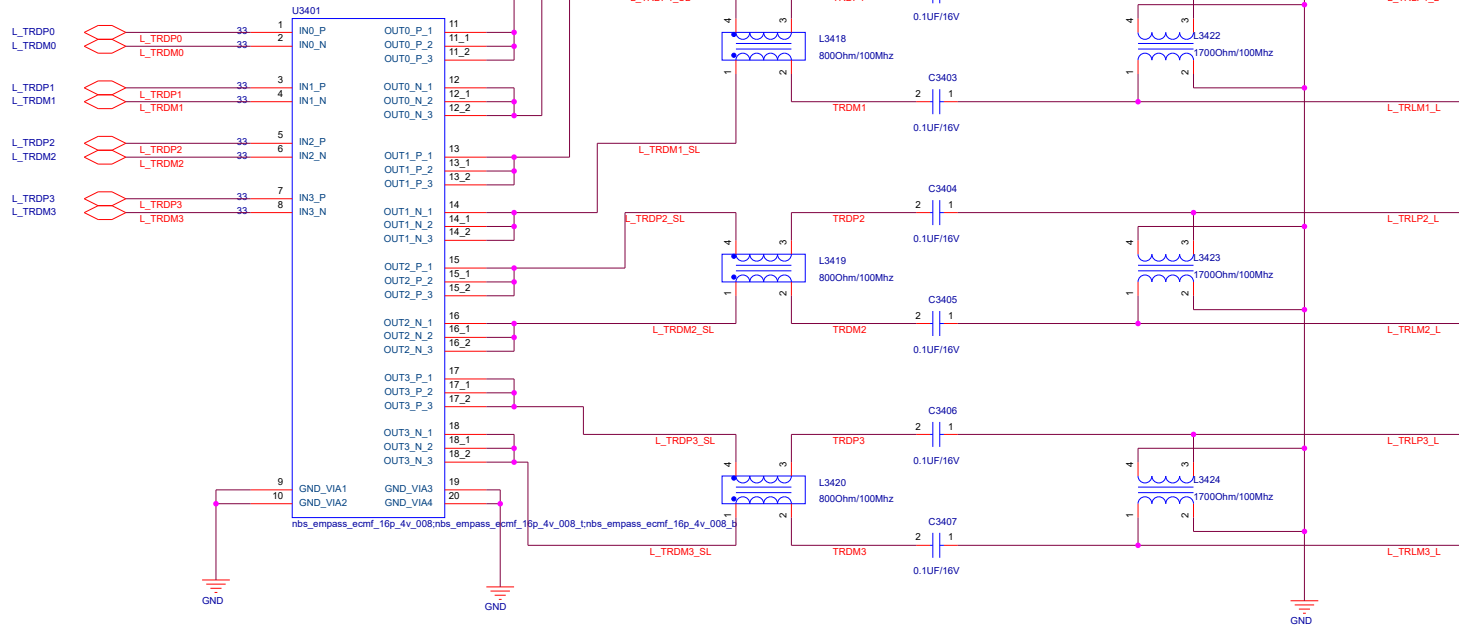
The distance from U3301.24 to L3301 within 200 mil.
The distance from L3301 to C3347 within 200 mil.



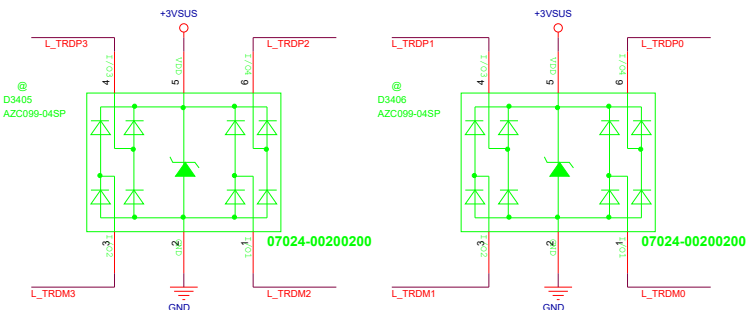
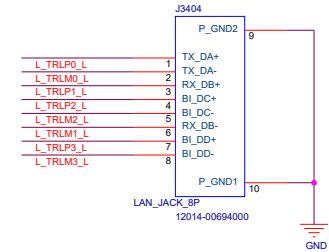
Realtek suggests 3V_LAN raise time >1ms



GL704 180111



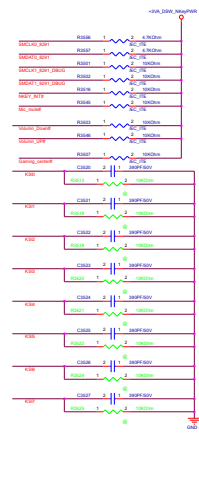
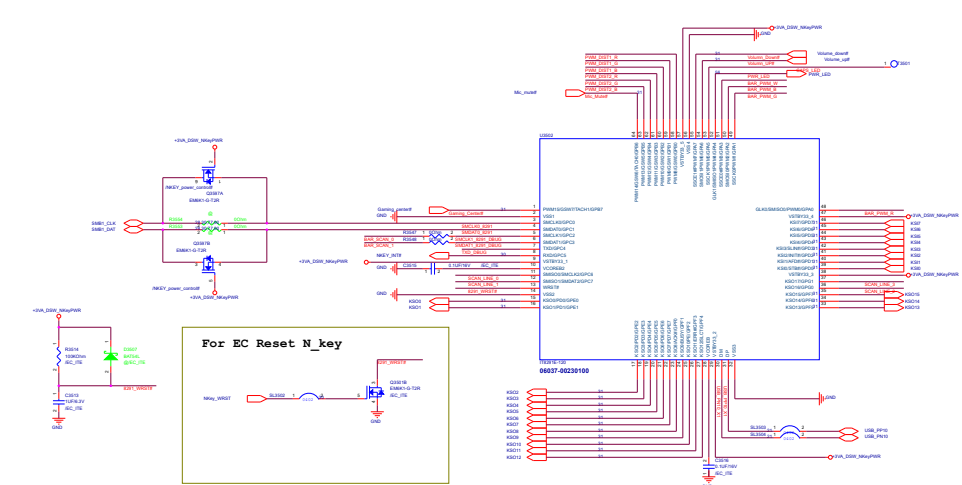
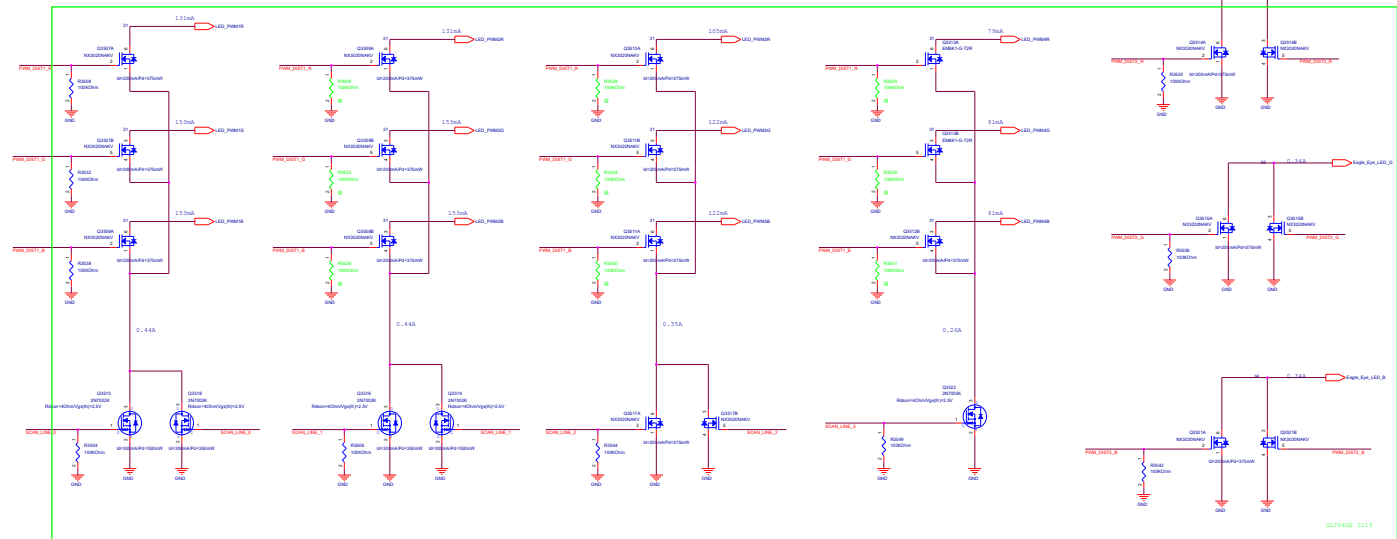
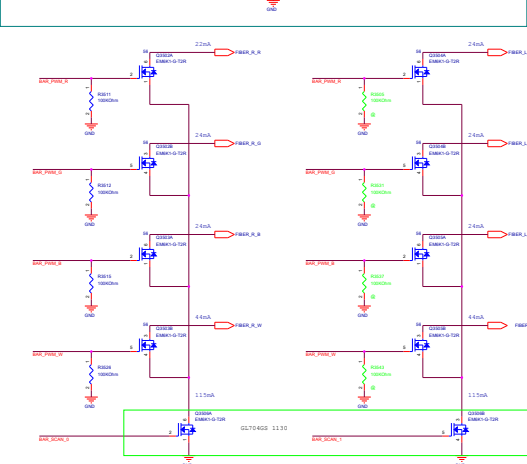
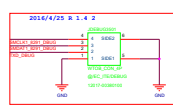
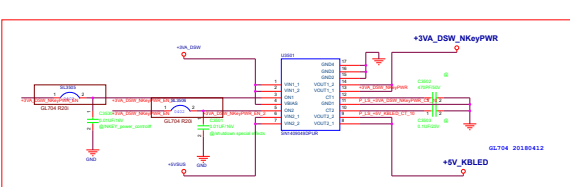
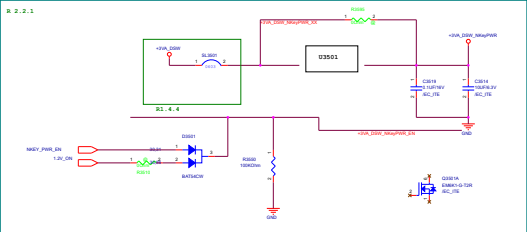
LAN Connector



D3401, D3402 ESD Diode

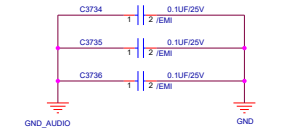
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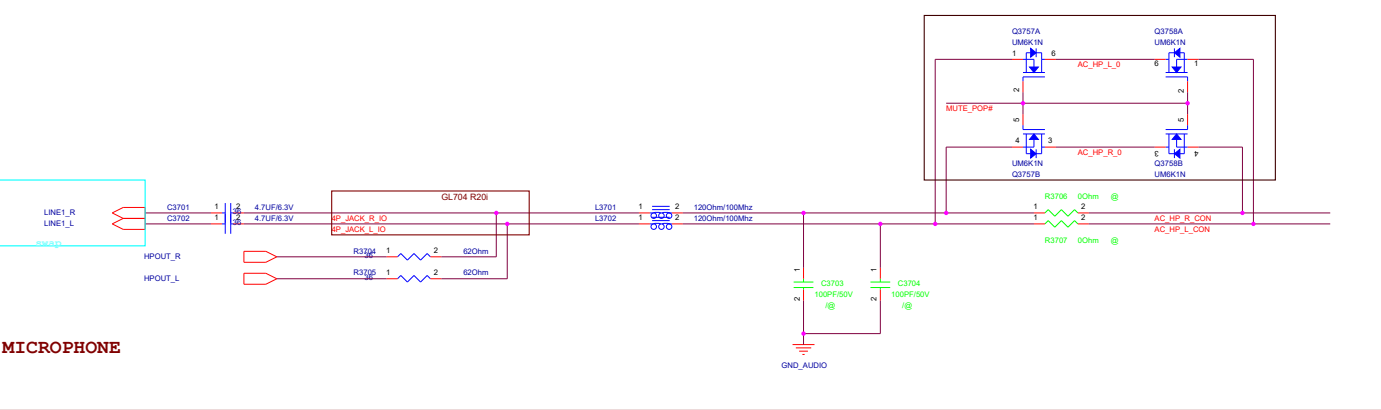


Headphone&MIC

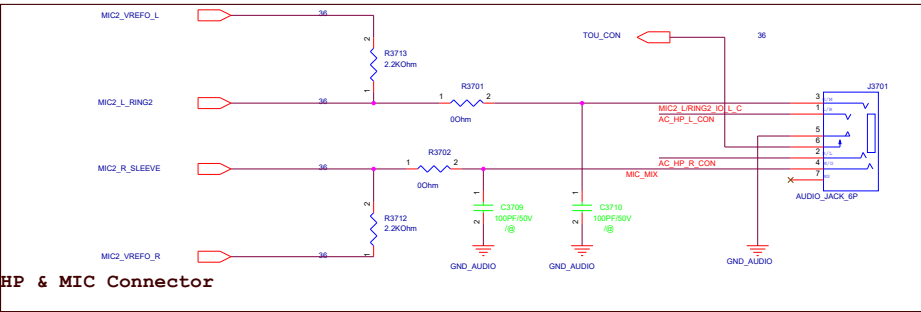
A_GND / GND



MICROPHONE

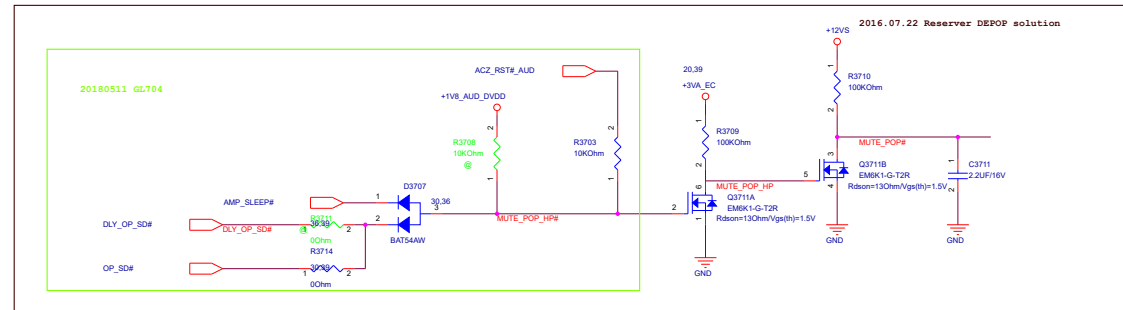
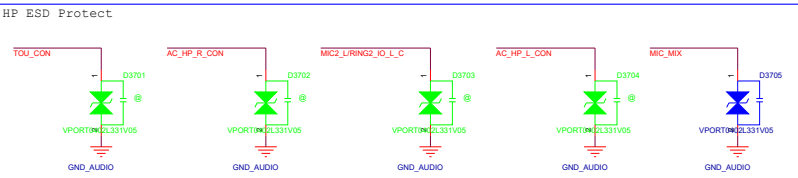



HP & MIC Connector



EXTERNAL MICROPHONE

Remove MIC Jack



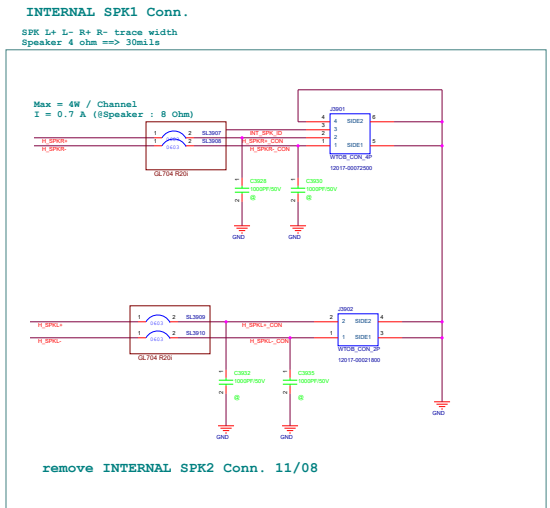
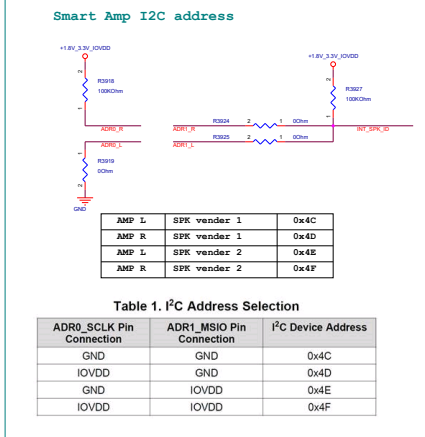
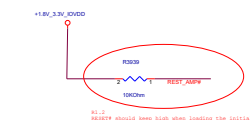
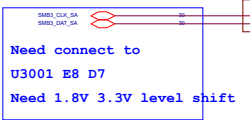
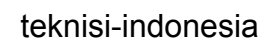
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Title : *****

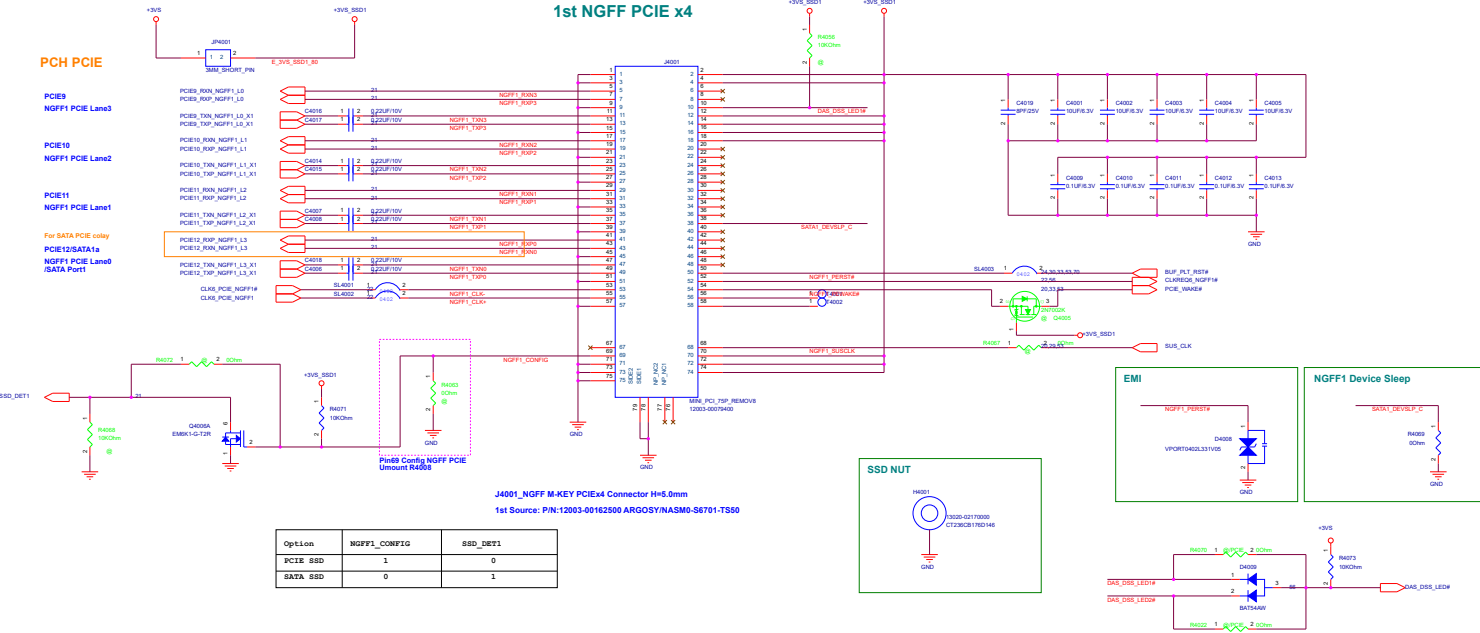
Size B	Dept.: ASUSTeK COMPUTER INC. Engineer: Gaming RD4 EE1
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Date: Friday, July 27, 2018	Sheet 38 of 103
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1116 pull high to +3VA_DSW

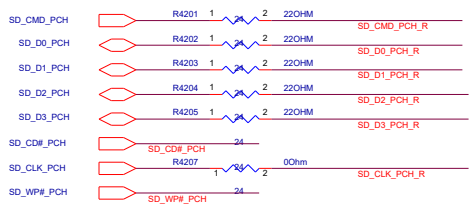


1st NGFF PCIE x4

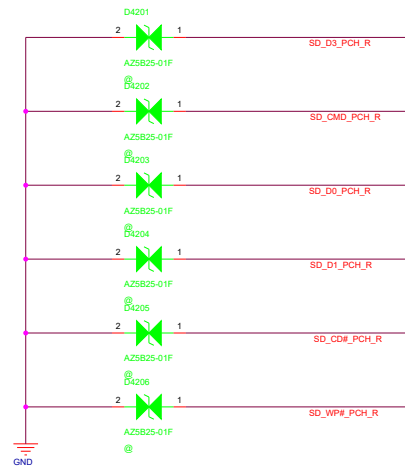
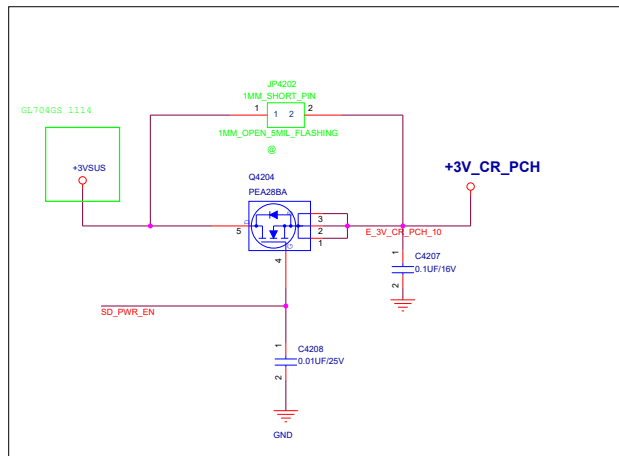
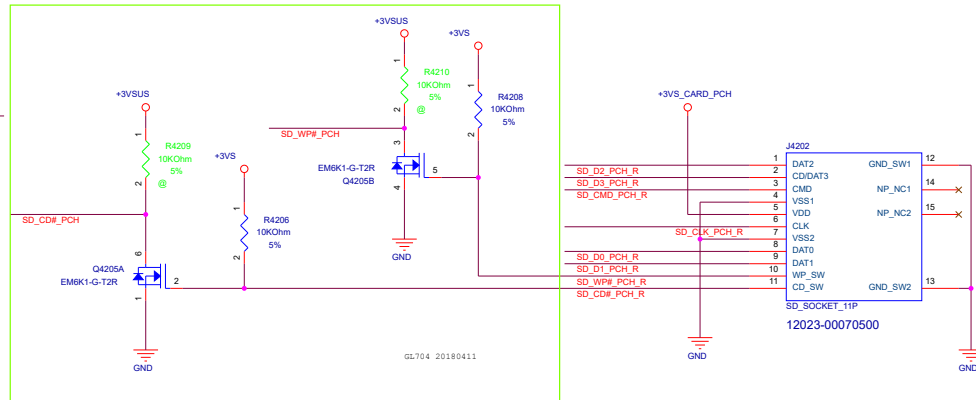
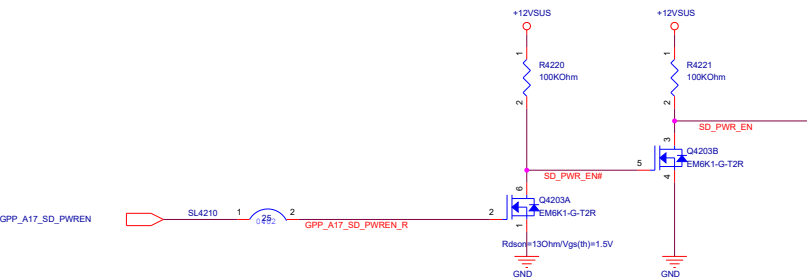
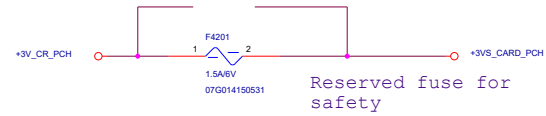



Option	NGFF1_CONFIG	SSD_DET1
PCIe SSD	1	0
SATA SSD	0	1

		Project Name		Rev	
		GL704GSM		R1.1	
Title : NGFF_SSD_SATA_CON					
Size B		Dept.: ASUSTeK COMPUTER INC. Engineer: Gaming RD4 EE1			
Date: Friday, July 27, 2018			Sheet 41 of 103		

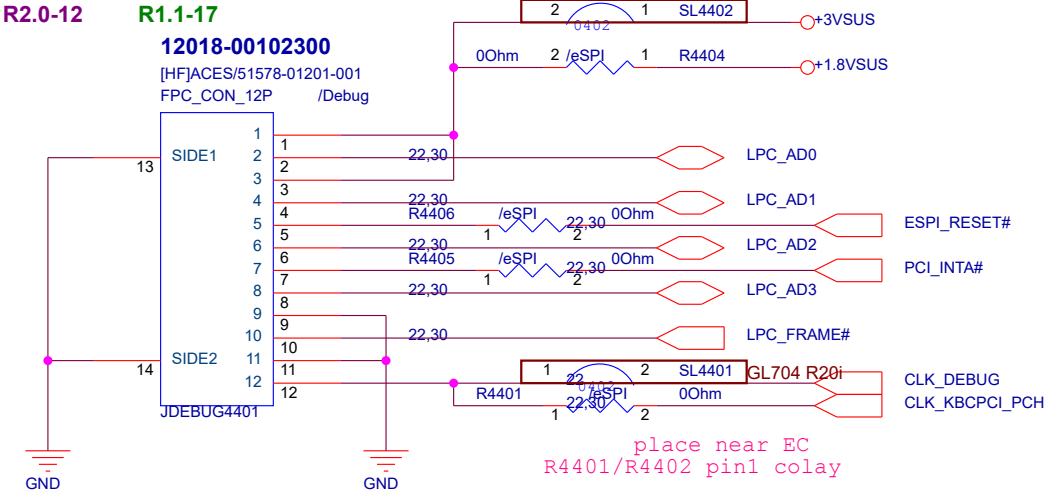


CR Socket



		Project Name	Rev
		GL704GSM	R1.1
Title : *****			
Size	Dept.: ASUSTeK COMPUTER INC. Engineer: Gaming RD4 EE1		
B			
Date: Friday, July 27, 2018		Sheet	43 of 103

LPC Debug Port

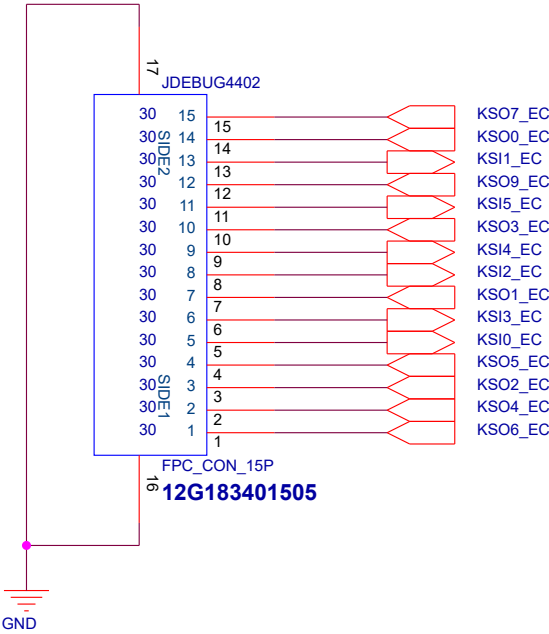


JDEBUG4401 Connector (MP USE)

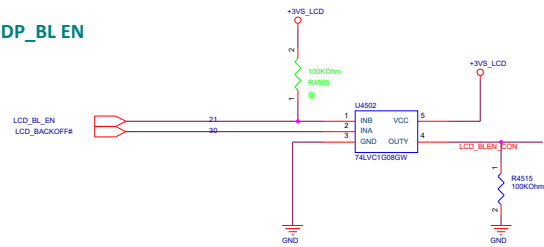
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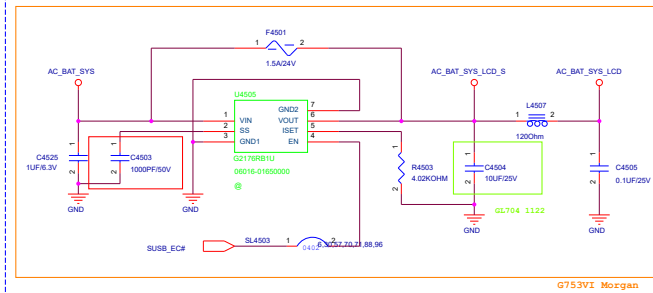
GL704 1128



eDP_BL EN

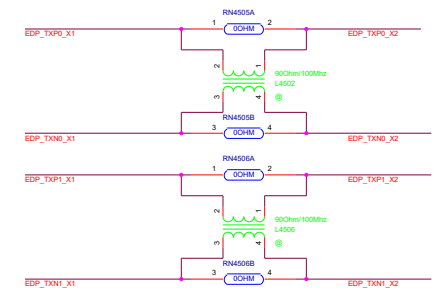


Panel BL Power

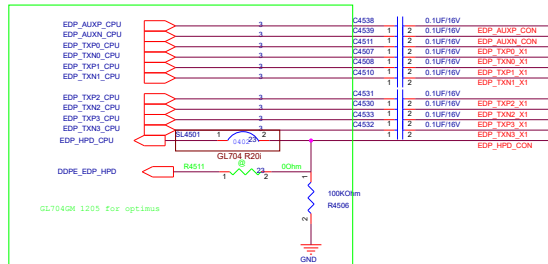


G753VI Morgan

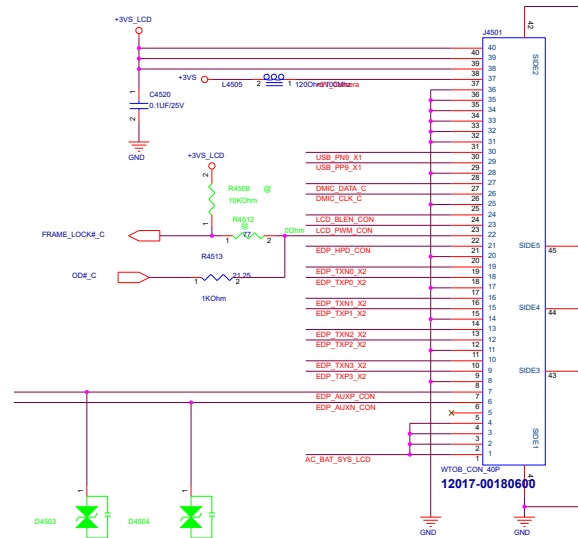
For EMI



eDP circuit

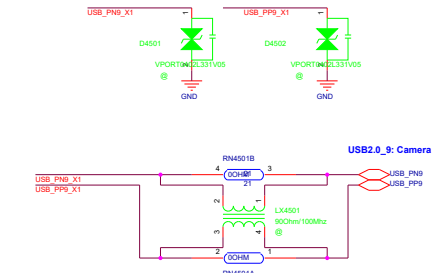


eDP Panel Conn.



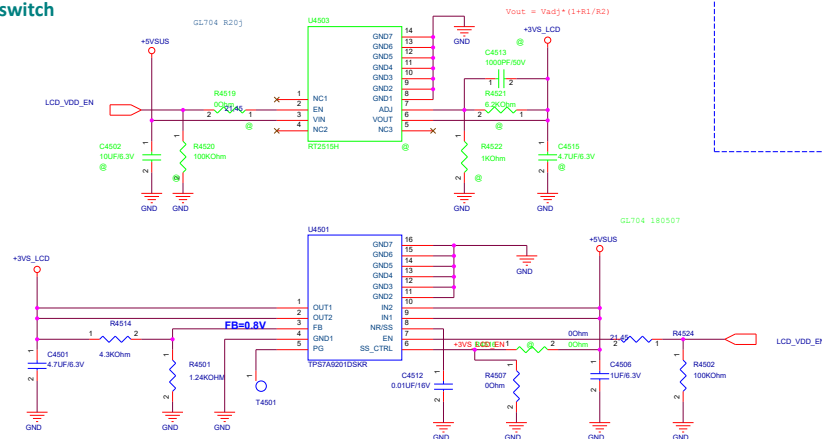
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 P/N:12017-00180600 STARCONN*11H48-100000-G4-R
 P/N:12017-00180900 ARGOSYLVDFH-04005-TP00*

Camera & D-MIC

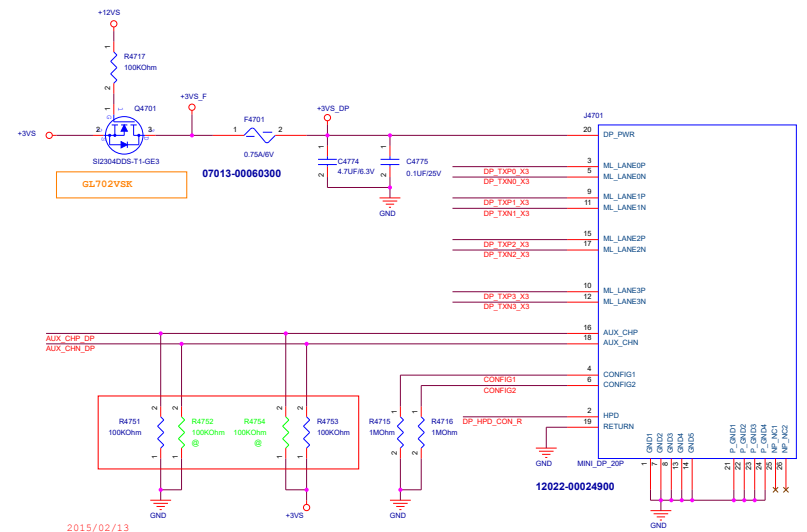
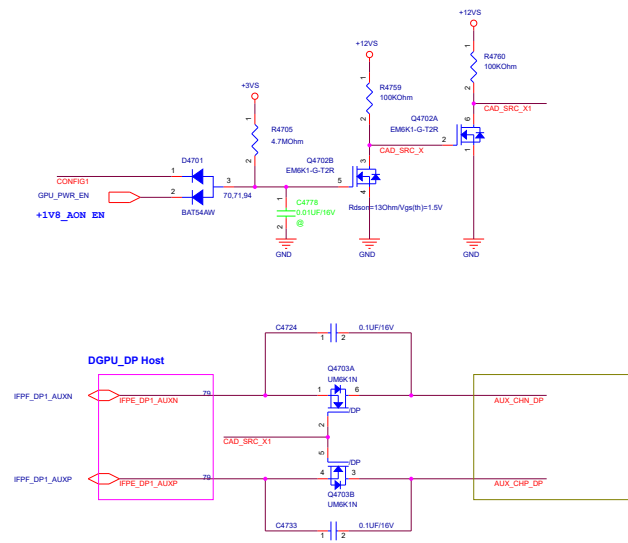
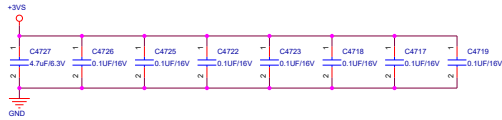
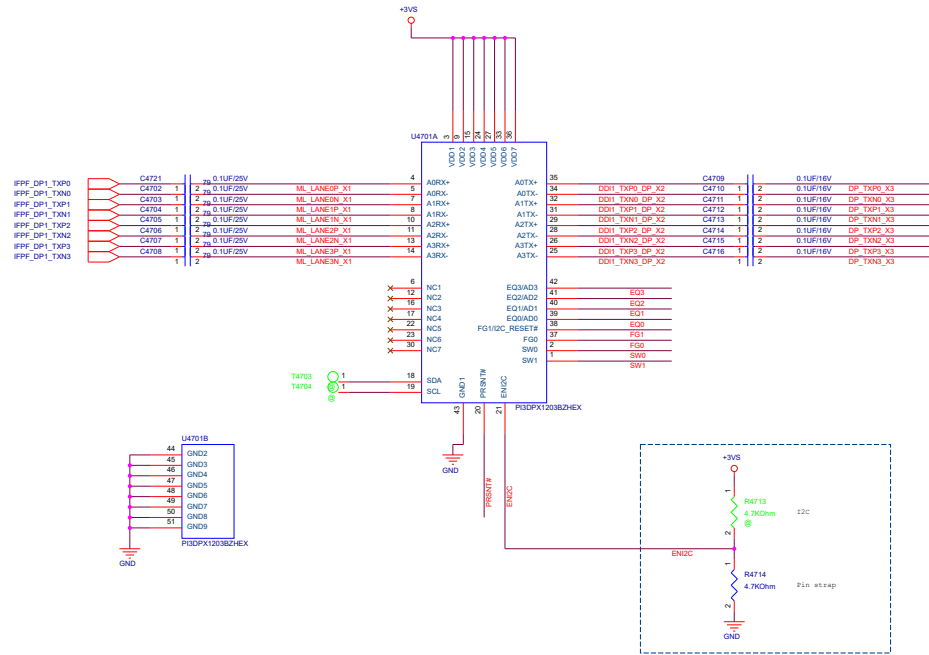


USB2.0_9: Camera

LCD Power switch

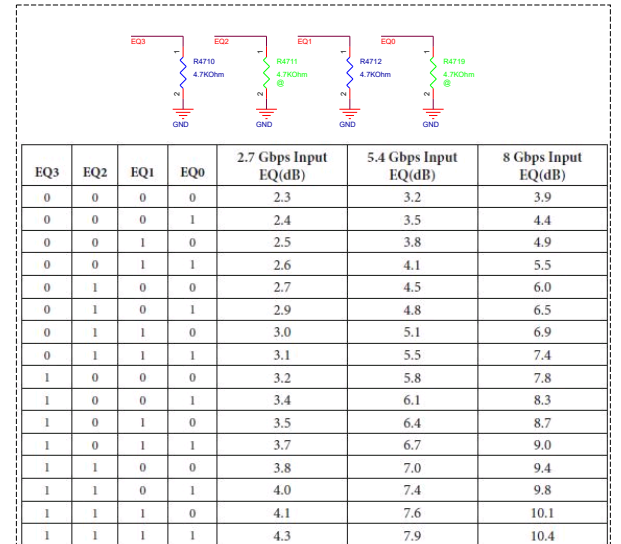
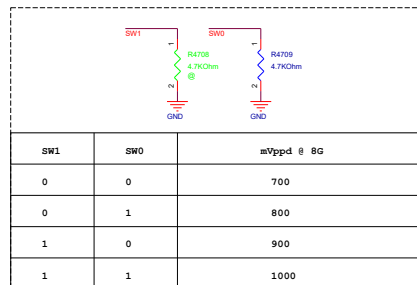
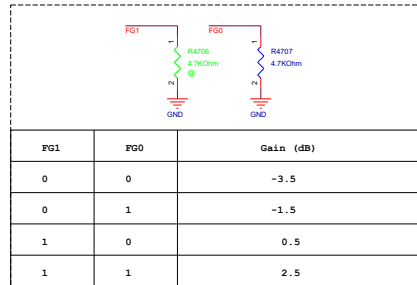
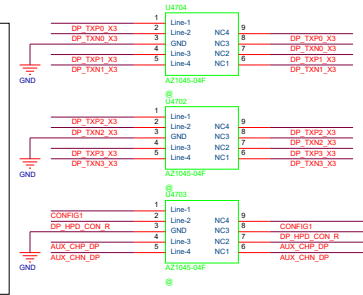
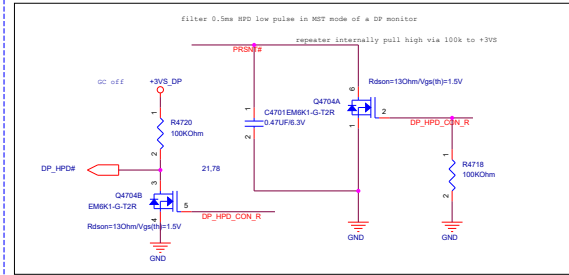


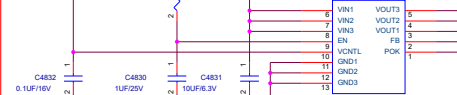
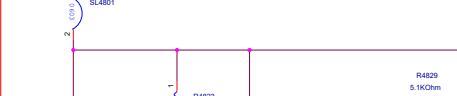
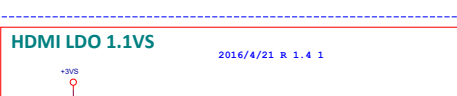
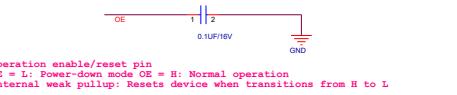
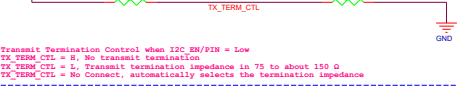
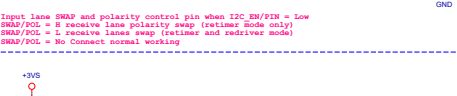
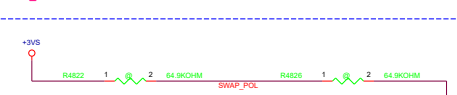
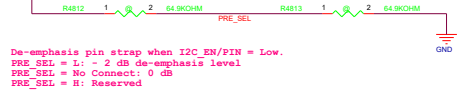
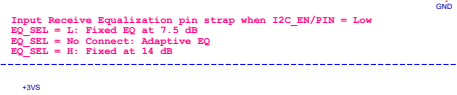
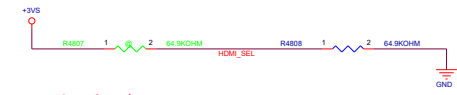
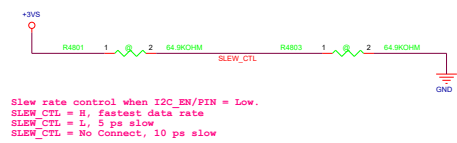
DP Repeater_PI3DPX1203B



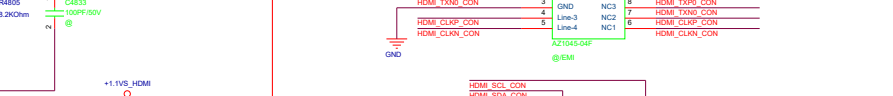
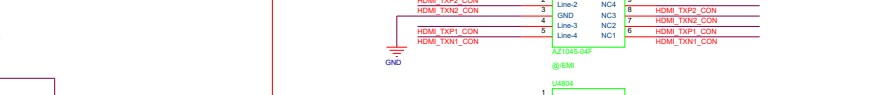
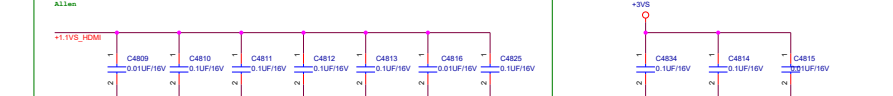
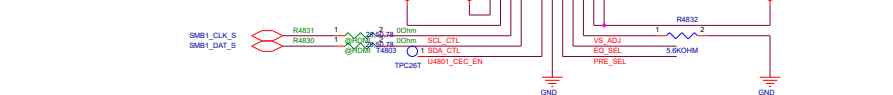
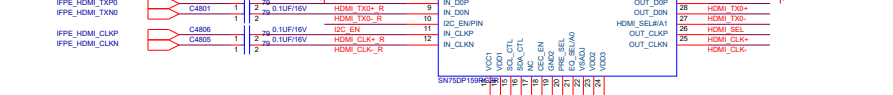
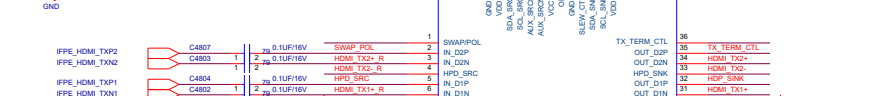
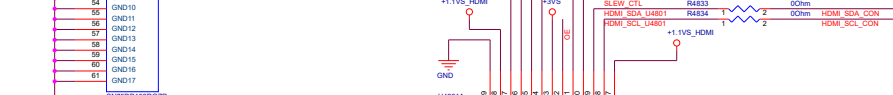
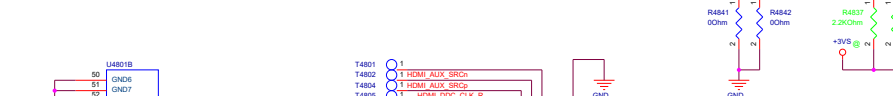
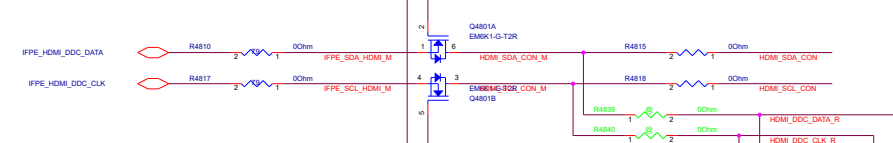
2015/02/13
使用PS8330可不上件。
若不使用需參考Intel/nVidia文件建議

www.teknisi-indonesia.com

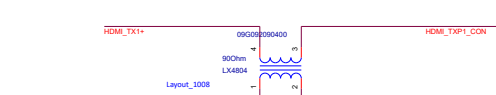
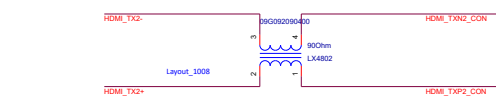
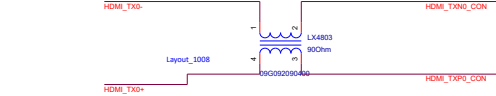
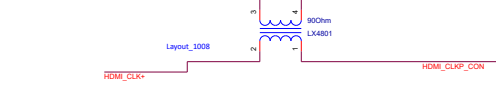
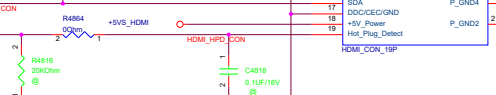
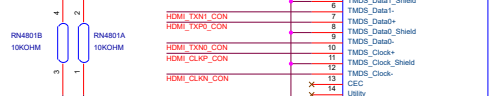
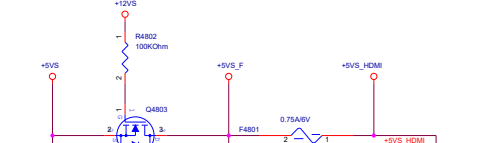




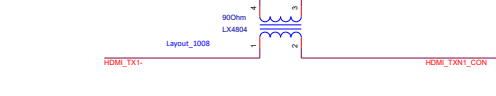
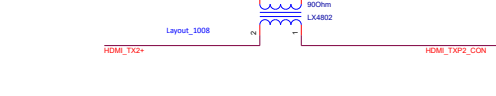
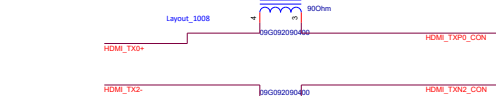
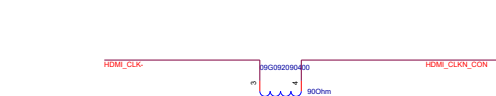
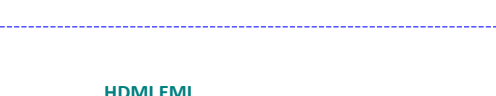
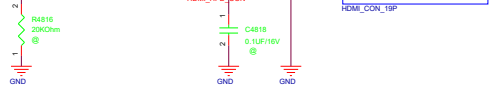
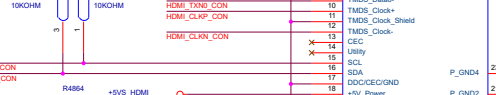
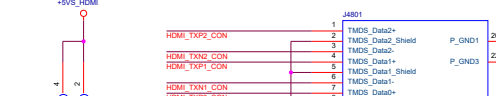
HDMI Active-Level Shift




HDMI PWR_+5V5_HDMI



HDMI Conn.



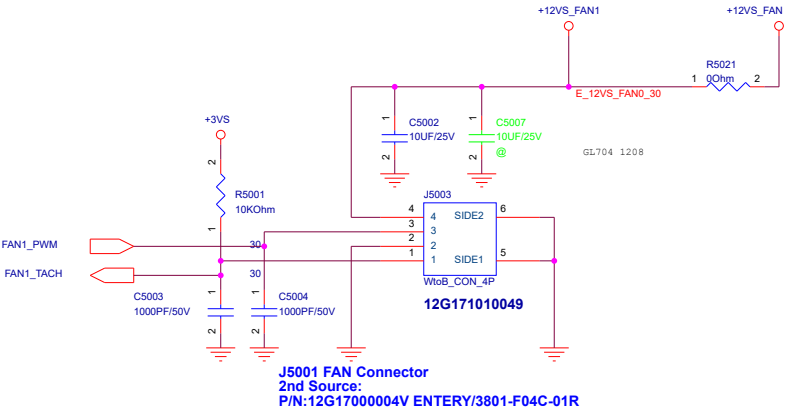
	Project Name GL704GSM	Rev R1.1
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Title : *****

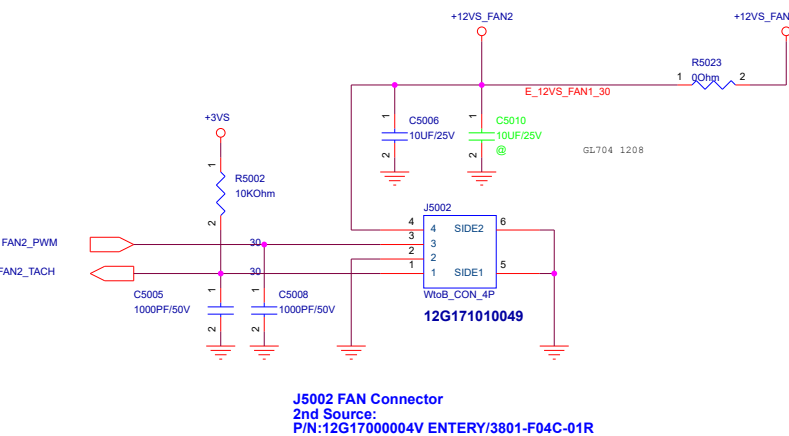
Size B	Dept.: ASUSTeK COMPUTER INC. Engineer: Gaming RD4 EE1
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Date: Friday, July 27, 2018	Sheet 49 of 103
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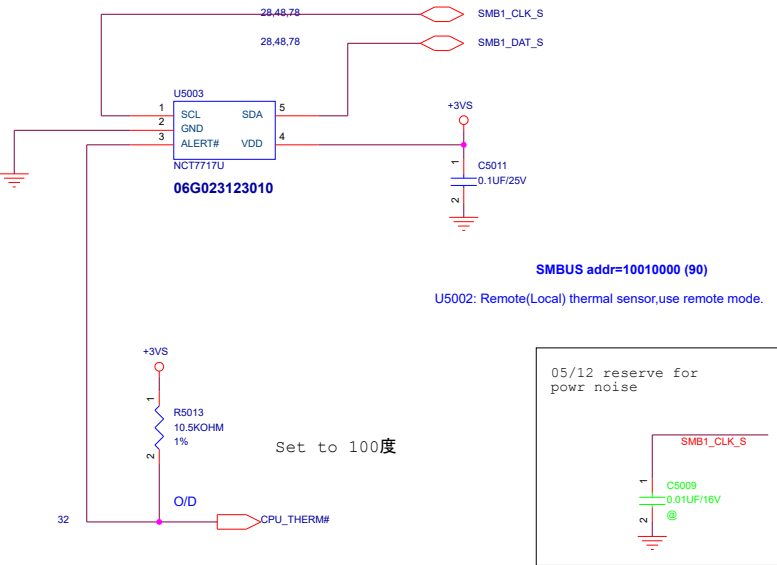
PWM CPU Fan

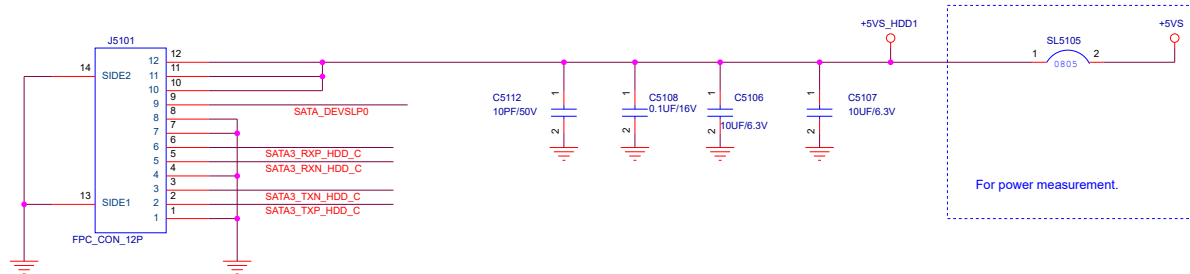
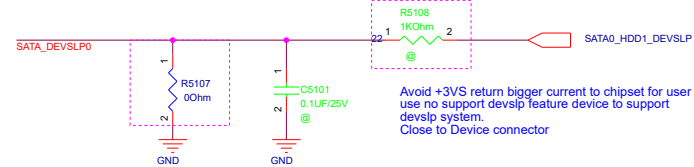
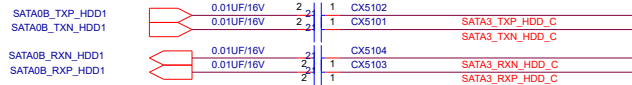


PWM VGA Fan

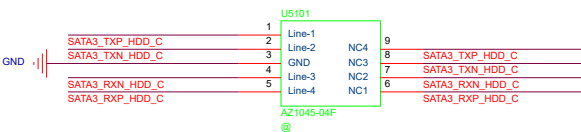


CPU Thermal Sensor





EMI Request

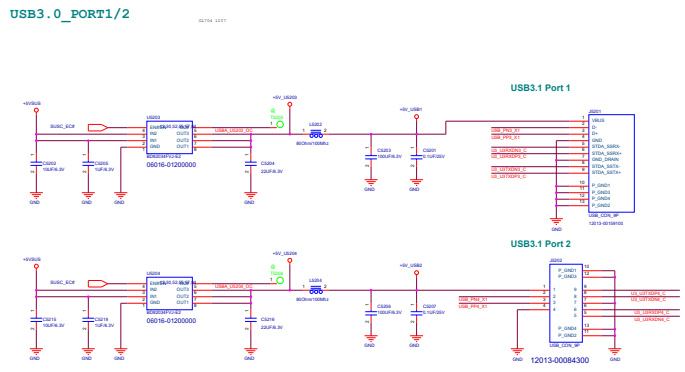
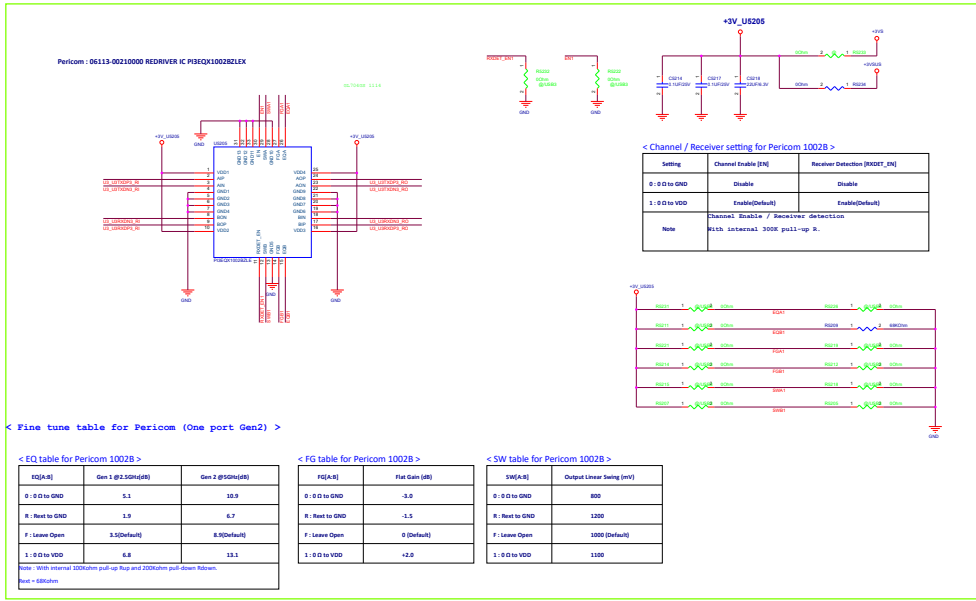
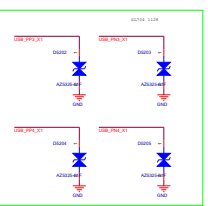
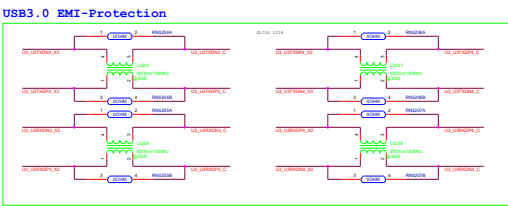
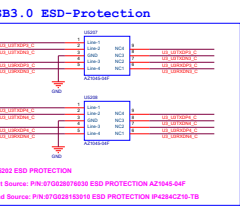
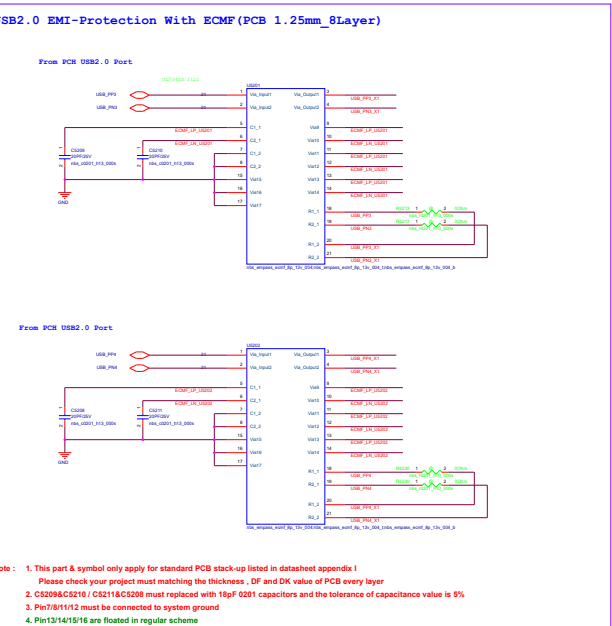
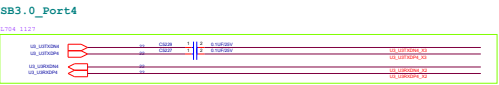
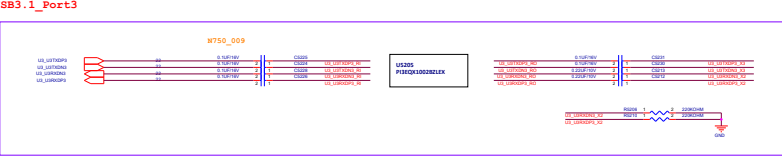


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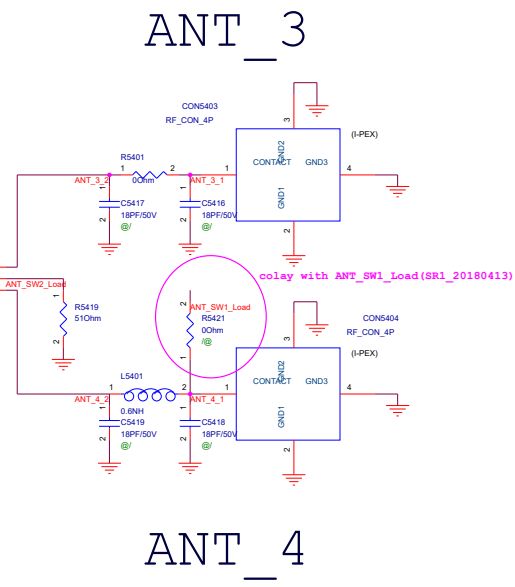
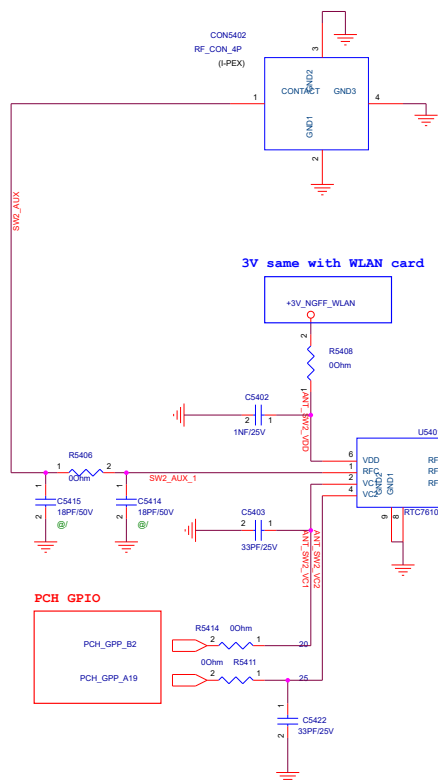
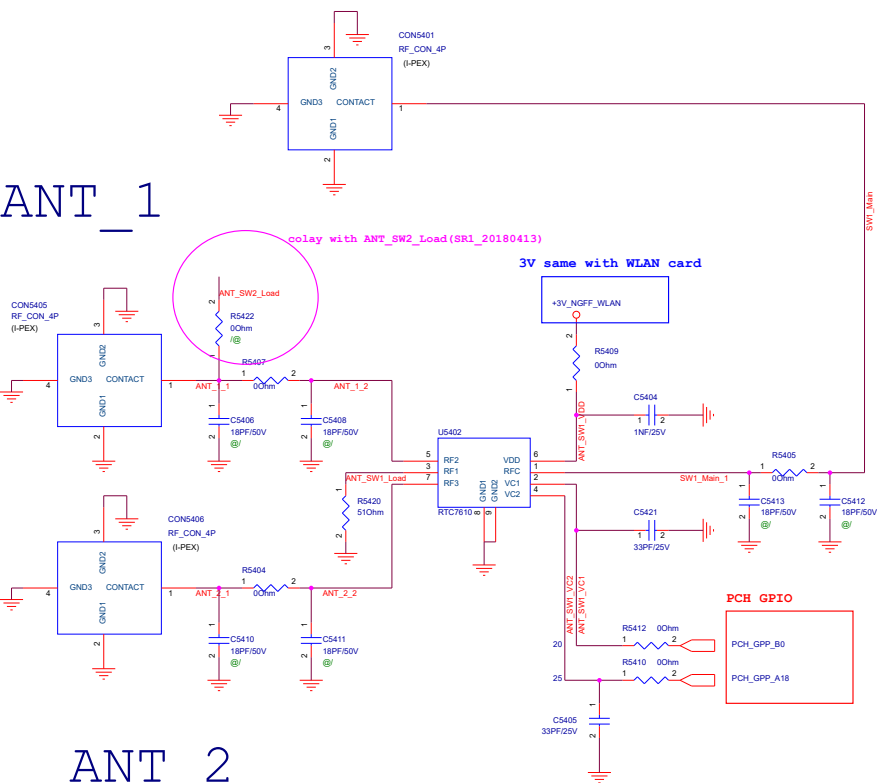
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<Core Design>

Project Name		Rev
ASUS GL704GSM		R1.1
Title : HDD		
Size	Dept.:	Engineer:
B	ASUSTek COMPUTER INC.	Gaming RD4 EE1
Date: Friday, July 27, 2018	Sheet	51 of 103



Module AUX



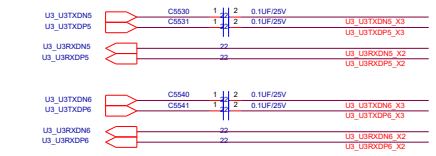
U5402 RTC7610			
ANT	Port	vc1 GPP_B0	vc2 GPP_A18
50 Q	RF1	1	0
ANT_1	RF2	X	1
ANT_2	RF3	0	0

X:	don't care
0:	-0.2v~0.3v
1:	1.6v~3.6v

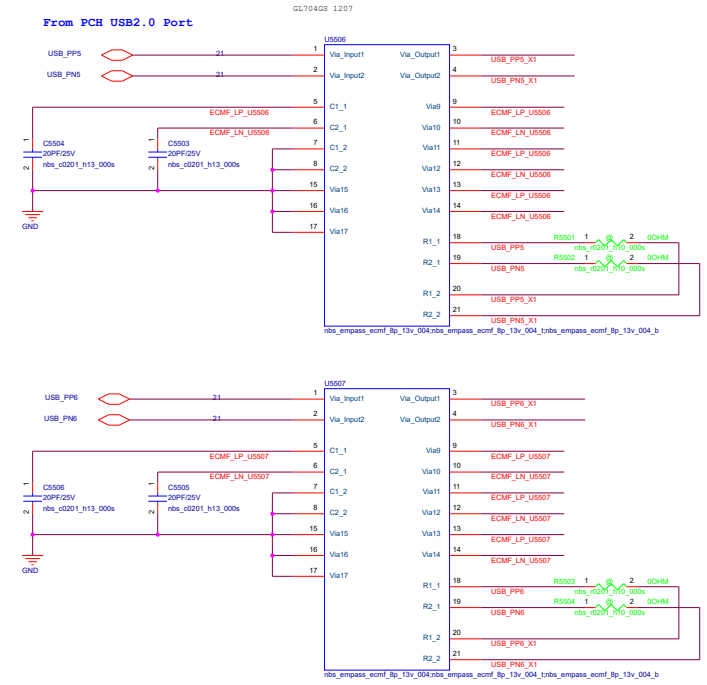
U5401 RTC7610			
ANT	Port	VC1 GFP_B2	VC2 GFP_A19
50 Ω	RF1	1	0
ANT_3	RF2	X	1
ANT_4	RF3	0	0

X:	don't care
0:	-0.2v~0.3v
1:	1.6v~3.6v

USB3.0_Port5 & USB3.0_Port6

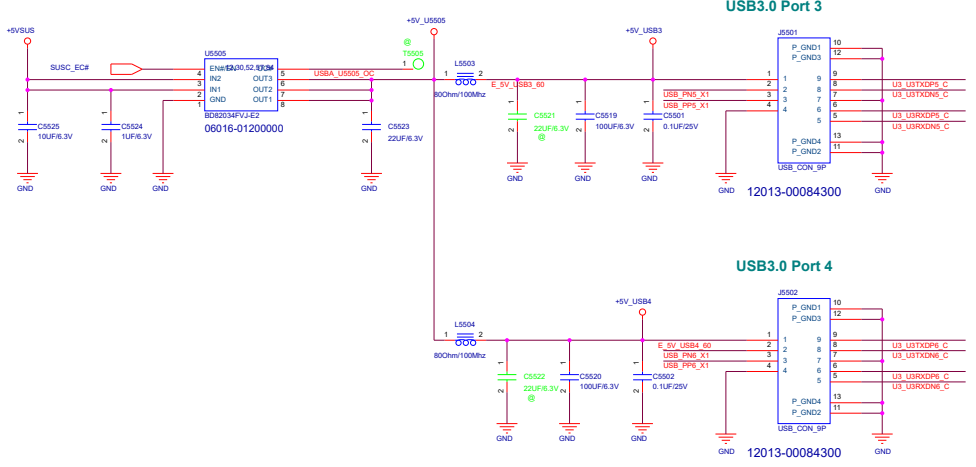
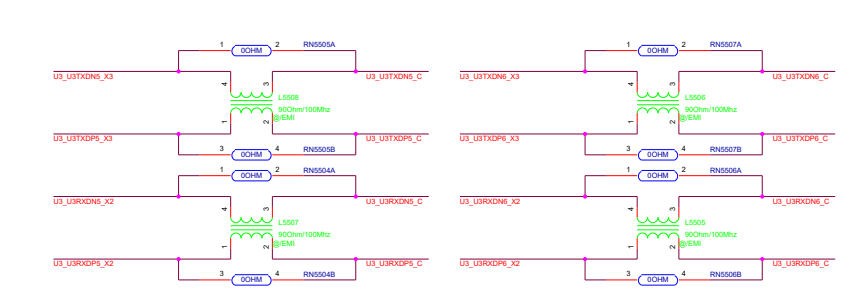


USB2.0 EMI-Protection With ECMF (PCB 1.25mm_8Layer)

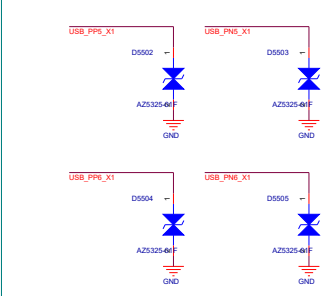


Note : 1. This part & symbol only apply for standard PCB stack-up listed in datasheet appendix I
Please check your project must matching the thickness , DF and DK value of PCB every layer
2. C5504&C5503 / C5505&C5506 must replaced with 18pF 0201 capacitors and the tolerance of capacitance value is 5%
3. Pin7 & Pin8 & Pin11 & Pin12 must be connected to system ground
4. Pin13,14,15,16 are floated in regular scheme

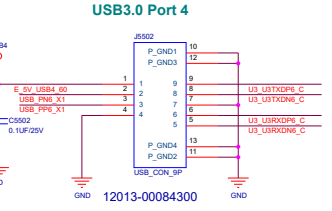
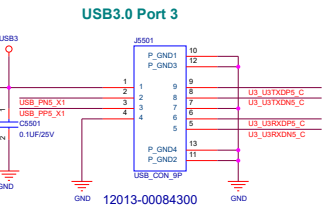
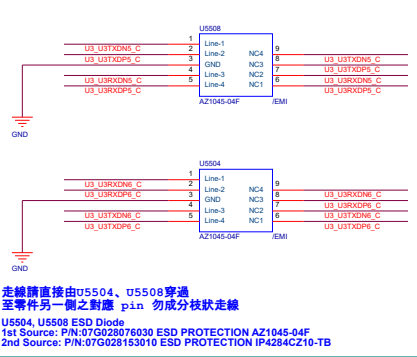
USB3.0 EMI-Protection



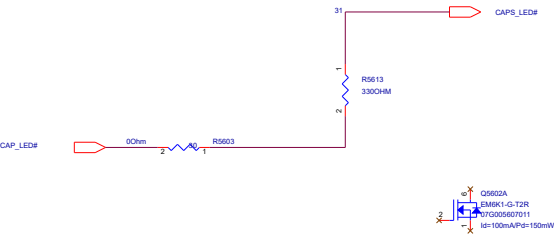
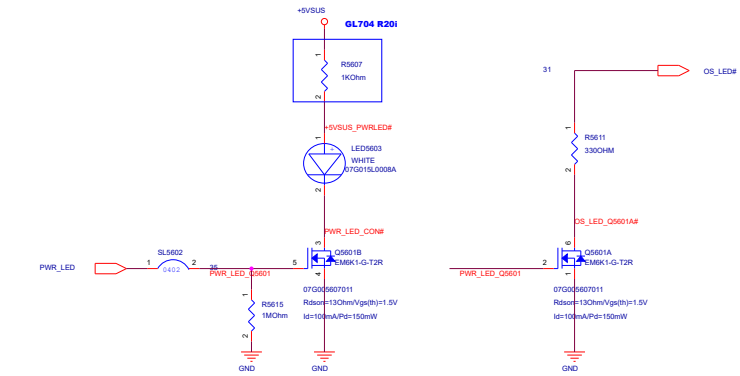
USB2.0 ESD-Protection



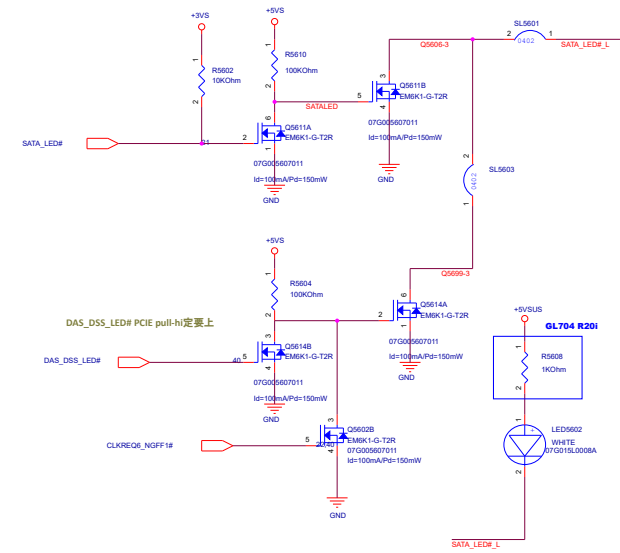
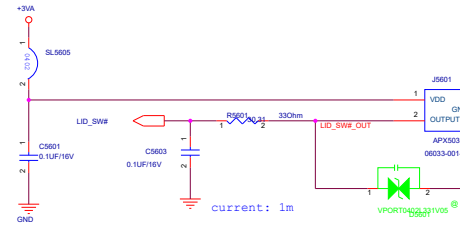
USB3.0 ESD-Protection



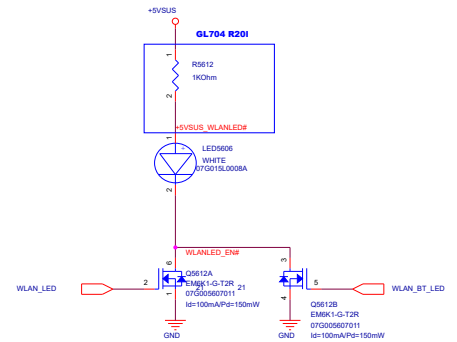
PWR LED



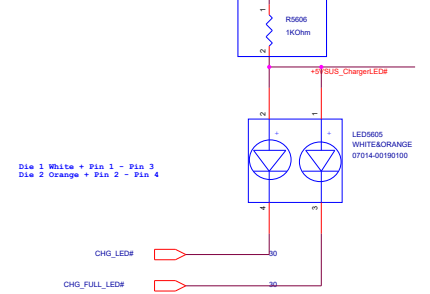
HDD LED & PCIE SSD LED

HALL SENSOR
06033-00140000

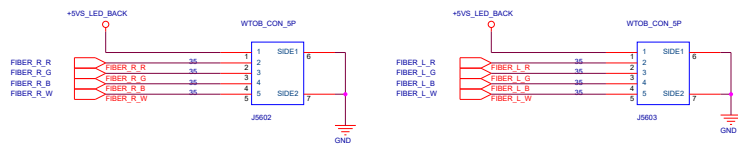
BT/WLAN LED



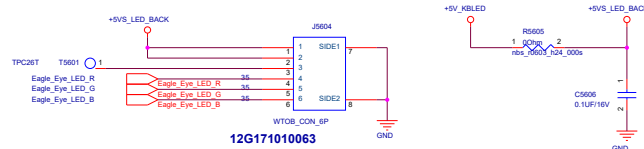
Charger LED



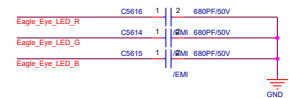
For FIBER LED CTRL

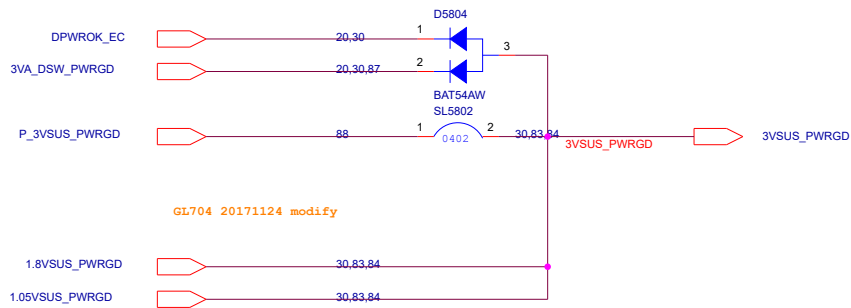


For Eagle Eye LED CTRL

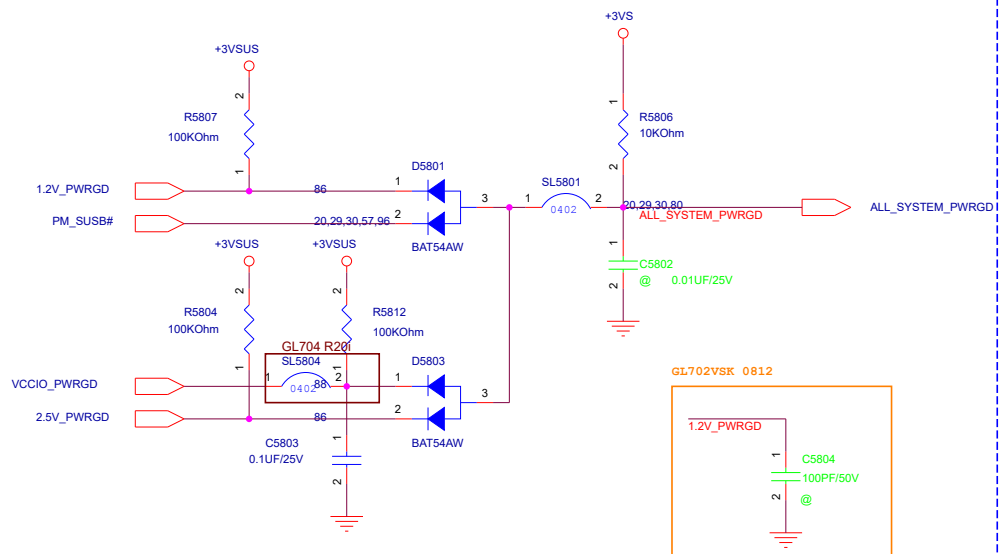
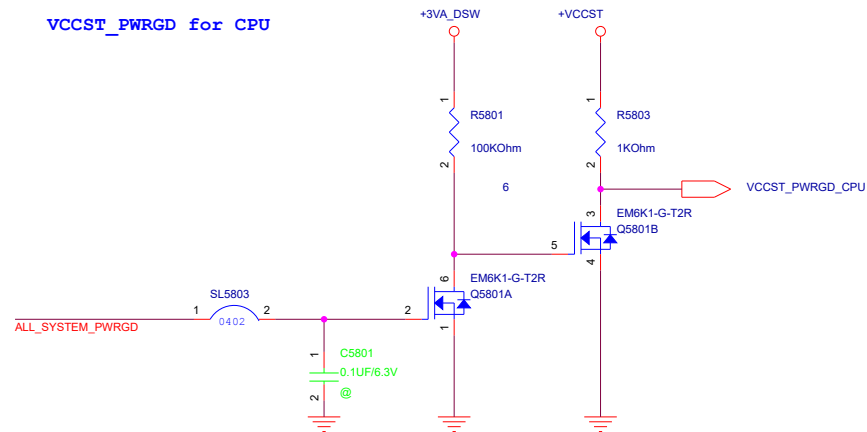


For EMI

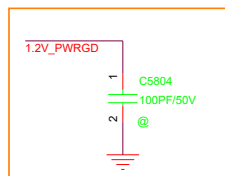




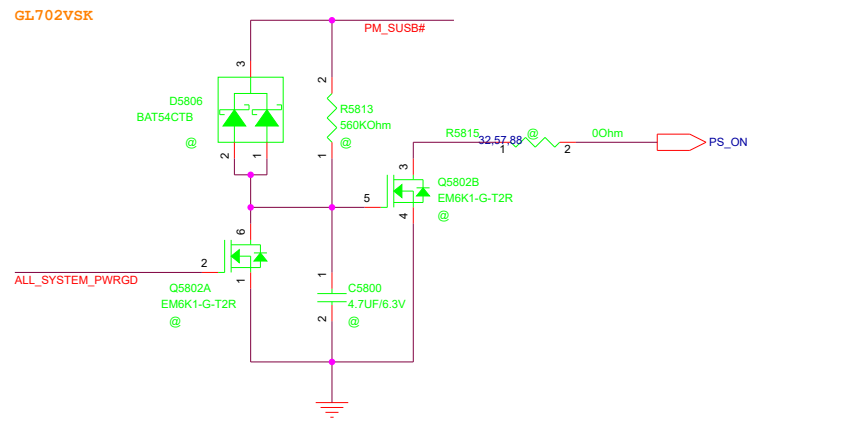
VCCST_PWRGD for CPU

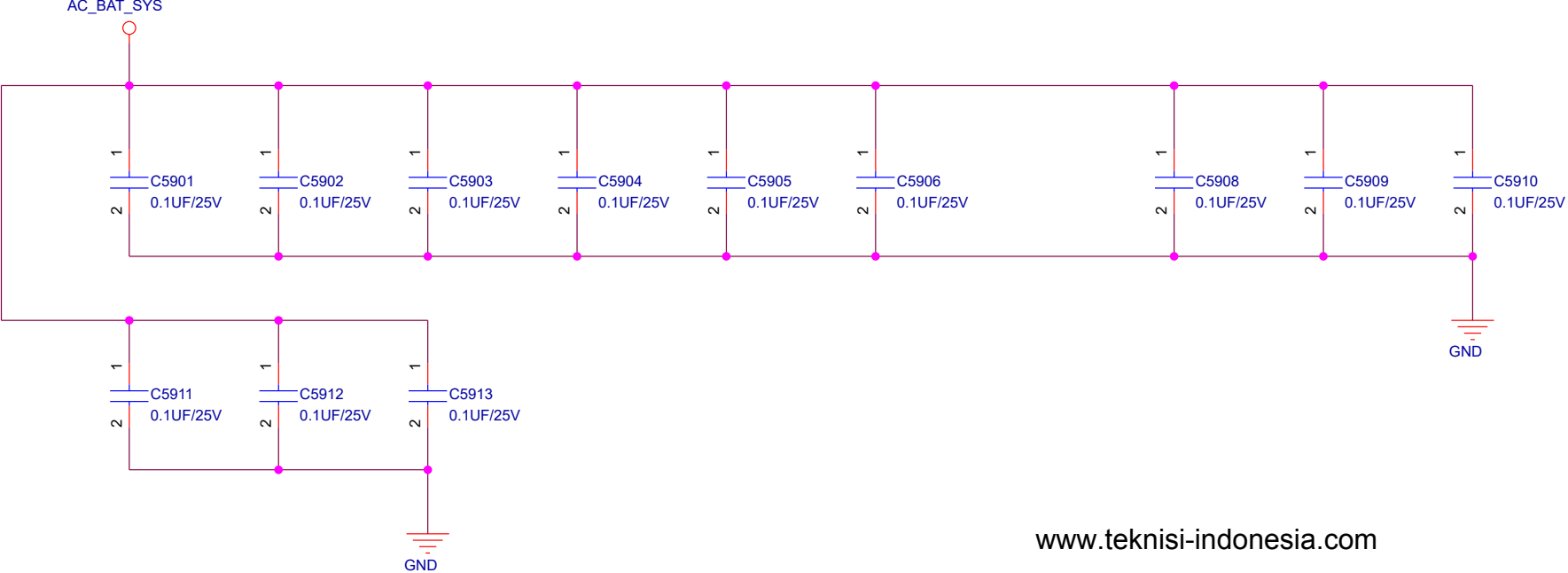


GL702VSK 0812

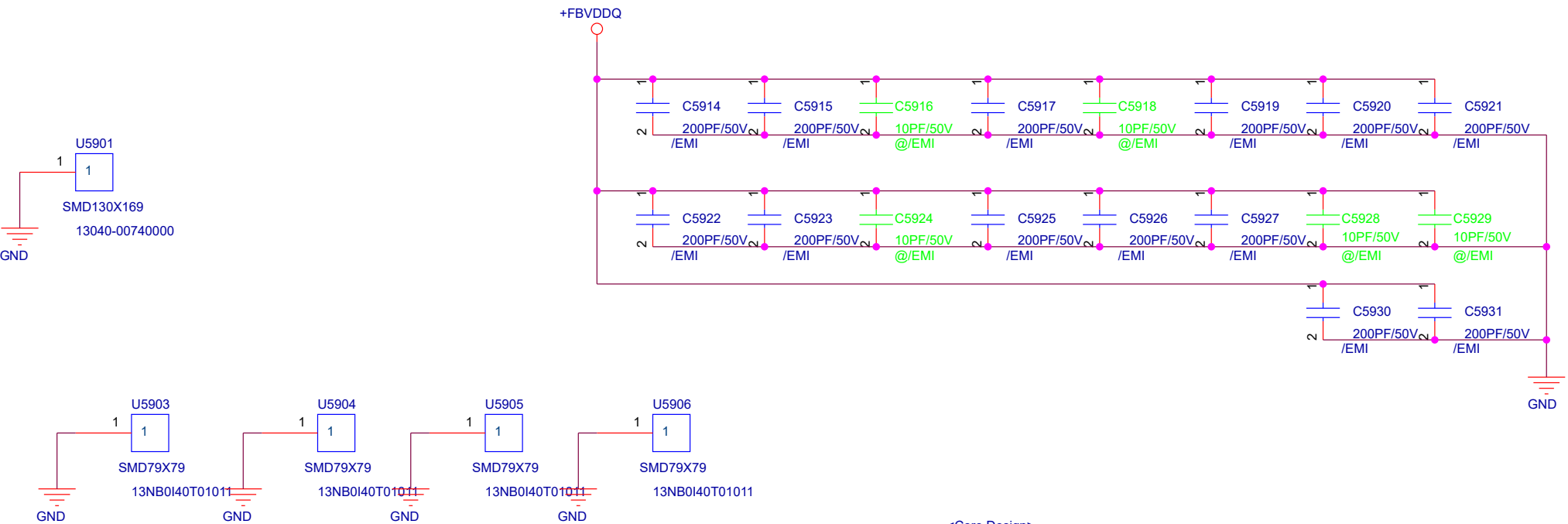


GL702VSK






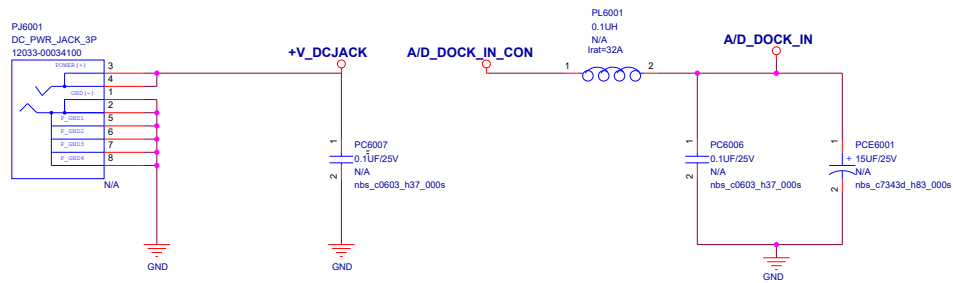
www.teknisi-indonesia.com



<Core Design>

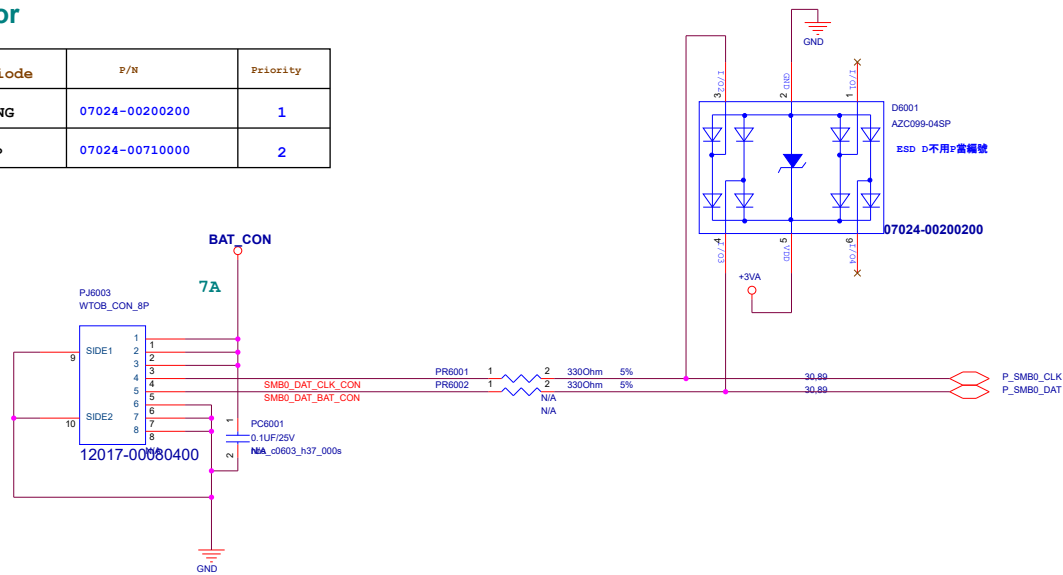
		Project Name	Rev
		GL704GSM	R1.1
Title : EMI			
Size A	Dept.: ASUSTeK COMPUTER INC. Engineer:		
Date: Friday, July 27, 2018	Sheet 59		of 103

DC-IN Connector

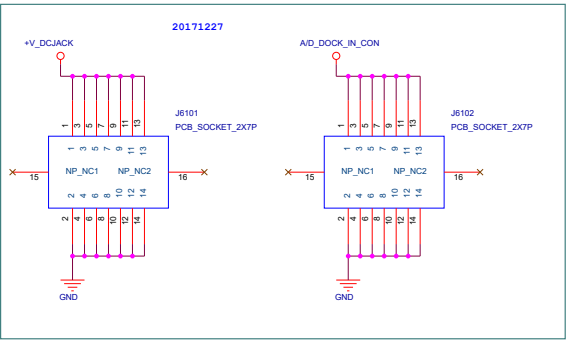


Battery Connector

ESD Diode	P/N	Priority
AMAZING	07024-00200200	1
NXP	07024-00710000	2



Note: Battery Connector 正確性與BAT1_IN_OC#是否預留!





Project Name

GL704GSM

Rev

R1.1

Title : *****

Size

B

Dept.: ASUSTeK COMPUTER INC. **Engineer:** **Gaming RD4 EE1**


Date: Friday, July 27, 2018

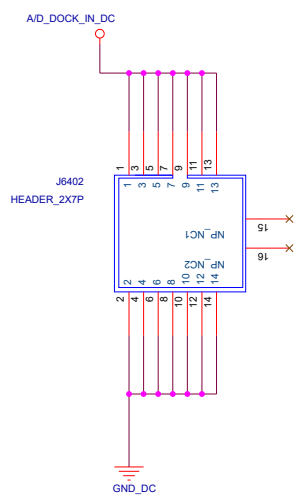
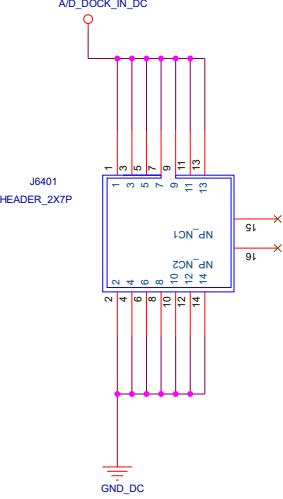
Sheet

62

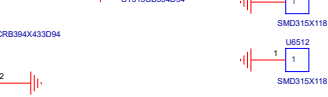
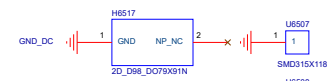
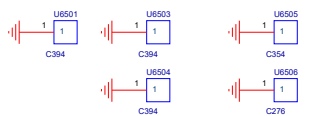
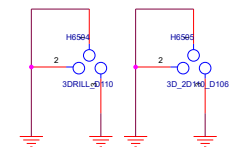
of

103

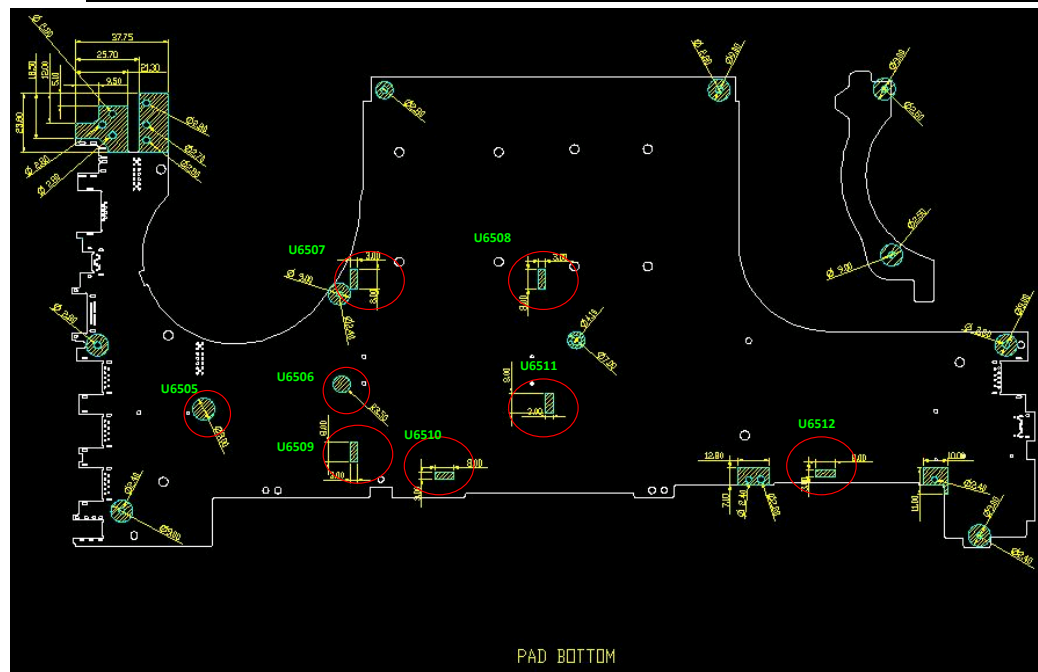
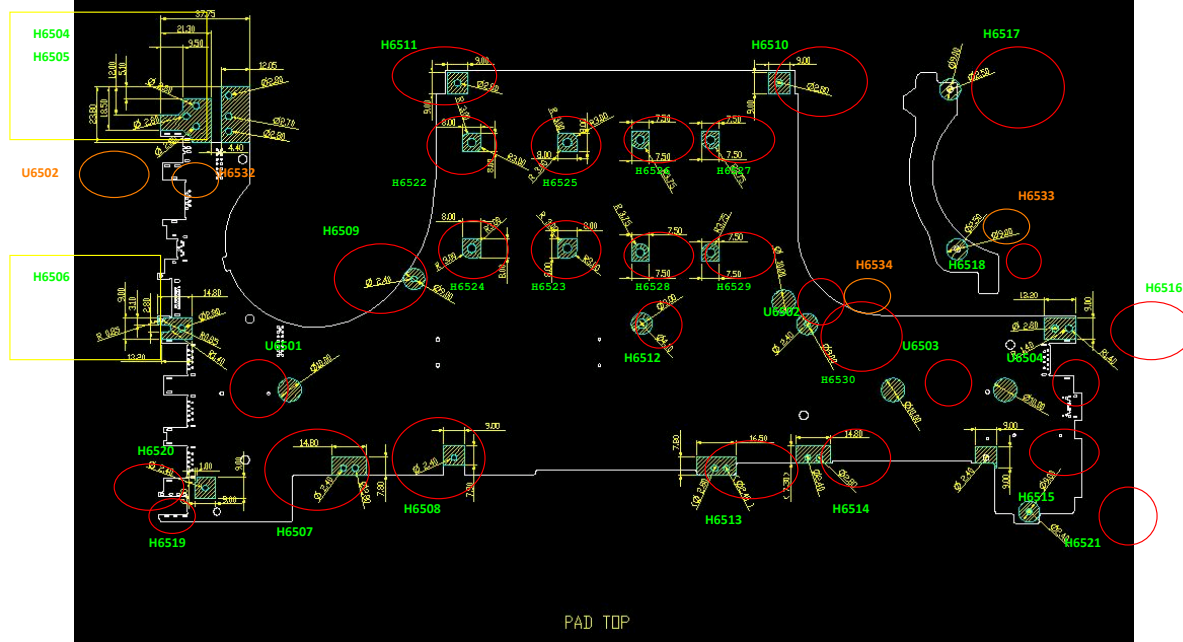
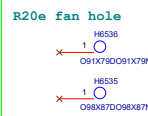
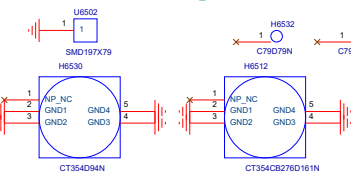
		Project Name	Rev
		GL704GSM	R1.1
Title : Power Button_IO_BD			
Size	Dept.: ASUSTek COMPUTER INC Engineer: Gaming RD4 EE1		
B			
Date:	Friday, July 27, 2018	Sheet	63 of 103



SKEW HOLE & PAD



20180416 SR2 update

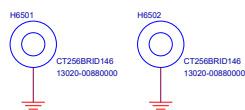


CPU bracket



GPU bracket

FAN NUT



PCH NUT



Project Name

GL704GSM

Rev

R1.1

Title : *****

teknisi-indonesia

Size

B

Dept.: ASUSTeK COMPUTER INC. **Engineer:** **Gaming RD4 EE1**

Date: Friday, July 27, 2018

Sheet 66 of 103



Project Name

GL704GSM

Rev

R1.1

Title : *****

Size

B

Dept.: ASUSTeK COMPUTER INC. **Engineer:** **Gaming RD4 EE1**

Date: Friday, July 27, 2018

Sheet

67

of

103



Project Name

GL704GSM

Rev

R1.1

Title : *****

Size

B

Dept.: ASUSTeK COMPUTER INC. **Engineer:** **Gaming RD4 EE1**

Date: Friday, July 27, 2018

Sheet

68

of

103



Project Name

GL704GSM

Rev

R1.1

Title : *****

Size

B

Dept.: ASUSTeK COMPUTER INC. **Engineer:** **Gaming RD4 EE1**

Date: Friday, July 27, 2018

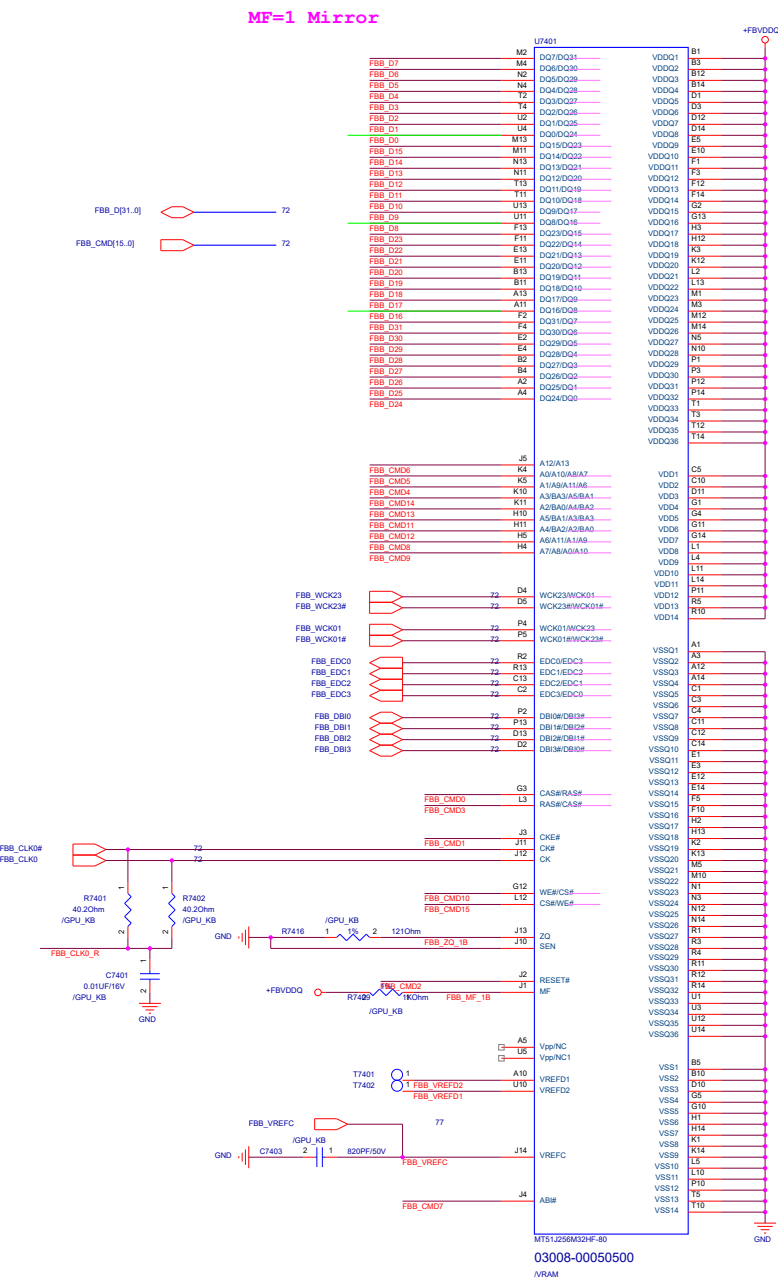
Sheet

69

of

103

FBB Partition Memory (1 of 2)



R1,3-02 R1,2-25

USE GDDR5 VRAM 128Mb x 32 (512MB)

1st: P/N:03008-00030100 HYNIX/H5GC4H24MFR-T2C (M-die) ,Strap: 0x2

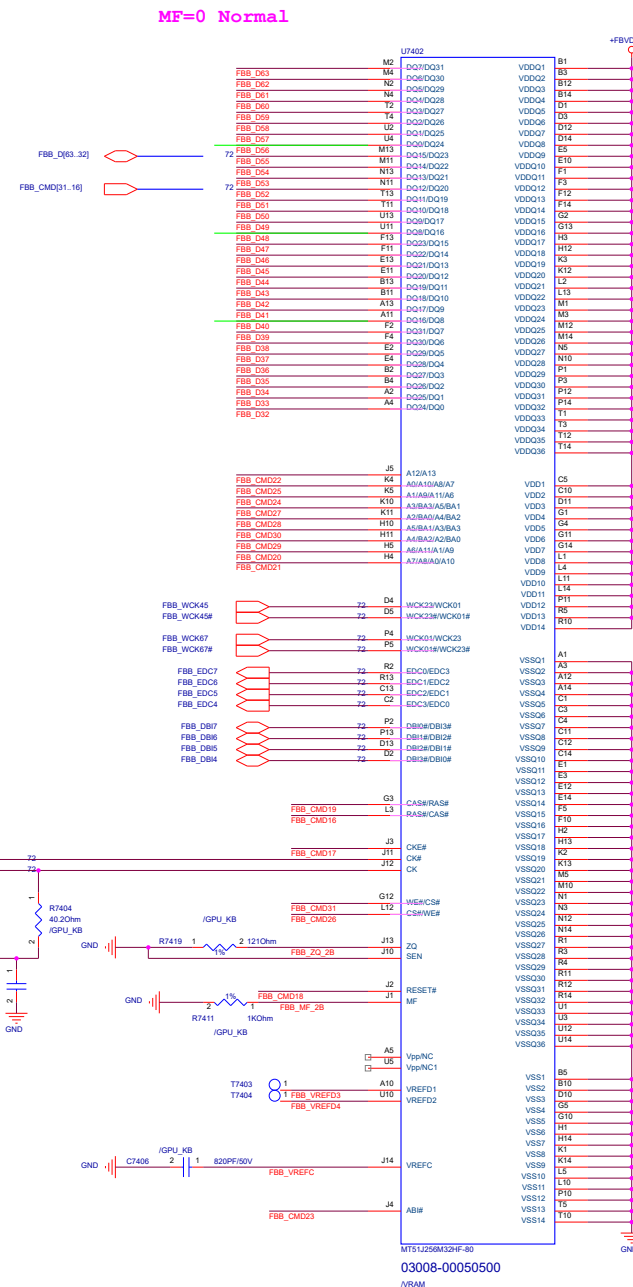
2nd: P/N:03008-00030200 SAMSUNG/K4G41325FC-HC03 ,Strap: 0x3

3nd: P/N:03008-00030400 Micron/EDW4032BABG-60-F (B-die) ,Strap: 0x4

GDD5 MODE SELECTION

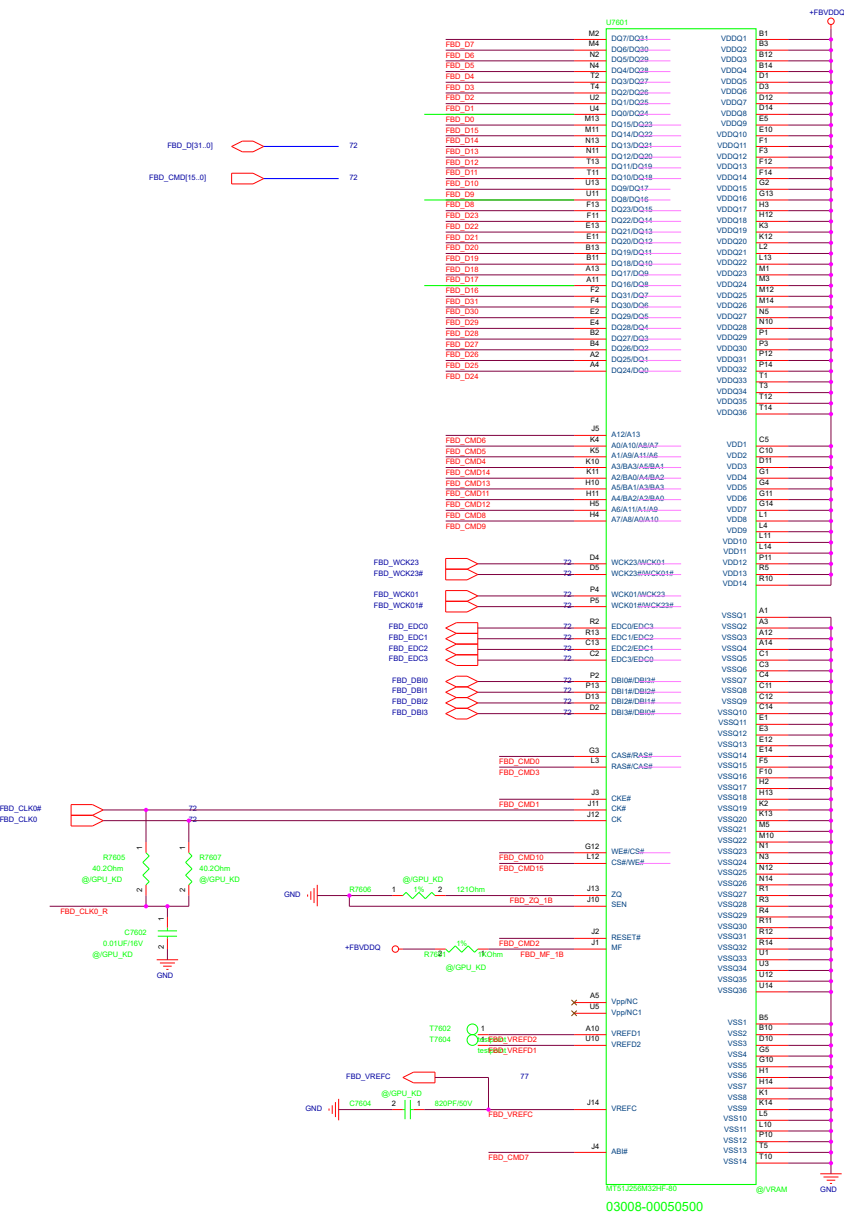
MODE	MF	EDC1	EDC2
x16	0	0	VDDQ
x32	0	VDDQ	VDDQ
x16 mirrored	VDDQ	VDDQ	0
x32 mirrored	VDDQ	VDDQ	VDDQ

FBF Partition Memory (2 of 2)



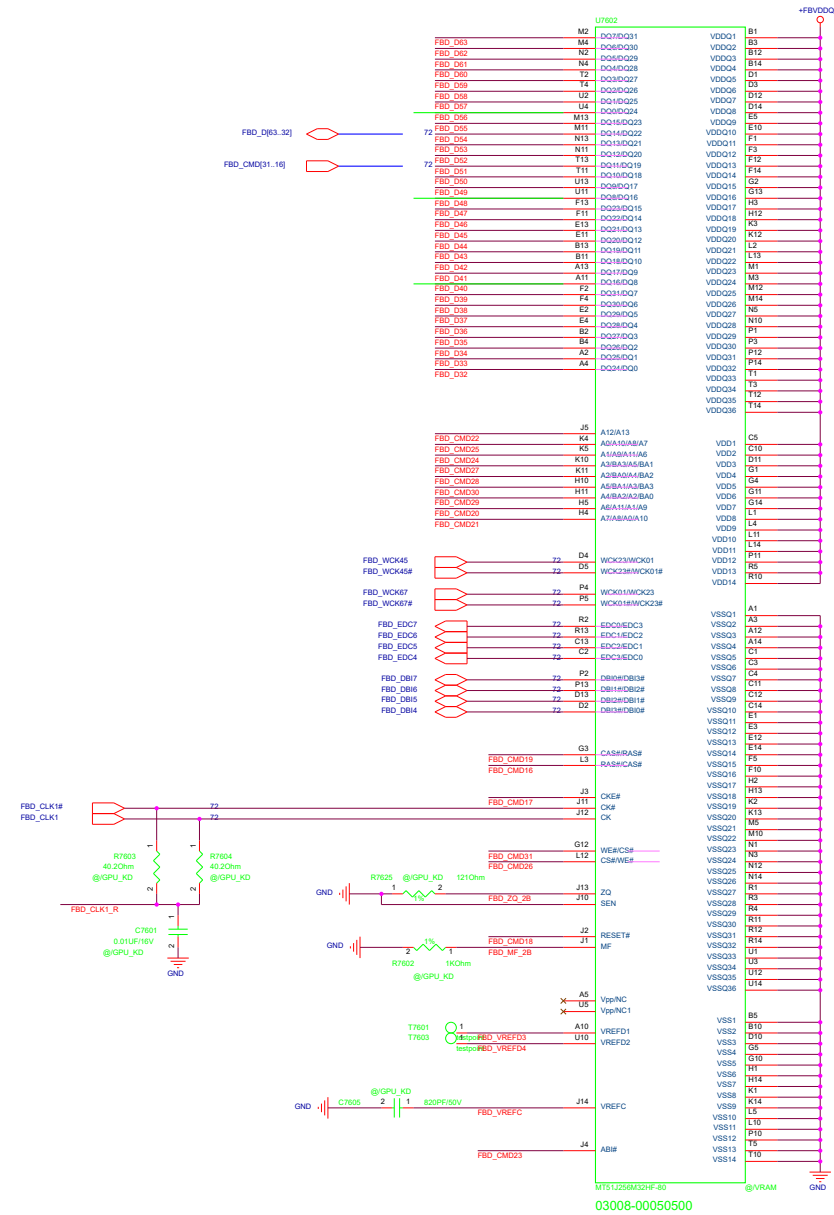
FBD Partition Memory (1 of 2)

MF=1 Mirror



FBD Partition Memory (2 of 2)

MF=0 Normal



R1.3-02 R1.2-25

USE GDDR5 VRAM 128Mb x 32 (512MB)

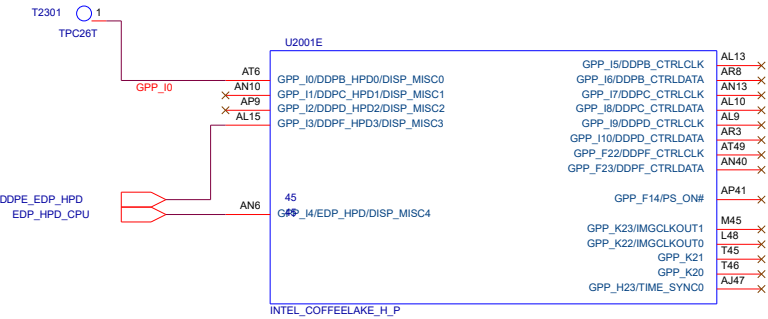
1st: P/N:03008-00030100 HYNIX/H5GC4H24MFR-T2C (M-die) ,Strap: 0x2

2nd: P/N:03008-00030200 SAMSUNG/K4G41325FC-HC03 ,Strap: 0x3

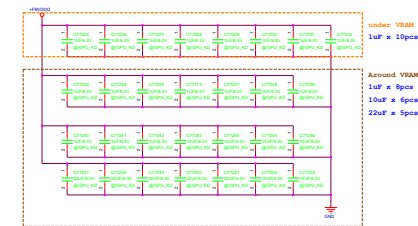
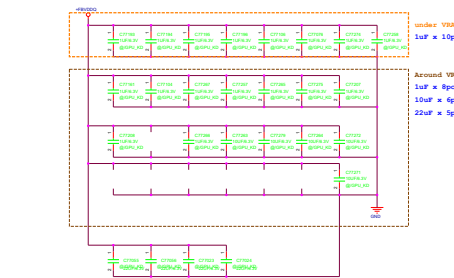
3nd: P/N:03008-00030400 Micron/EDW4032BABG-60-F (B-die) ,Strap: 0x4

GDD5 MODE SELECTION

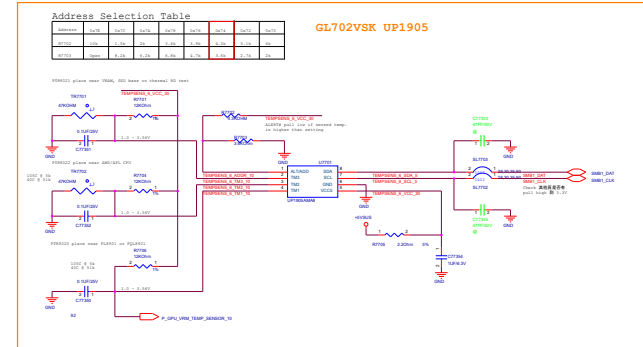
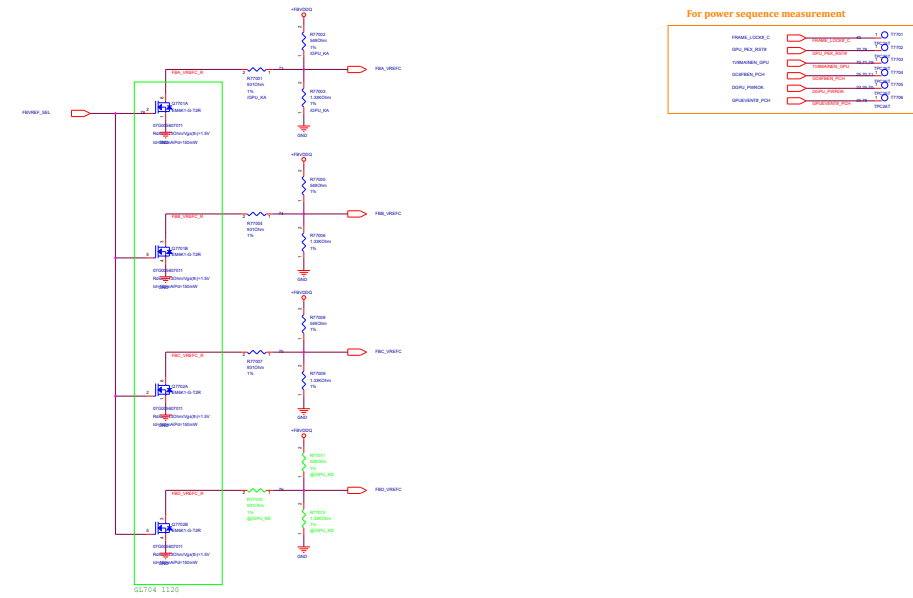
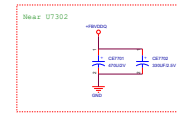
MODE	MF	EDC1	EDC2
x16	0	0	VDDQ
x32	0	VDDQ	VDDQ
x16 mirrored	VDDQ	VDDQ	0
x32 mirrored	VDDQ	VDDQ	VDDQ

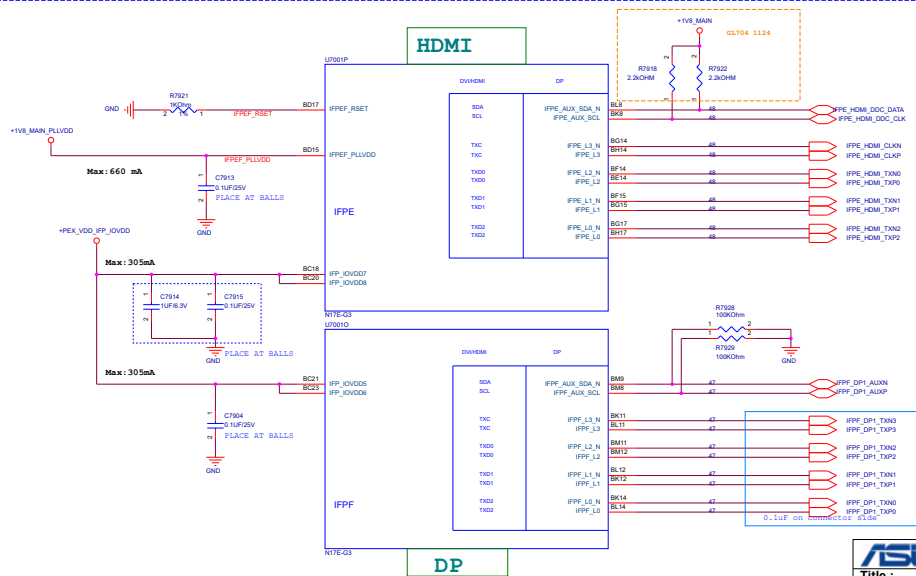
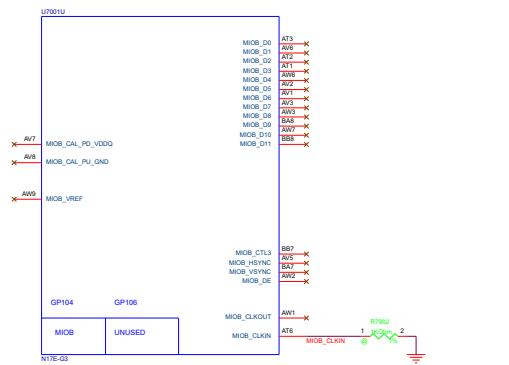
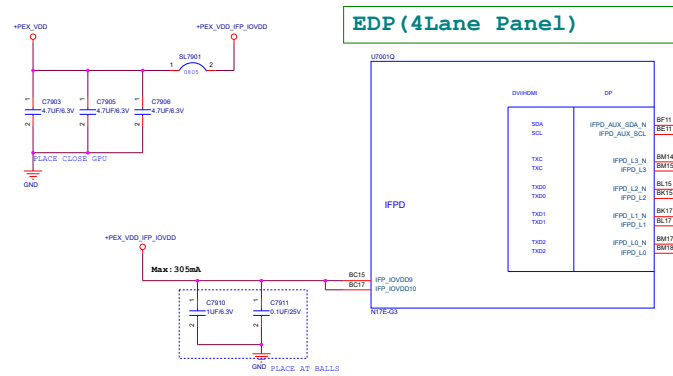
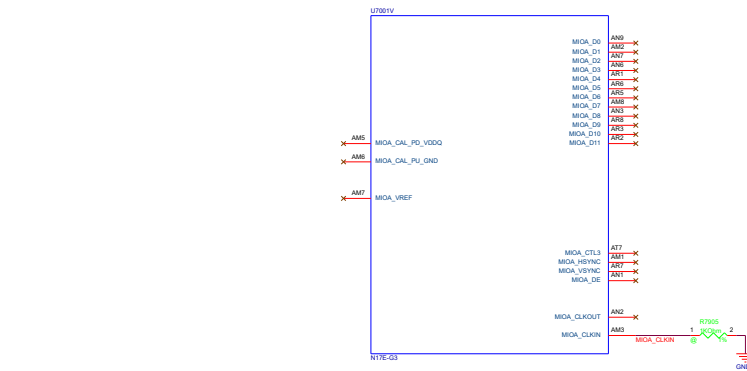
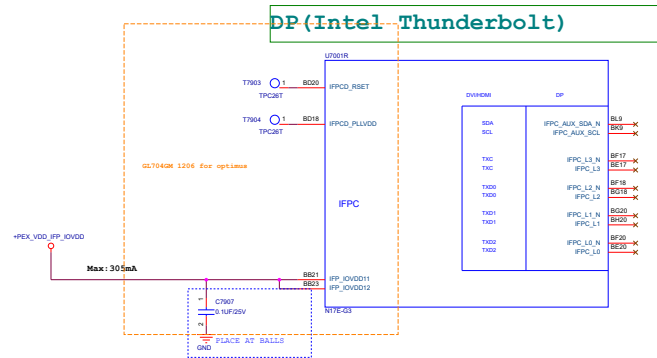
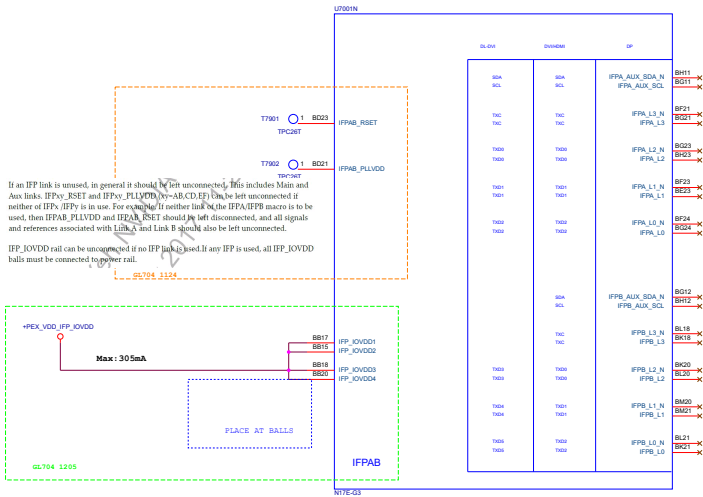


Channel D



□






15.2.3 Unconnected Signals (NC)

The following guidelines apply to unused MIO interfaces:

- Power up all VDDI8 pins.
- Leave MIO data pins and clock pins floating.

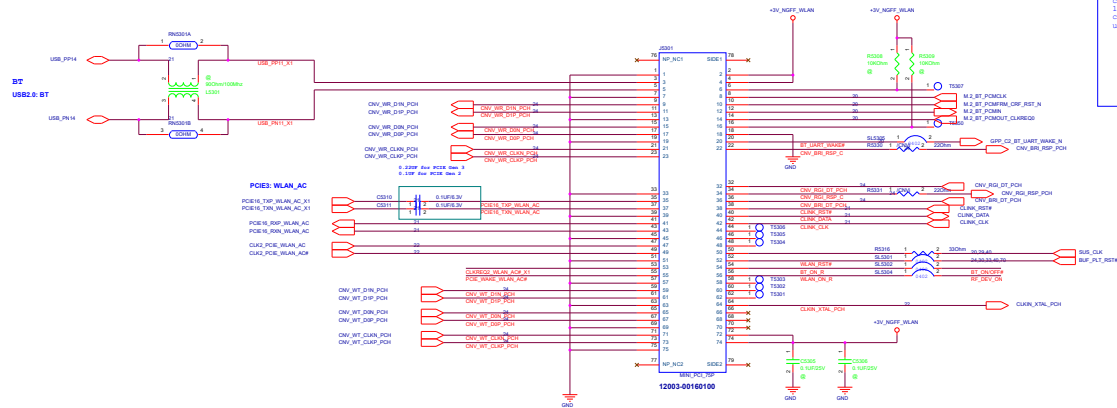
	Project Name GL704GSM	Rev R1.1
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Title : *****

Size B	Dept.: ASUSTeK COMPUTER INC. Engineer: Gaming RD4 EE1
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Date: Friday, July 27, 2018	Sheet 46 of 103
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NGFF M.2 TYPE_E-KEY WIFI



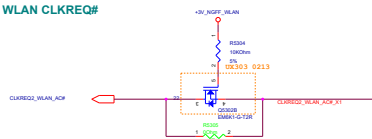
J5301_NGFF E-KEY WLAN Connector H=2.0mm

1st Source: P/N:12003-00076000 ARGOSY/NA50-S6701-TP20

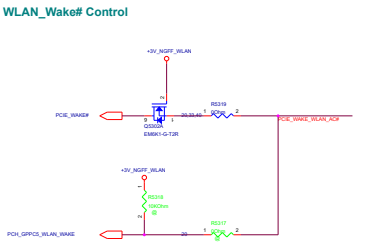
2nd Source: P/N:12003-00075200 DRAGONSTATE/213EBAA2FFB

3rd Source: P/N:12003-00075800 LOTES/APC10062-P001A

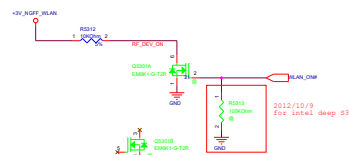
WLAN CLKREQ#



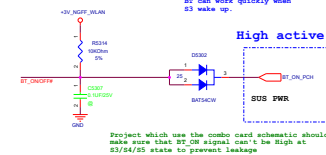
WLAN_Wake# Control



WLAN & BT ON

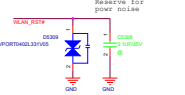


To match WISOL test. Due to BT wake up to spend much time if use +3VS. So, change to +3V, let BT can work quickly when S3 wake up.

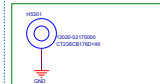


Project which use the combo card schematic should make sure that ST_ON signal can't be High at S3/S4/S5 state to prevent leakage

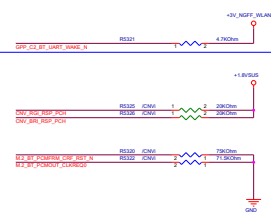
For EMI



WLAN NUT

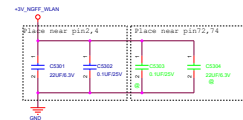
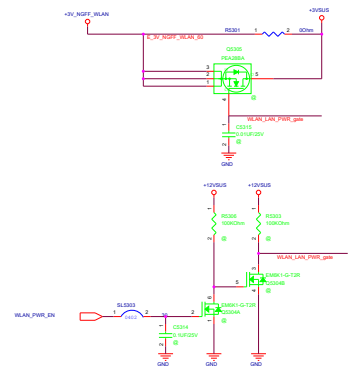


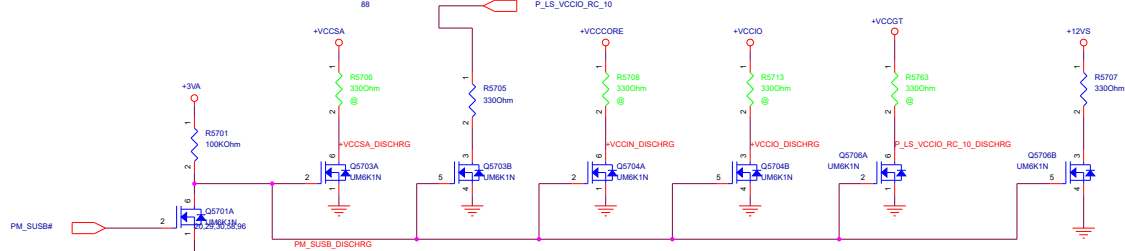
```
GPP C2 B7 UART WAKE N(PCH GPP C2): weak internal pull down
0 : Disable Intel ME Crypto Transport Layer Security(TLS)
cipher suite (no confidentiality). (Default)
1 : Enable Intel ME Crypto Transport Layer Security(TLS)
cipher suite (with confidentiality). Must be pulled
up to support Intel AMT with TLS.
```



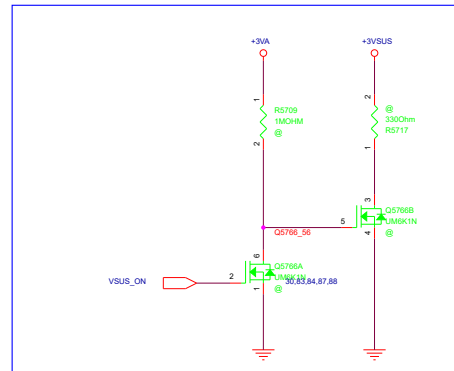
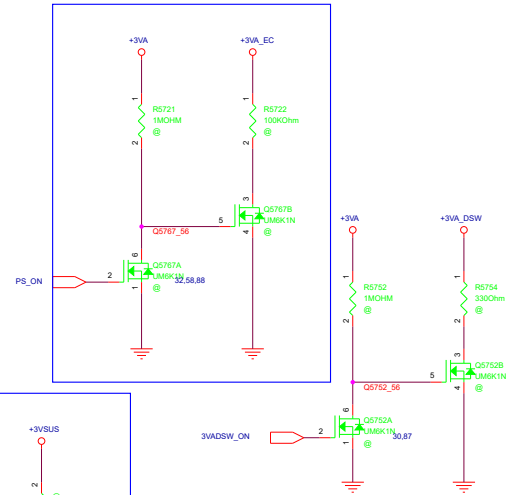
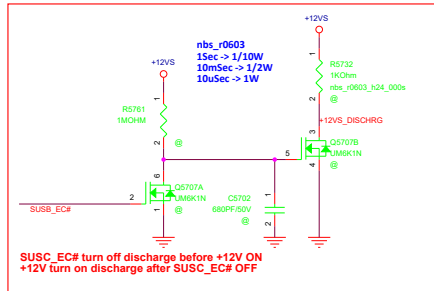
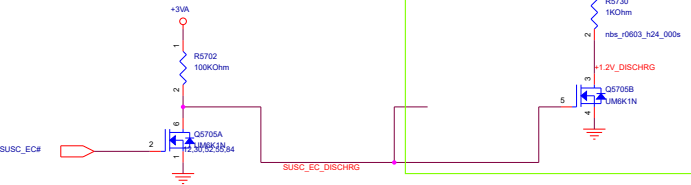
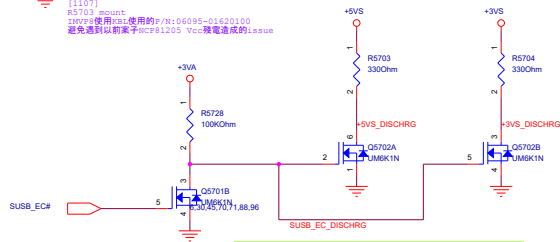
WLAN PWR_+3V_NGFF_WLAN (Non-ISCT)

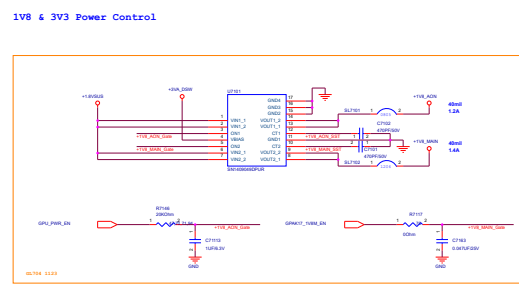
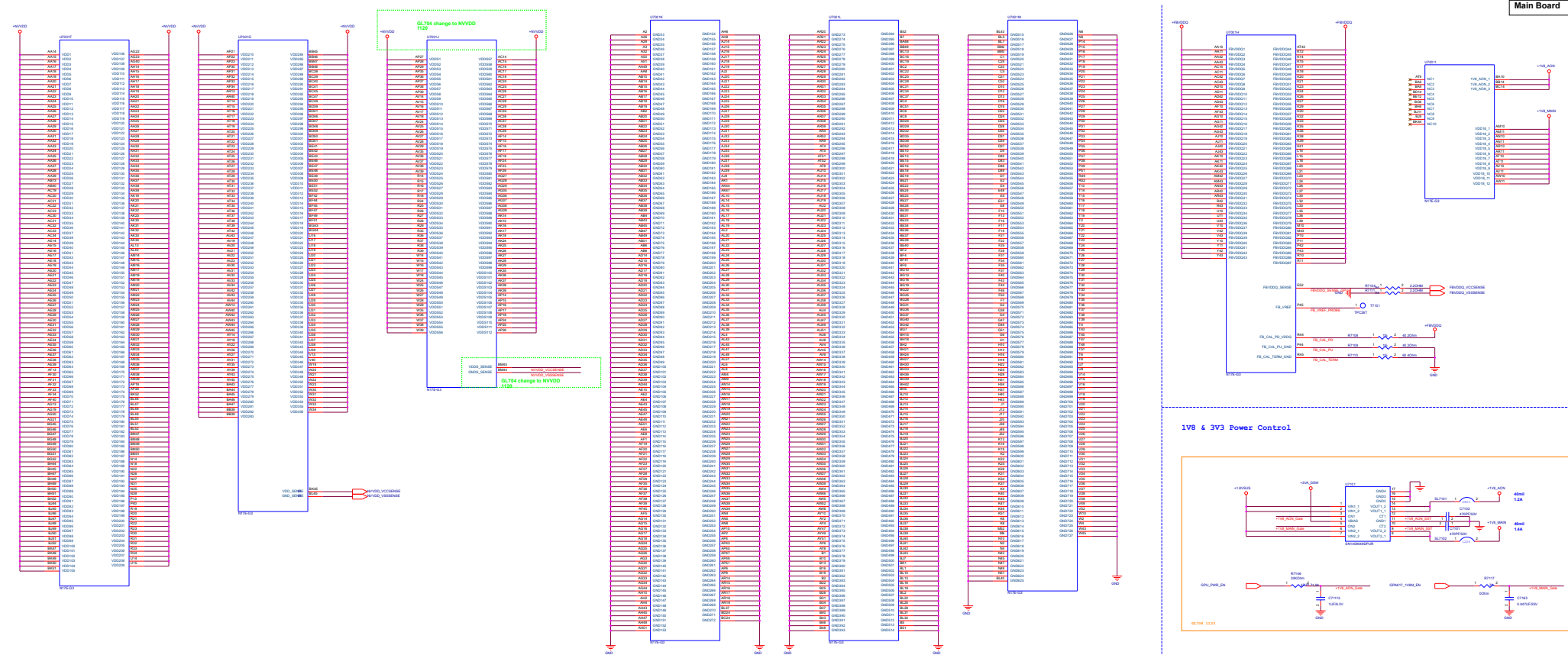
Support ASUS Open Cloud Computing (AOCConnect)
WLAN FWR to +3VSUS



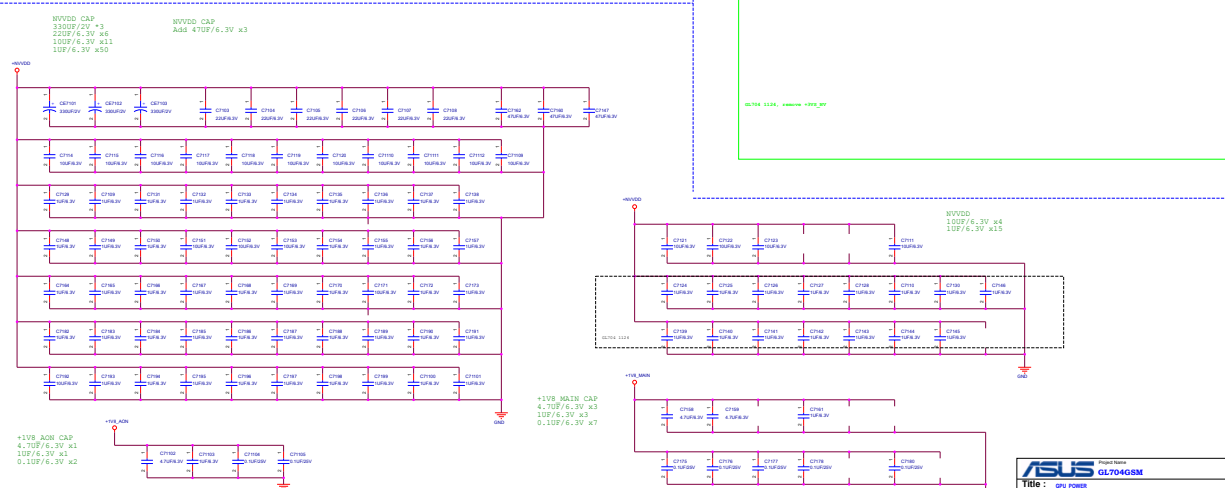
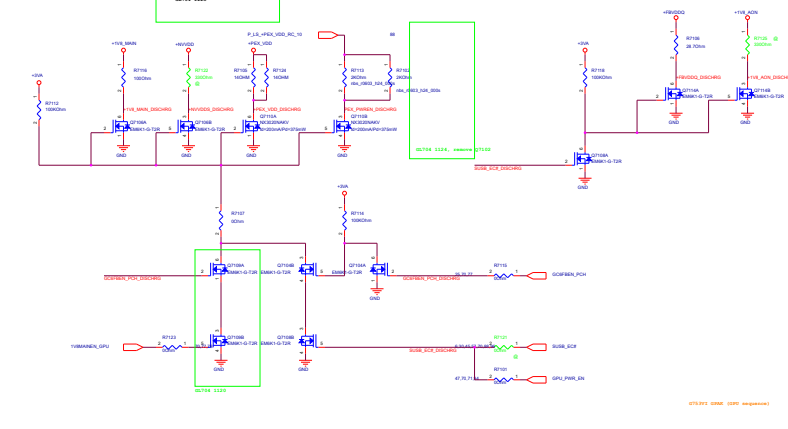


[1107]
R5703 mount
12V22 使用12V22 使用的P/N:06095-01620100
避免遇到以前案子VCCF81205 Vcc-放电造成的Issue



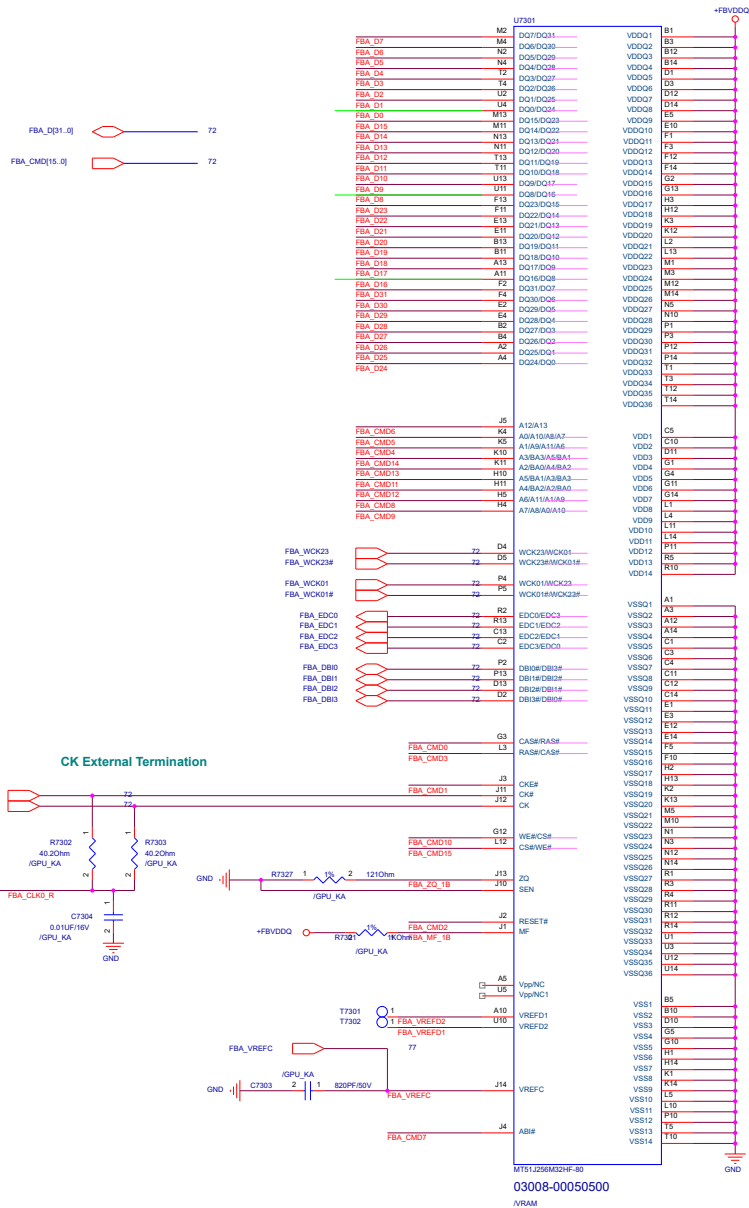


Discharge



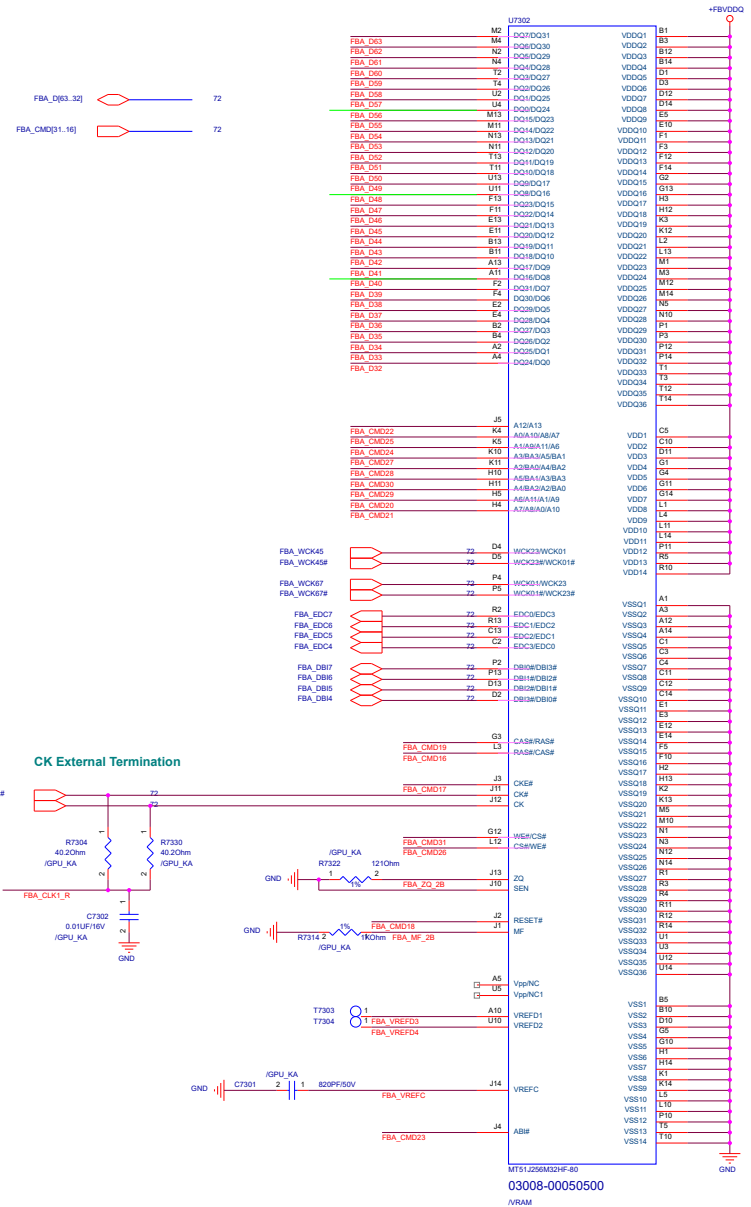
FBA Partition Memory (1 of 2)

MF=1 Mirror



FBA Partition Memory (2 of 2)

MF=0 Normal



R1.3-02 R1.2-25

USE GDDR5 VRAM 128Mb x 32 (512MB)

1st: P/N:03008-00030100 HYNIX/H5GC4H24MFR-T2C (M-die) ,Strap: 0x2

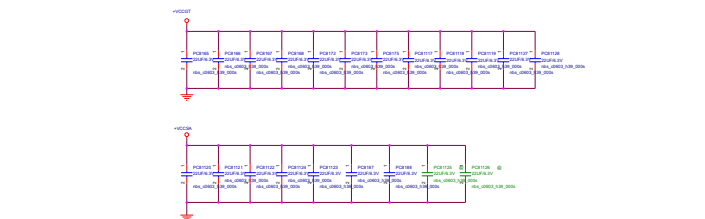
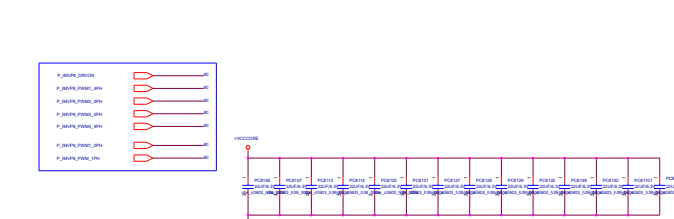
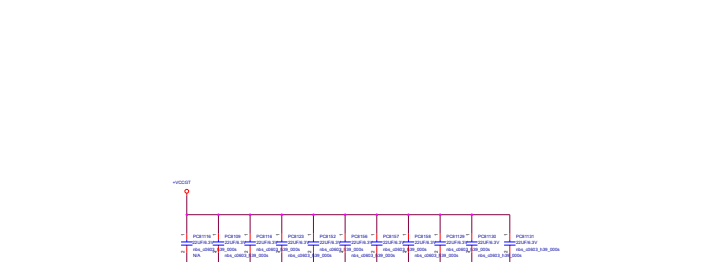
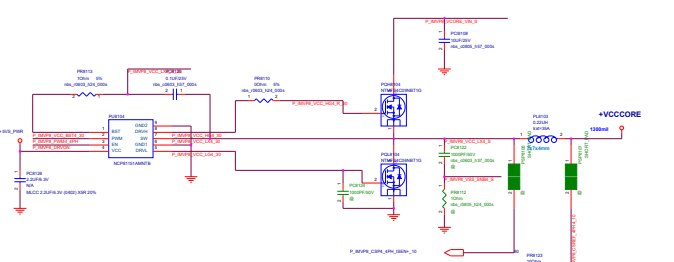
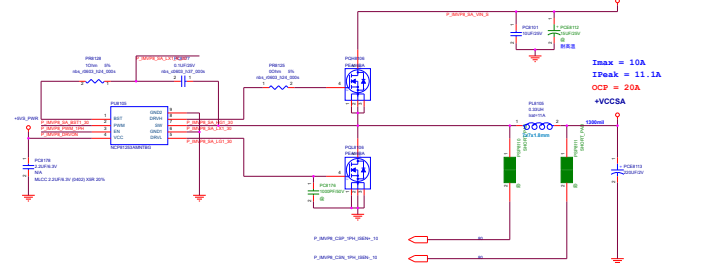
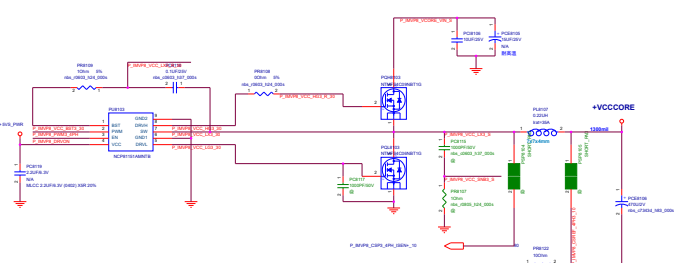
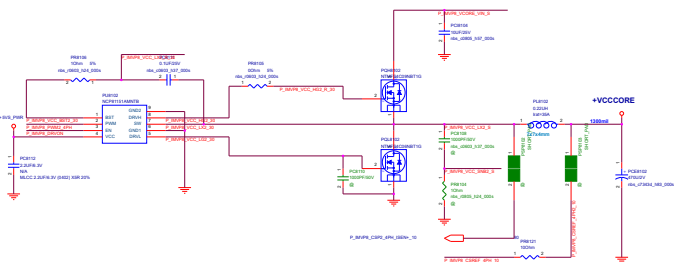
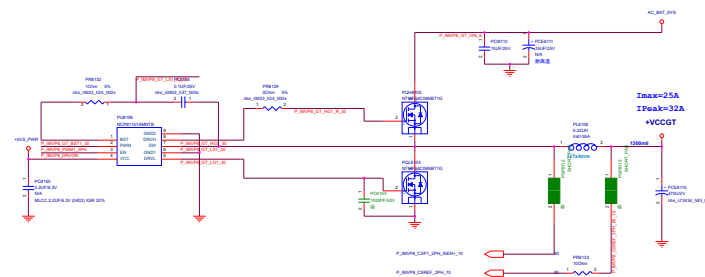
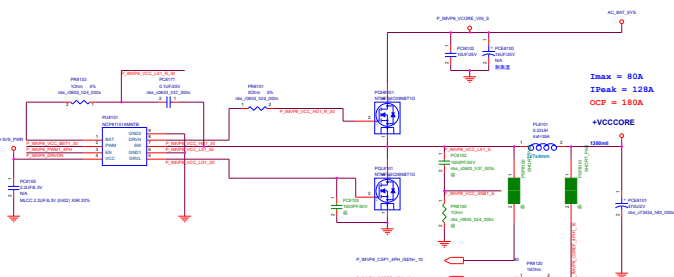
2nd: P/N:03008-00030200 SAMSUNG/K4G41325FC-HC03 ,Strap: 0x3

3rd: P/N:03008-00030400 Micron/EDW4032BABG-60-F (B-die) ,Strap: 0x4

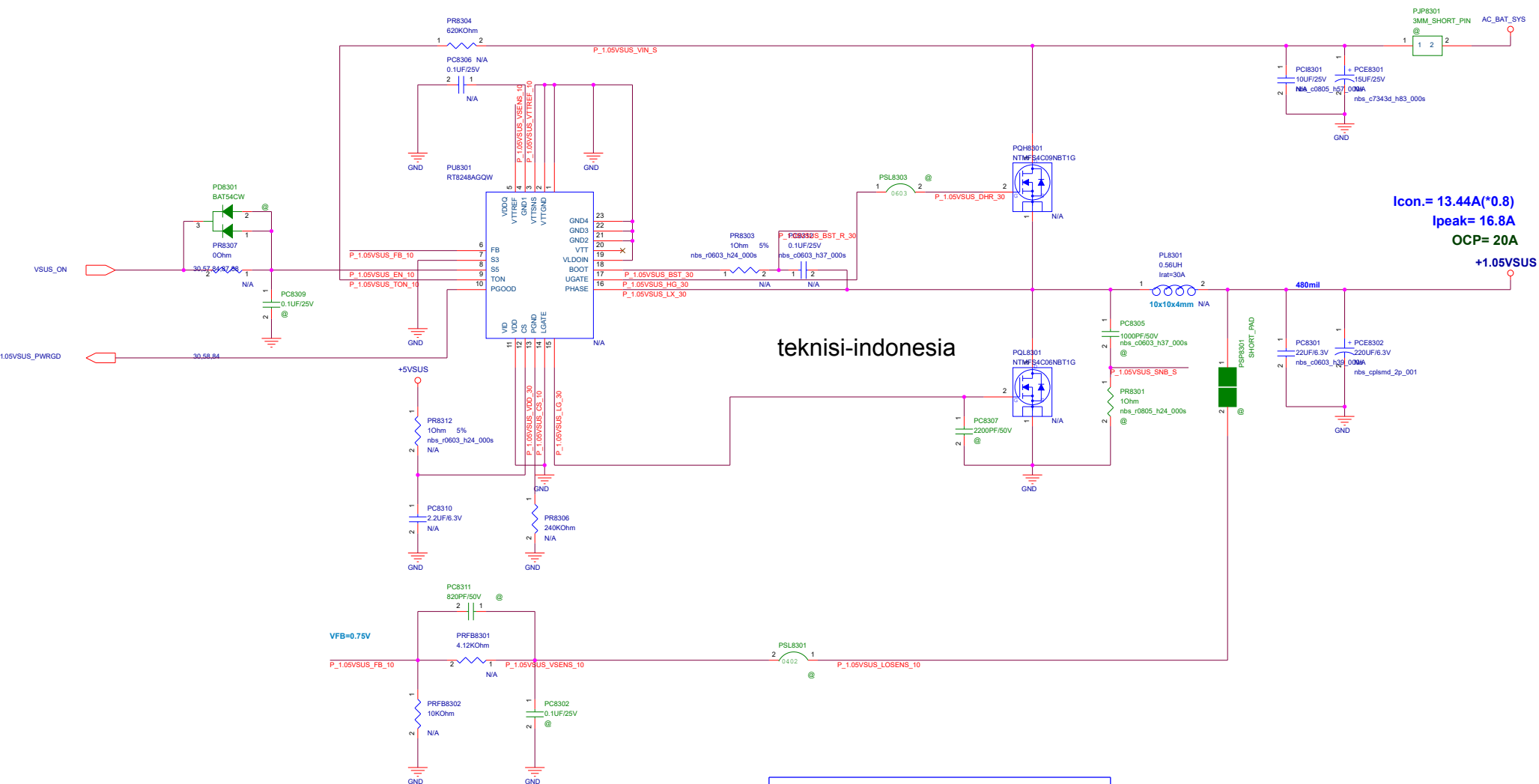
GDD5 MODE SELECTION

MODE	MF	EDC1	EDC2
x16	0	0	VDDQ
x32	0	VDDQ	VDDQ
x16 mirrored	VDDQ	VDDQ	0
x32 mirrored	VDDQ	VDDQ	VDDQ

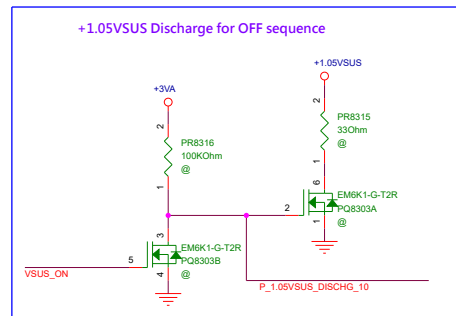
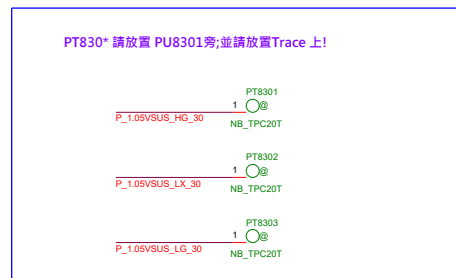
Coffee lake P8 Power [For CPU]



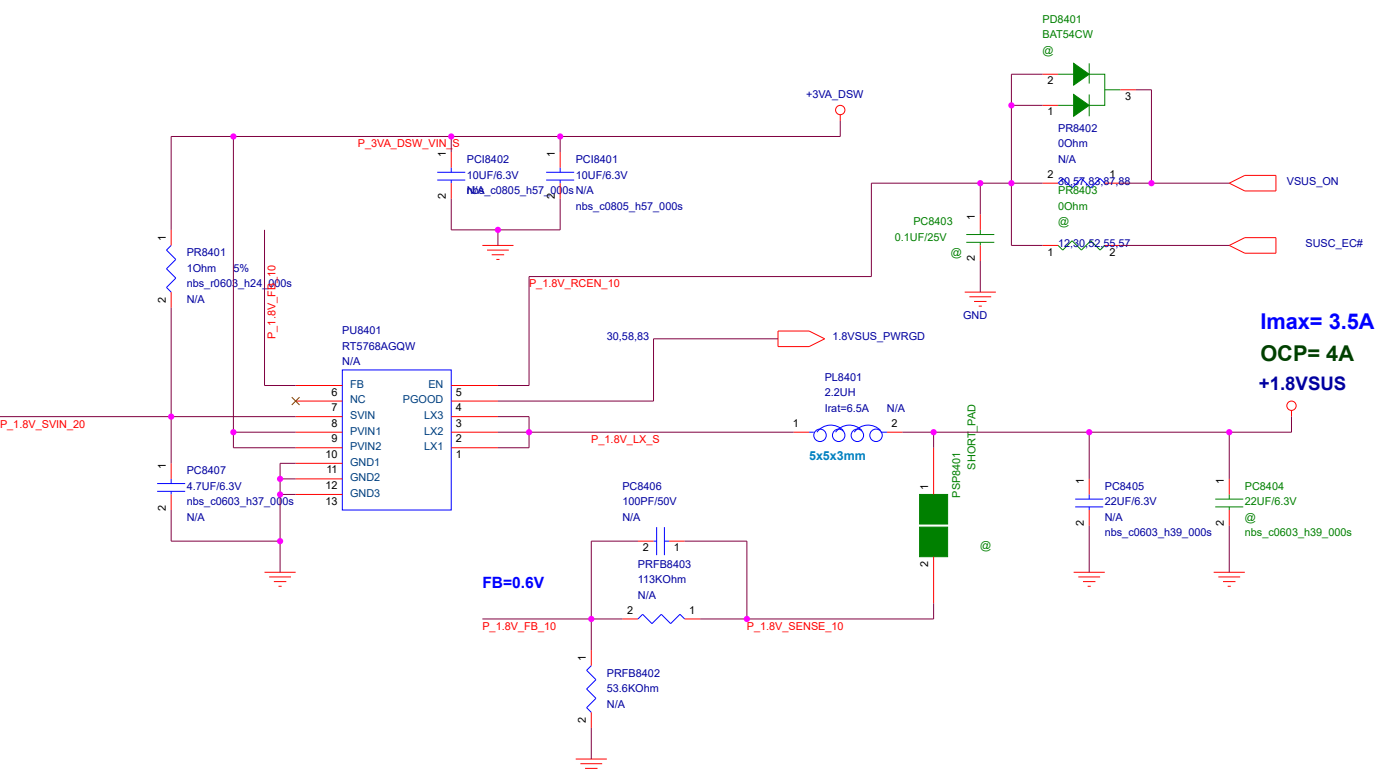
+1.05VSUS [For PCH]




Icon = 13.44A(*0.8)
Ipeak = 16.8A
OCP = 20A
+1.05VSUS



+1.8VSUS [For PCH]



<Variant Name>

		Project Name GL704GM		Rev R1.0
Title : PW_+1.8VSUS				
Size A3	Dept.: NB Power Team		Engineer: Hon	
Date: Friday, Friday, July 27, 2018			Sheet 84	of 103



Project Name

Coffe Lake-H

Rev

R1.0

Title : PW_

Size

A3

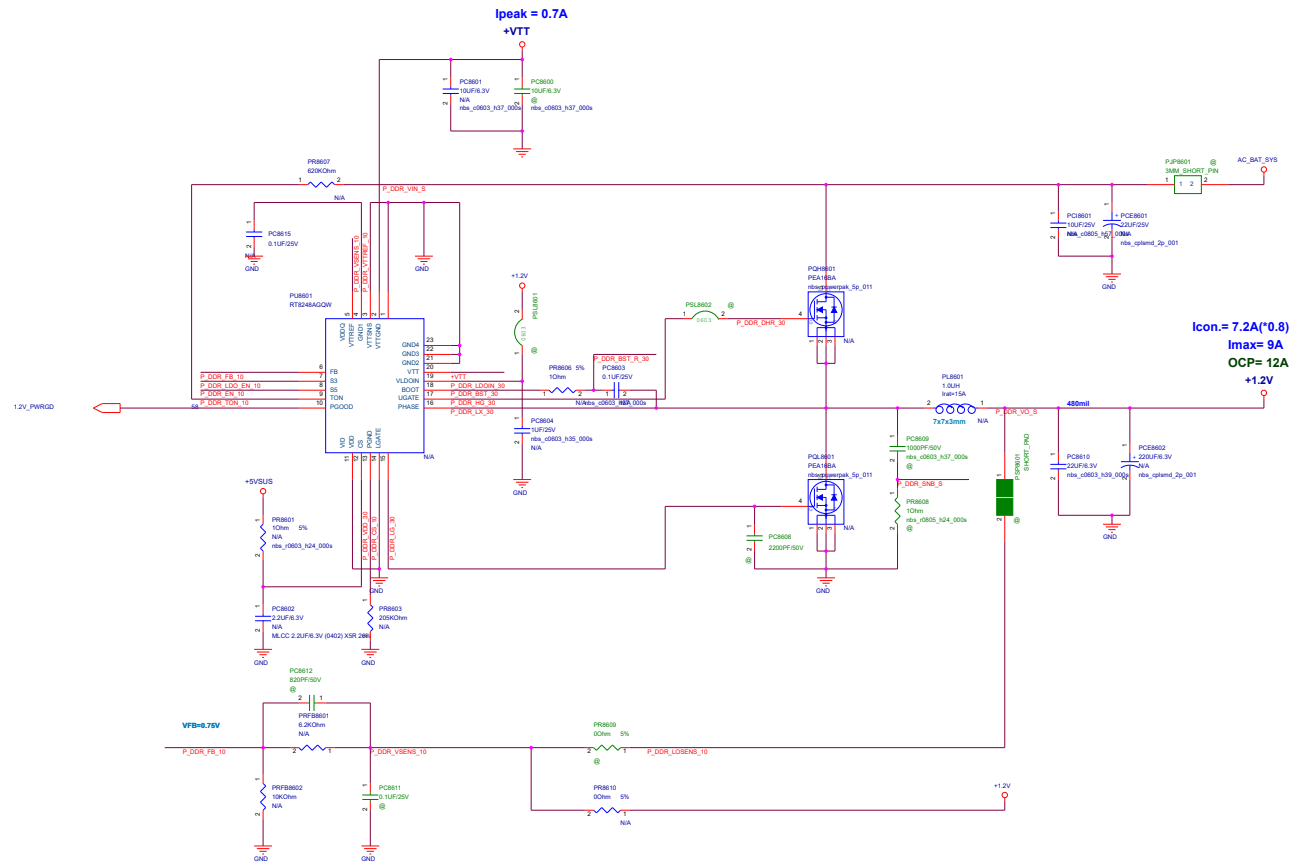
Dept.: NB Power team

Engineer: Benson

Date: Friday, July 27, 2018

Sheet 85 of 103

$I_{\text{peak}} = 0.7\text{A}$



P_DDR_HQ_30

P_DDR_LX_30

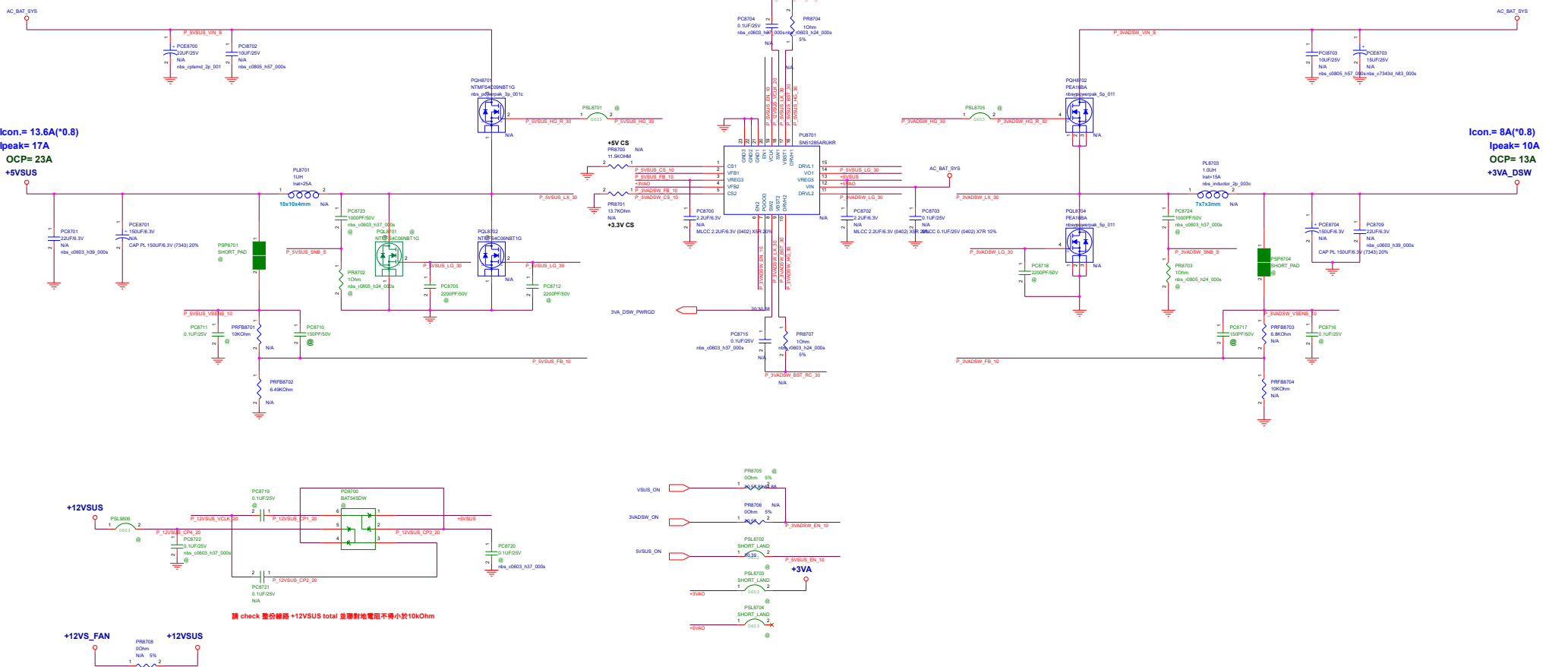
P_DDR_LG_30

PT860

TPC20T



+3VA_DSW / +5VSUS [System Power]

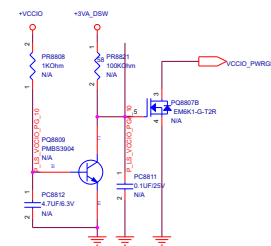


Adaptor Mode (MVP8)							
	S0	S1	S2	S3	S4	S5	S5 with USB Charger+
PS_ON	1	-	1	-	1	-	1
3VADSW_ON	1	-	1	-	1	-	1
3VBSW_ON	1	-	1	-	1	-	1
RVBSW_ON	1	-	1	-	1	-	1
1.35V_ON	1	-	1	-	0	-	0
SUSC_ECF	1	-	1	-	0	-	0
SVBS_ECF	1	-	0	-	0	-	0

Battery Mode (MVP8)							
	B0	CS	S3	DS3	S4	S5	S6 with USB Charger+
PS_ON	1	-	-	1	0	0	1
3VADSW_ON	1	-	-	1	0	0	0
3VSUS_ON	1	-	-	0	0	0	0
IVBUS_ON	1	-	-	1	0	0	1
1.35V_ON	1	-	-	1	0	0	0
BUSC_ECF	1	-	-	0	0	0	0
SUSB_ECF	1	-	-	0	0	0	0

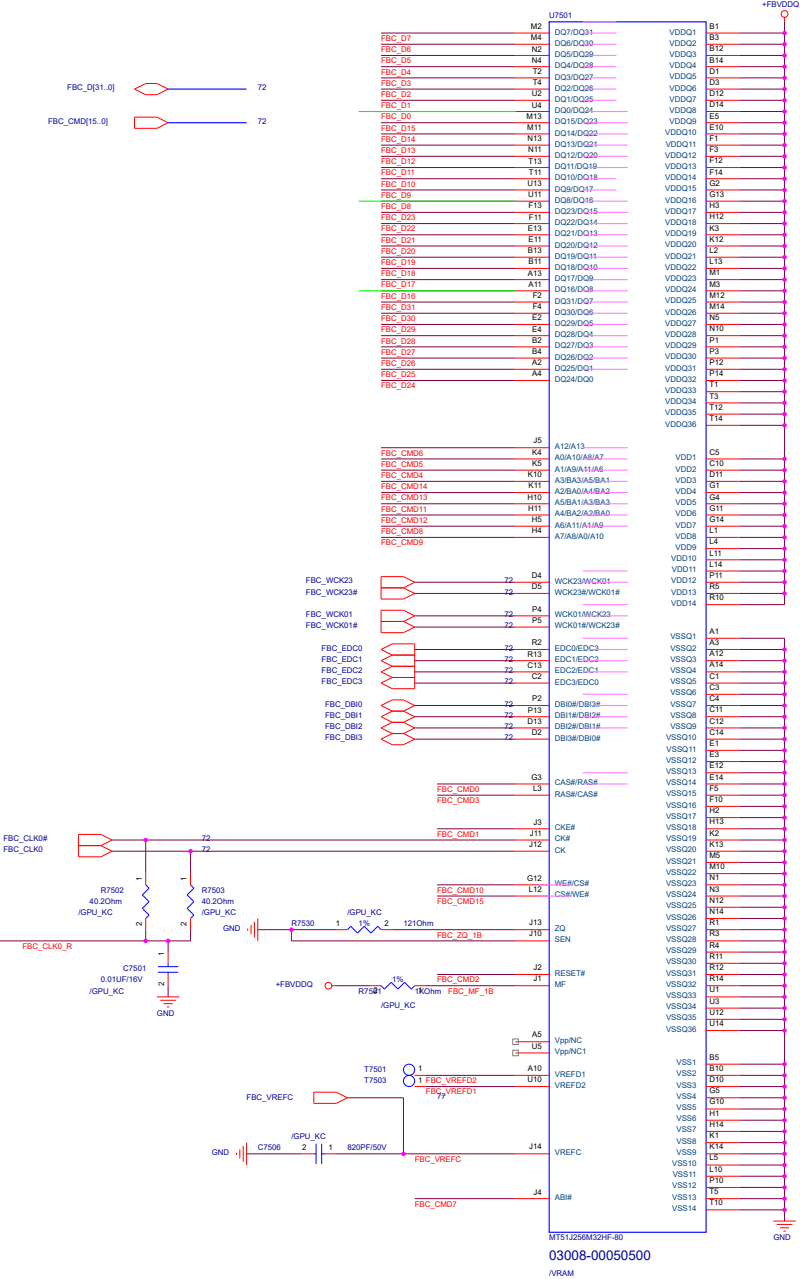


Main Board



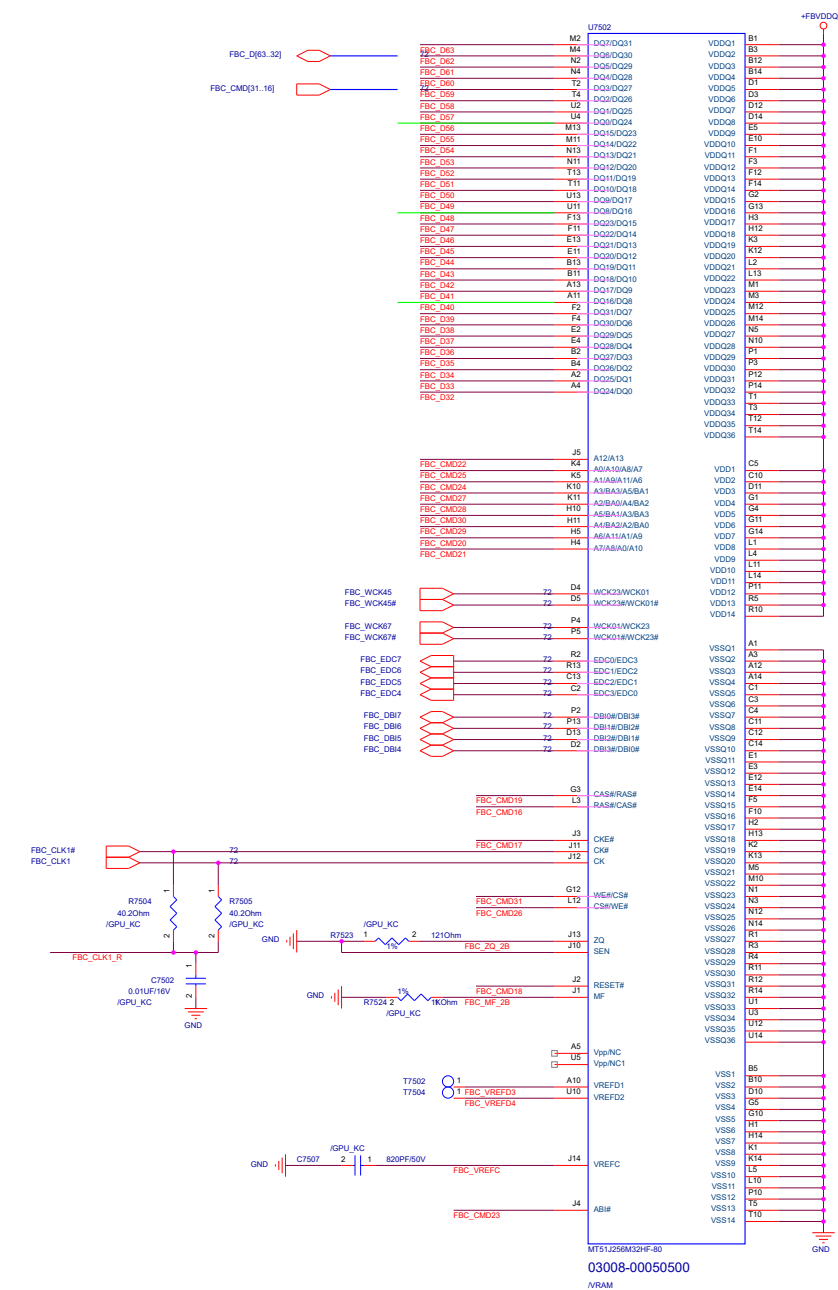
FBC Partition Memory (1 of 2)

MF=1 Mirror



FBC Partition Memory (2 of 2)

MF=0 Normal



R1.3-02 R1.2-25

USE GDDR5 VRAM 128Mb x 32 (512MB)

1st: P/N:03008-00030100 HYNIX/H5GC4H24MFR-T2C (M-die), Strap: 0x2

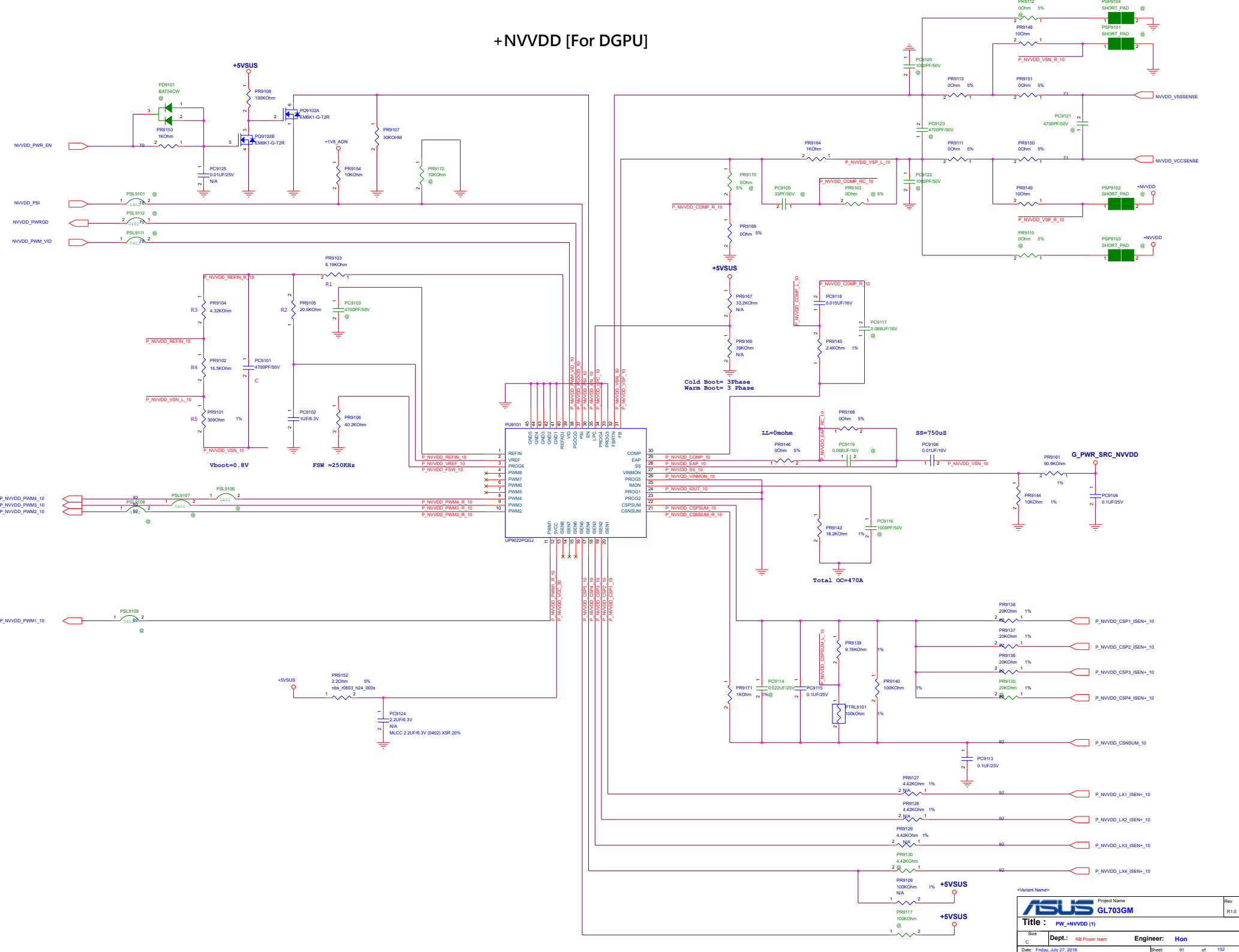
2nd: P/N:03008-00030200 SAMSUNG/K4G41325FC-HC03, Strap: 0x3

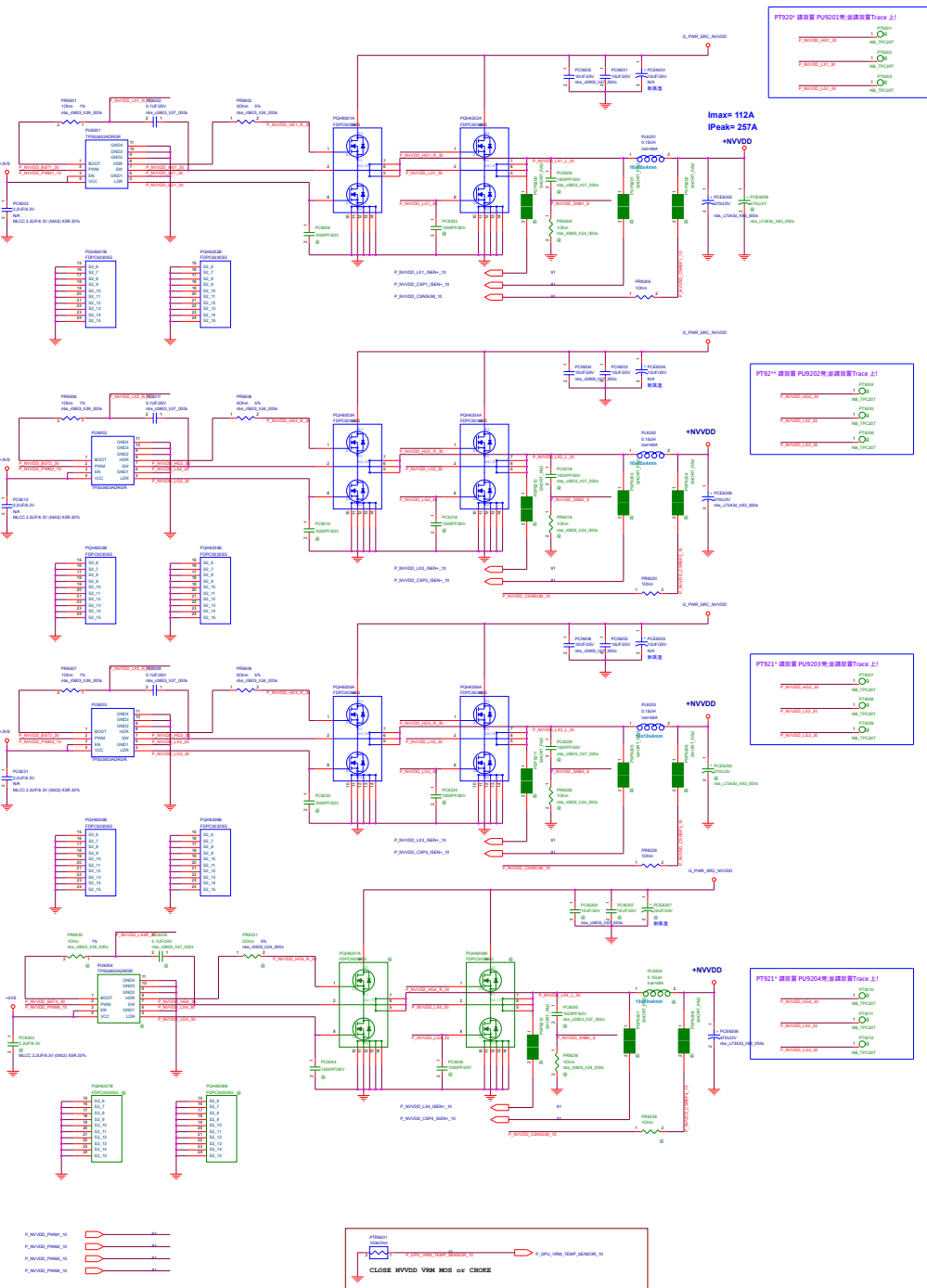
3nd: P/N:03008-00030400 Micron/EDW4032BABG-60-F (B-die), Strap: 0x4

GDD5 MODE SELECTION

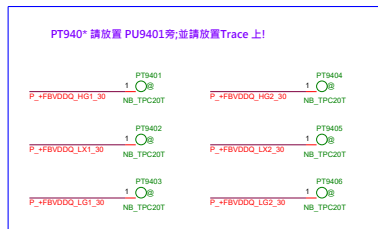
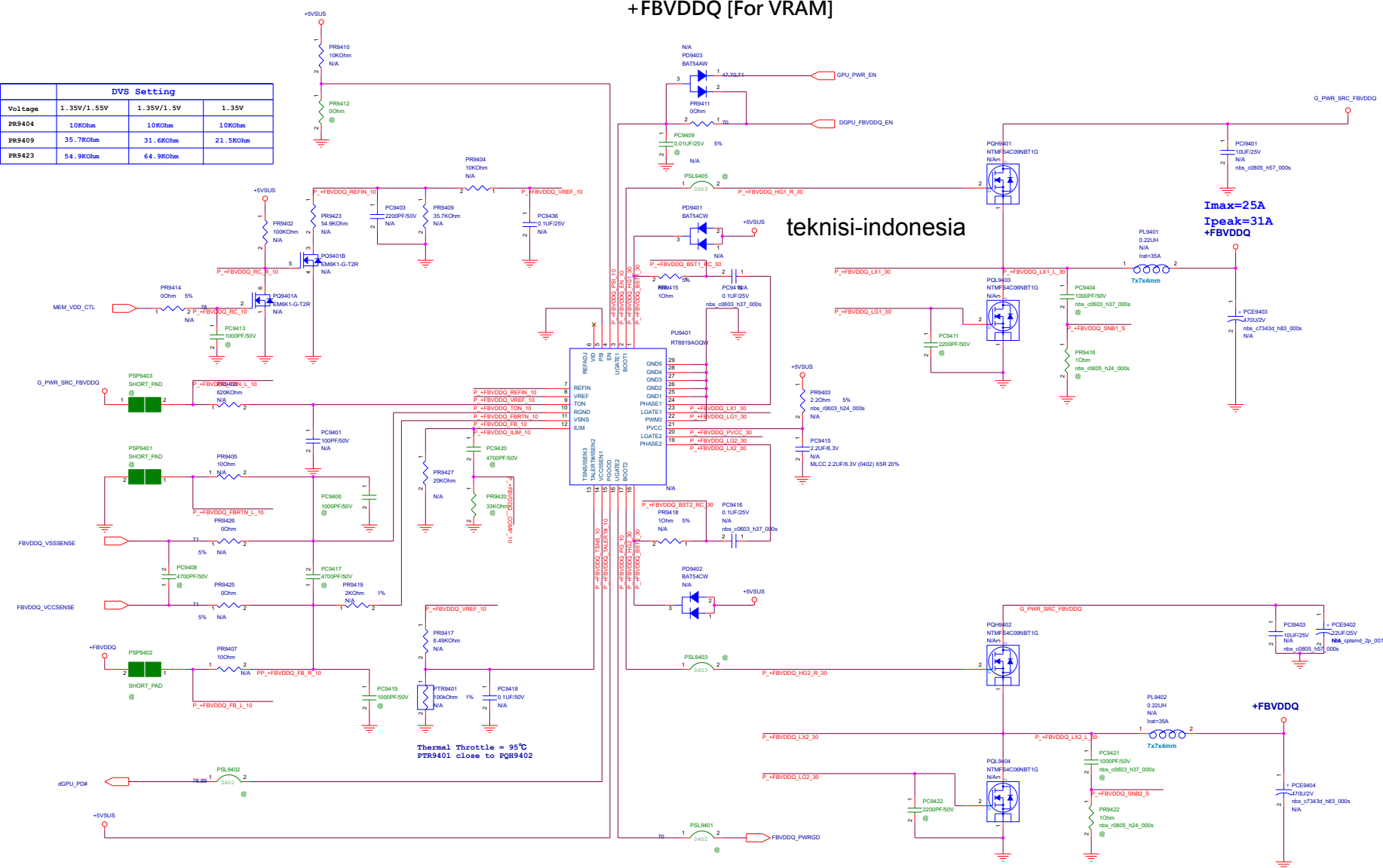
MODE	MF	EDC1	EDC2
x16	0	0	VDDQ
x32	0	VDDQ	VDDQ
x16 mirrored	VDDQ	VDDQ	0
x32 mirrored	VDDQ	VDDQ	VDDQ

+NVVDD [For DGPU]

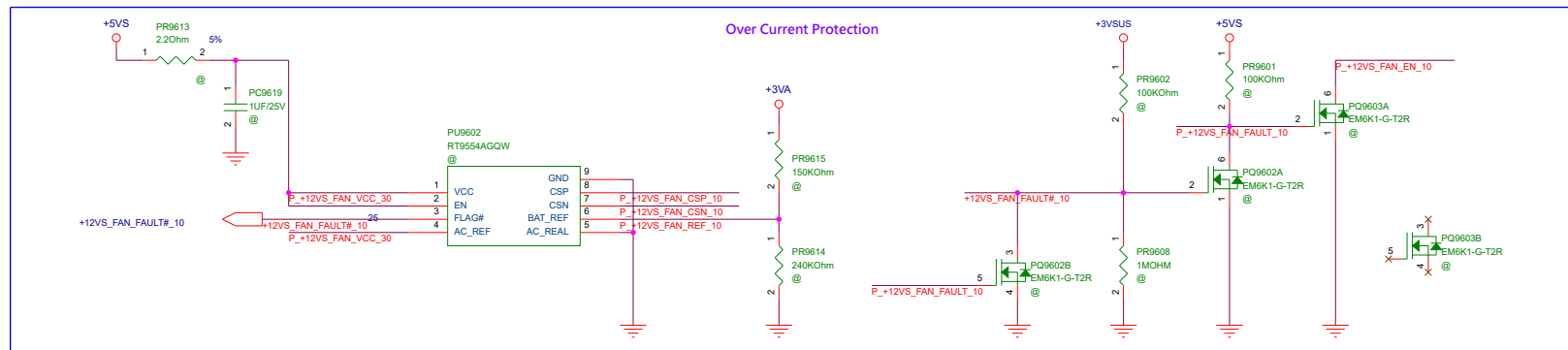
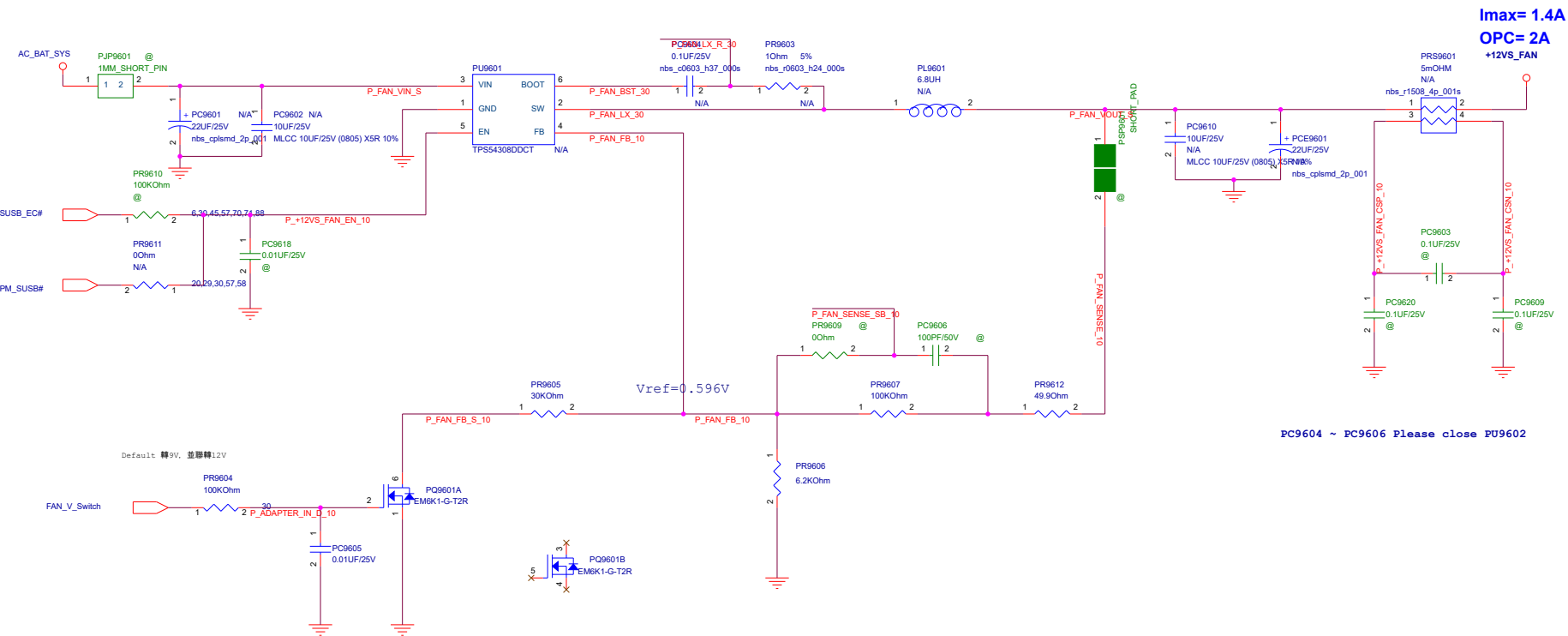




	DVS Setting		
Voltage	1.35V/1.55V	1.35V/1.5V	1.35V
PR9404	10KOhm	10KOhm	10KOhm
PR9409	35.7KOhm	31.6KOhm	21.5KOhm
PR9423	54.9KOhm	64.9KOhm	



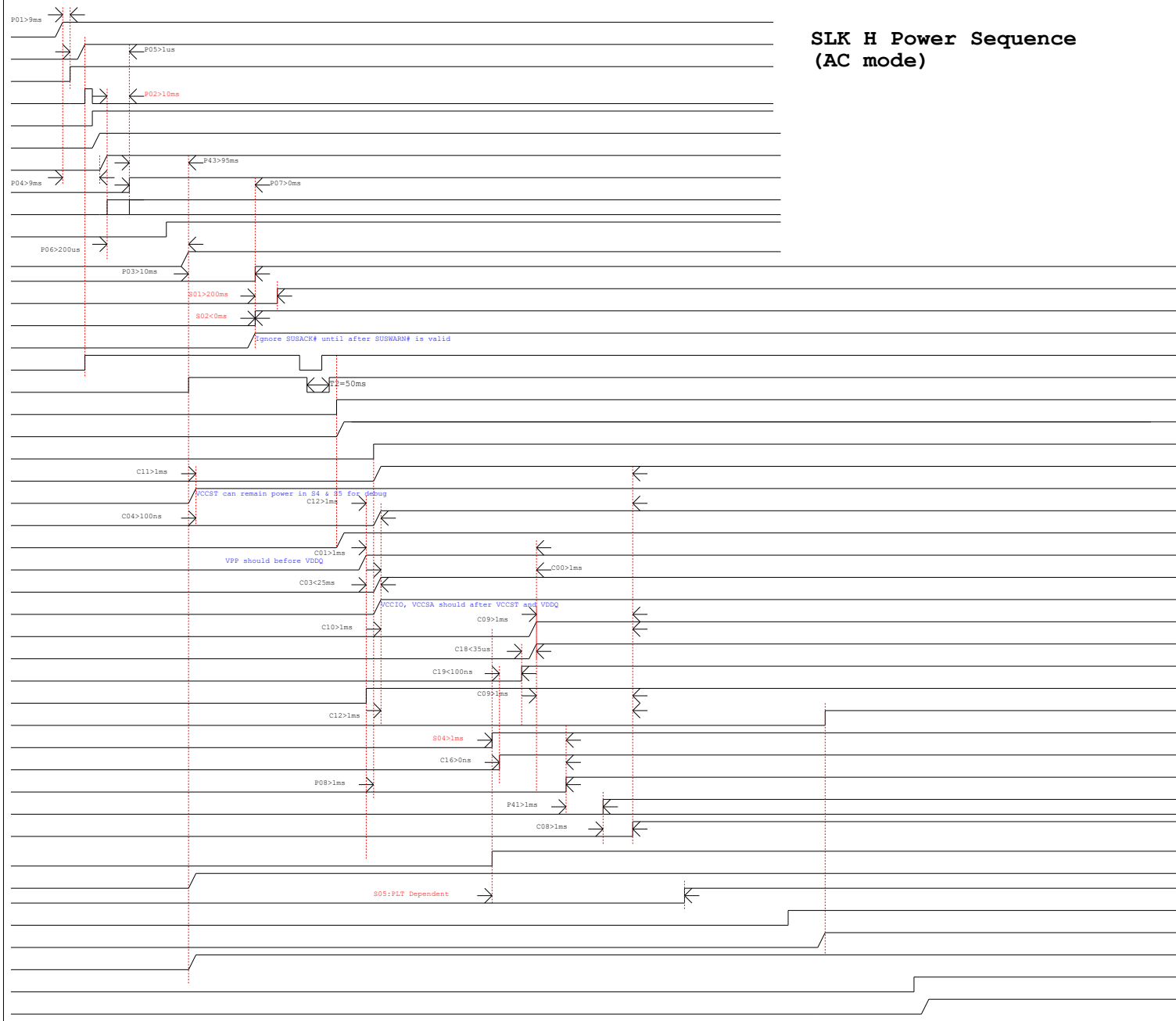
+12VS_FAN [For FAN]



<Variant Name>

Project Name		Rev
GL704GS		R1.0
Title : PW_+12VS_FAN		
Size	Dept.: NB Power team	Engineer: Hon
A3		
Date: Friday, July 27, 2018	Sheet	96 of 103

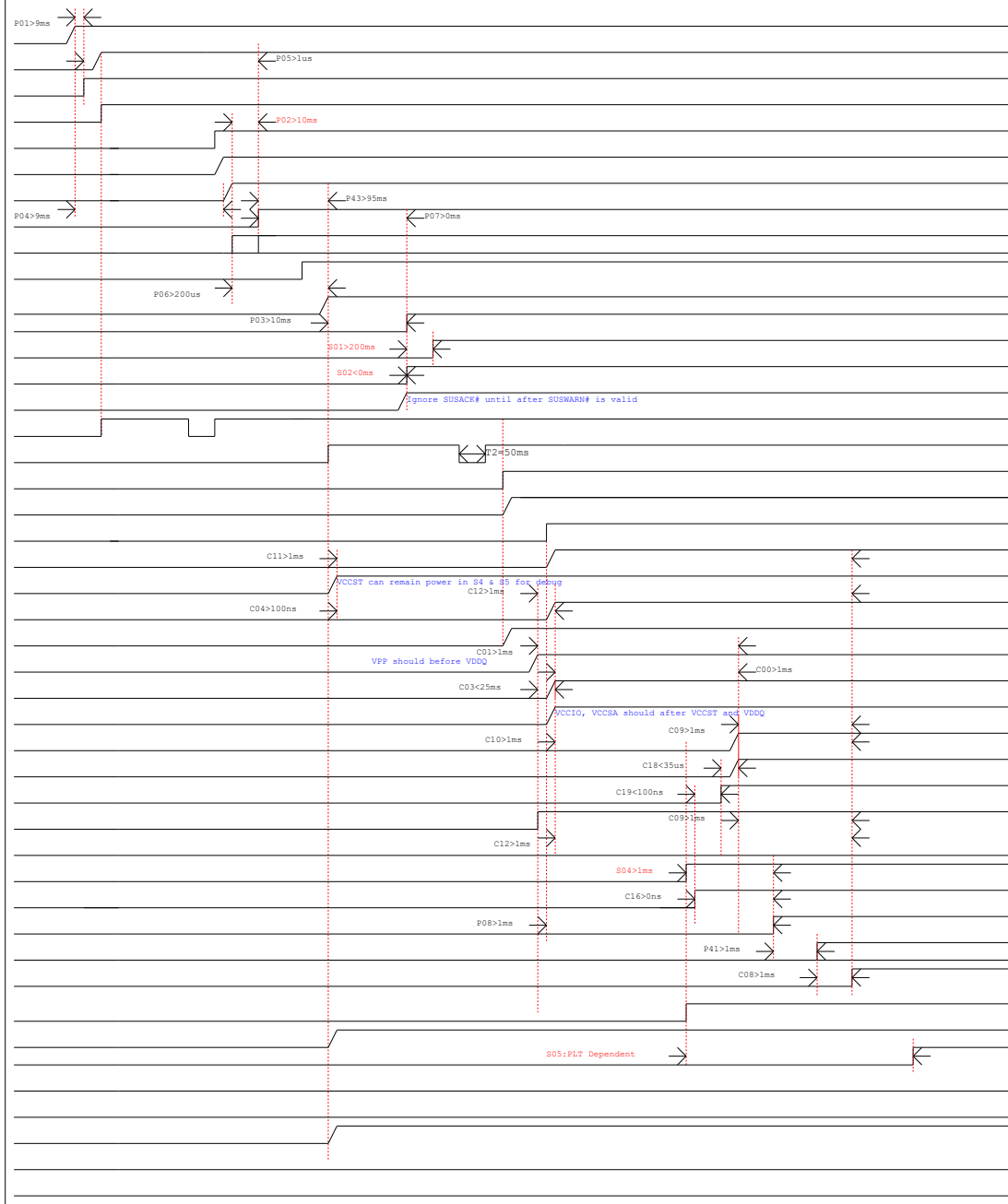
C:CPU (+RTCBAT)+3VA_RTC
P:PCH (AC_BAT_SYS)+3VA/+5VA
S:PLT (+3VA_RTC)RTCRST#(PCH)
Power (Power)AC_IN_OC#(EC)
Signal (EC)PS_ON(+3VA_EC)
(PS_ON)+3VA_EC(EC)
(3VADSW_ON)+3VA_DSW(3VA_DSW_PWRGD)
(EC)DPWROK_EC(PCH)
(+3VA_DSW)PM_BATLOW#(PCH)
(PCH)PM_SLP_SUS#(EC)
(VSUS_ON)+1.0VSUS_VCCPRIM(1.0VSUS_PWRGD)
(EC)PM_RSMRST#_PCH(PCH)
(PCH)SUSWARN#(EC)
(EC)ME_AC_PRESENT_PCH(PCH)
(EC)PCH_SUSACK#(PCH)
(PWR_Switch)PWR_SW#(EC)
(EC)PM_PWRBTN#(PCH)
(EC)SUSC_EC#(Power)
(SUSC_EC#)+12V/+5V/+3V
(EC)SUSB_EC#(Power)
(SUSB_EC#)+12VS/+5VS/+3VS
(VSUS_ON)+1.0V_VCCST,VCCPLL(VCCST_PWRGD)
(+VCCIO)+VCCSTG
(1.2V_ON)+2.5V(2.5V_PWRGD)
(1.2V_ON)+VDDQ_CPU(1.2V_PWRGD)
(+12VS)+VCCPLL_OC
(SUSB_EC#)+VCCIO(VCCIO_PWRGD)
(ALL_SYSTEM_PWRGD)+VCCSA(IMVP8_PWRGD)
(DDR_VTT_CTRL)+0.6V
(CPU)DDR_VTT_CTRL(Power)
(Power)1.2V_PWRGD(AND)
(Power)IMVP8_PWRGD
(AND)ALL_SYSTEM_PWRGD(CPU/PCH/EC/Power)
(ALL_SYSTEM_PWRGD)VCCST_PWRGD_CPU(CPU)
(EC)PM_PWROK_PCH(PCH)
(PCH)CLK_PCH_BCLK(CPU)
(PCH)H_CUPWRGD(CPU)
(ALL_SYSTEM_PWRGD)P_IMVP8_EN_10(Power)
(CPU)P_SVID_DATA_X2(Power)
(EC)PM_SYSPWROK_PCH(PCH)
(PCH)PLT_RST#(CPU/EC/Device)
(P_IMVP8_DRVON)+VCCCORE(IMVP8_PWRGD)
(CPU)H_THERMTRIP#(PCH)
(PCH)DDR4_DRAMRST#(Memory)
+VCCGT



SLK H Power Sequence (AC mode)

DC-IN Mode

C:CPU (+RTCBAT)+3VA_RTC
 P:PCH (AC_BAT_SYS)+3VA/+5VA
 S:PLT (+3VA_RTC) RTCRST# (PCH)
 Power (Power) AC_IN_OC# (EC)
 Signal (EC) PS_ON (+3VA_EC)
 (PS_ON)+3VA_EC (EC)
 (3VADSW_ON)+3VA_DSW (3VA_DSW_PWRGD)
 (EC) DPWROK_EC (PCH)
 (+3VA_DSW) PM_BATLOW# (PCH)
 (PCH) PM_SLP_SUS# (EC)
 (VSUS_ON)+1.0VSUS_VCCPRIM (1.0VSUS_PWRGD)
 (EC) PM_RSMRST#_PCH (PCH)
 (PCH) SUSWARN# (EC)
 (EC) ME_AC_PRESENT_PCH (PCH)
 (EC) PCH_SUSACK# (PCH)
 (PWR_Switch) PWR_SW# (EC)
 (EC) PM_PWRBTN# (PCH)
 (EC) SUSC_EC# (Power)
 (SUSC_EC#)+12V/+5V/+3V
 (EC) SUSB_EC# (Power)
 (SUSB_EC#)+12VS/+5VS/+3VS
 (VSUS_ON)+1.0V_VCCST, VCCPLL (VCCST_PWRGD)
 (+VCCIO)+VCCSTG
 (1.2V_ON)+2.5V (2.5V_PWRGD)
 (1.2V_ON)+VDDQ_CPU (1.2V_PWRGD)
 (+12VS)+VCCPLL_OC
 (SUSB_EC#)+VCCIO (VCCIO_PWRGD)
 (ALL_SYSTEM_PWRGD)+VCCSA (IMVP8_PWRGD)
 (DDR_VTT_CTRL)+0.6V
 (CPU) DDR_VTT_CTRL (Power)
 (Power) 1.2V_PWRGD (AND)
 (Power) IMVP8_PWRGD
 (AND) ALL_SYSTEM_PWRGD (CPU/PCH/EC/Power)
 (ALL_SYSTEM_PWRGD) VCCST_PWRGD_CPU (CPU)
 (EC) PM_PWROK_PCH (PCH)
 (PCH) CLK_PCH_BCLK (CPU)
 (PCH) H_CPU_PWRGD (CPU)
 (ALL_SYSTEM_PWRGD) P_IMVP8_EN_10 (Power)
 (CPU) P_SVID_DATA_X2 (Power)
 (EC) PM_SYSPWROK_PCH (PCH)
 (PCH) PLT_RST# (CPU/EC/Device)
 (P_IMVP8_DRVON)+VCCCORE (IMVP8_PWRGD)
 (CPU) H_THERMTRIP# (PCH)
 (PCH) DDR4_DRAMRST# (Memory)
 +VCCGT



SLK H Power Sequence (DC mode)



Project Name

GL704GM

Rev

R1.1

Title : *********

Size

B

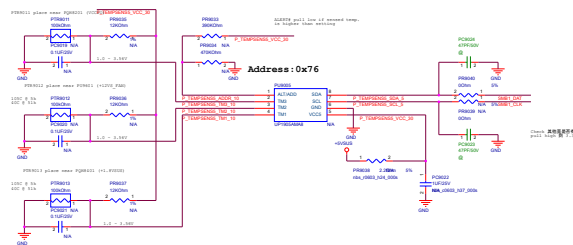
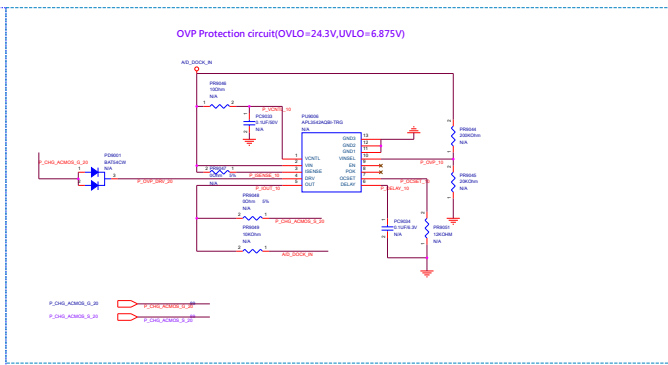
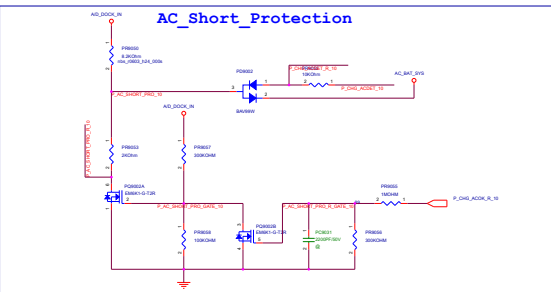
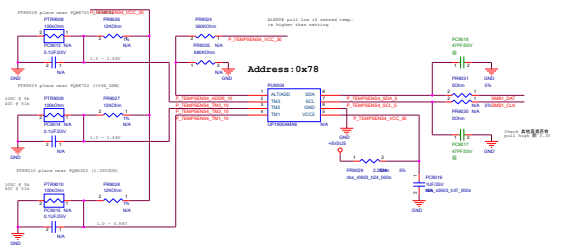
Dept.: **ASUSTeK COMPUTER INC.** **Engineer:** **NB1 RD2 EE1**

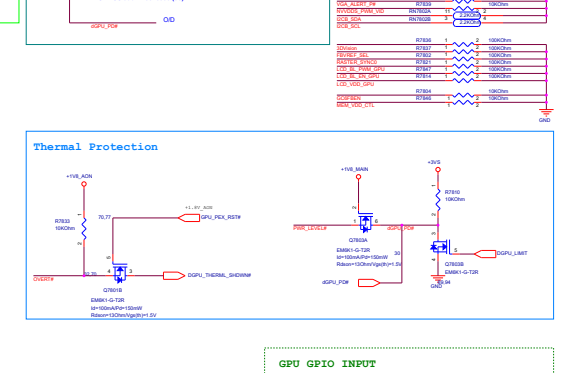
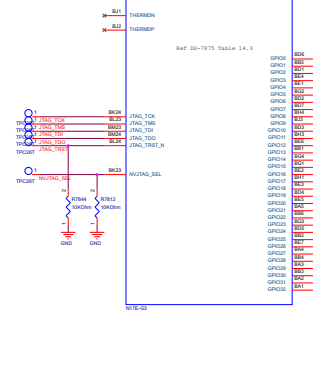
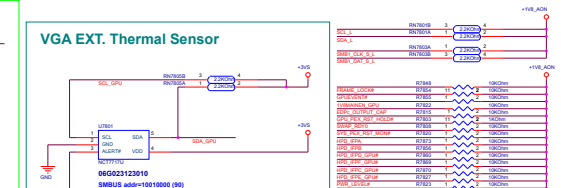
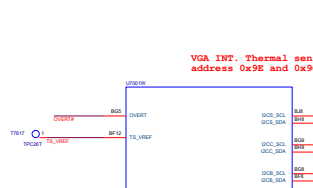
Date: **Friday, July 27, 2018**

Sheet **102** of **103**

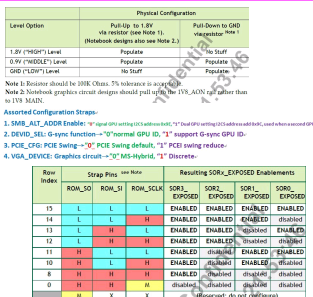
2408

Function	Input	Output	Notes
Function	Temp, alarm threshold setting	Recent temp. data	100 2 = 2 100 3 = 2 100 4 = 2 When <u>ALERT</u> occurs





STRAP PIN



Strap Pins ^{See Note}			RAMCFG Setting Number
STRAP2	STRAP1	STRAP0	(see Memory PVI, for memory config corresponding to these numbers)
M	M	L	14 (0x000E)
M	M	H	15 (0x000F)
M	L	M	16 (0x0010)
M	L	L	17 (0x0011)
M	M	M	18 (0x0012)
M	M	H	19 (0x0013)
L	M	M	20 (0x0014)
M	L	M	21 (0x0015)
M	M	L	22 (0x0016)
M	M	H	23 (0x0017)
M	L	L	24 (0x0018)
M	M	M	25 (0x0019)
M	M	H	26 (0x001A)

Strip Size: Min 1			Functions Selected by This Striping			
STRIPS	STRAP1	STRAP2	SWD_ALT_ADDR	DEV_SED	POE_CFG	VSA_DEVICE
L	L	L	0	0	0	0
L	L	M	0	0	0	0
L	L	H	0	0	0	0
L	M	M	0	0	0	0
M	L	M	0	1	0	0
M	M	M	0	1	0	0
M	L	H	1	0	0	0
L	L	M	1	0	0	0
L	M	M	1	0	0	1
M	L	M	1	0	0	1
M	M	M	1	0	0	1
M	L	H	1	0	0	0
M	M	H	1	0	0	0
M	L	M	1	1	1	1
M	M	M	1	1	1	1

Total Display Lines (HDMI, DVI or Audio)				See this Row	
Total Enabled for DVI (HDMI, DVI or AV)				Table 5-6	
Is eDP Supported on:					
	PPA or PPA+	PPC or PPC+	PPF or PPF+		
4	4	---	---	---	15
4	3	---	---	---	14
3	3	---	yes	---	13
4	3	---	---	---	12
3	3	---	---	---	11
3	2	yes	---	---	10
3	2	---	yes	---	12
2	2	---	yes	---	11
2	1	---	---	---	8
2	1	---	---	---	8
2	1	---	---	---	8
1	1	---	---	---	7
1	0	---	---	---	6
1	0	---	---	---	6

